

1 Description

The QT2032 and QT2022 products are fully integrated PHY ICs designed for use in 10 Gb/s IEEE 802.3-2005 compliant Ethernet and Fibre Channel LAN, SAN and WAN applications. The main physical layer functions (PHY) of the receiver and transmitter are integrated onto a single chip.

The QT2022 is a serial to XAUI bidirectional PHY chip that integrates the XGXS, PCS and PMA layers and supports 10 Gb/s Ethernet (10GBASE-R) and 10 Gb/s Fibre Channel protocols. In addition to the QT2022 features, the QT2032 includes an IEEE802.3-2005 WAN Interface Sublayer (WIS) for Ethernet over SONET protocol (10GBASE-W). This layer can be bypassed for LAN or SAN applications.

In the transmit direction, the chip converts four differential input 3.125 Gb/s lanes (XAUI) into a serial 9.95-10.5 Gb/ s data stream. In the receive direction the chip converts an input serial 9.95-10.5 Gb/s data stream into four differential output 3.125 Gb/s lanes (XAUI).

The QT2032 and QT2022 include a standard two-wire interface for communicating with external EEPROM and DOM devices or XFP modules. An MDC/MDIO interface provides control and status capability for the IC.

In the QT2032, maximum flexibility is provided by the transmit data clocking and jitter clean-up options and extended SONET overhead processing when connecting the module to the existing OC-192 and DWDM networks.

The QT2032 and QT2022 are fully compliant with IEEE 802.3-2005 10GE and ANSI INCITS/T11 10GFC standards, and the XENPAK, XPAK, X2, and XFP Multi Source Agreements (MSA).

2 Applications

10 Gb/s Ethernet and Fibre Channel LAN, SAN and WAN applications. XENPAK, XPAK, and X2 fiber optic modules. System cards that support XFP modules.

Figure 1: Application Diagrams for QT2032 and QT2022. Top: System application. Bottom: Module application.

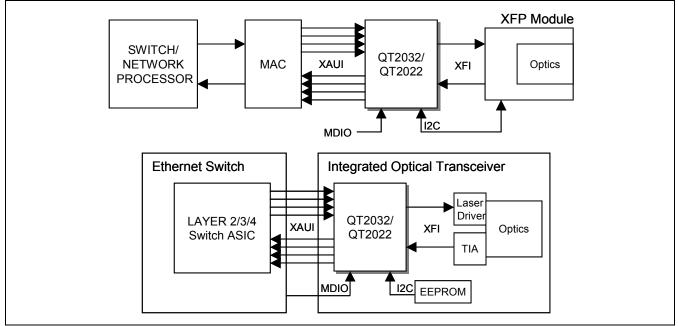




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Features	Benefits
Selectable LAN or WAN ¹ mode operation	Single module footprint to support LAN and WAN.
10GE, 10GFC and SONET ¹ data rate support	Compliant with multiple protocols
Compliant to IEEE 802.3-2005 standard including WIS $^{\rm 1}$, and XENPAK and XFP MSAs	Industry standard operation
Selectable XAUI lane ordering	Flexible system card design
Selectable 10G I/O polarity	Accommodates polarity inversion
Adjustable XAUI and 10G output amplitude	Optimizes performance / power
9.6kB jumbo frame support	Supports all Ethernet frame sizes
3.3V tolerant I/O	Low speed I/O pins are compatible with 3.3V logic
Optional ability to configure registers from an external EEPROM on powerup or reset	Modify default register settings to customize device operation.
Configurable polarity of low-speed CMOS I/O	Flexible interface logic
25MHz MDIO operation	Superior bus speed
1. QT2032 only QT2032 WIS Features	
WIS interface with extended SONET overhead processing	Maximum flexibility in network design
SONET overhead serial interface	SONET overhead insertion and extraction
Line-timing capability with optional VCXO interface	Support synchronous transport
Conditional (auto-linetiming) or forced line-timing operation	Flexible operation
VCXOONLY mode where the local SONET reference clock is	Reduce system cost
eliminated	
SONET-compliant jitter performance	Compatible with SONET network timing requirements
Module Features	
Integrated limiting amplifier with 20mVppD sensitivity	Eliminates need for external limiting amp
Internal LOS detector with option to use external LOS detector.	Increased flexibility to accommodate design constraints.
Support for dual rate module (10GE/10GFC)	Two reference clock inputs for 10.3 and 10.5Gb/s in a single module
Standard two-wire I2C interface to external EEPROM/DOM devices	Reduced module cost
I2C interface supports clock stretching by an external device	Allows I2C operation with devices which use clock stretching for flow control
Dedicated power-up reset pin	No large capacitor required on the reset pin to the connector
Two-byte I2C addressing capability to allow combined EEPROM+DOM memory in a single device	Reduce number of devices on I2C bus
Configurable LASI interrupt input for fast response to externally generated alarms	Meet sub-10ms response time.
Configure any register on powerup from EEPROM	Customization of module
System Card Features	
XFI compliant 10G serial interface	XFP compliant
XFP module access through MDIO	Eliminates additional I2C bus to control XFP module
3 GPIOs, configurable as LED drivers with built-in Link and Tx/Rx Activity modes	Easily drive faceplate LEDs with no additional firmware required
Provides divide-by-64 output clock reference to XFP module	Eliminates extra clock source on the board.
Ability to access internal registers via the I2C interface	Chip can be controlled entirely from I2C interface, eliminating need for MDIO access.
Test and Diagnostics	
Multiple loopback modes	Assists in system test and diagnostics
PRBS and jitter generators and checkers	Reduces need for expensive test equipment
JTAG interface for Boundary Scan	Standard design and manufacturing test and verification
AC BSCAN IEEE1149.6 on XAUI I/O	Standard design and manufacturing test and verification
'Extended link monitoring' feature allowing far-end link status	Link diagnostic capability
monitoring	
monitoring XAUI 8B/10B decoder error counters on each lane	Per-lane integrity checking, aids litter tolerance testing
XAUI 8B/10B decoder error counters on each lane	Per-lane integrity checking, aids jitter tolerance testing Full control of XAUI signal
XAUI 8B/10B decoder error counters on each lane Ability to selectively turn-off any XAUI output	Full control of XAUI signal
XAUI 8B/10B decoder error counters on each lane	



Features	Benefits
PLL lock indications	Reports whether PLLs are functioning properly.
Ability to override fault indications	Flexible configuration.
Characteristics	
Electrical	
Power supplies	+1.2 V (+3.3 V tolerant digital I/O)
Power consumption, LAN applications	0.90 W typical (XFP mode)
Power consumption, WAN applications	0.95 W typical (XFP mode)
Mechanical	
Package	15x15 mm ² LBGA
Ball spacing	1.0 mm
Environmentally friendly package	meets RoHS specifications

3 Available Package Options

The body of the QT2022/32 package complies with the RoHS directive for elimination of banned materials. The solder balls are composed of a SnAgCu alloy, which requires a hotter thermal reflow profile for die attach.

The adoption of a hotter reflow profile for the Pb-free solder presents practical difficulties in manufacturing. To ease the transition to RoHS compliant products for our customers, the product is also available with standard $Sn_{63\%}/Pb_{37\%}$ solder balls.

The order codes for the products with leaded and lead-free solder balls are listed in Table 79 on page 219.

4 Pin Assignment and Description

4.1 QT2032 Ball Arrangement

The QT2032 comes in a 15x15 mm² LBGA package with 1.0 mm ball pitch. The pin arrangement is shown in Table 1 and the pin assignments are described in Table 3.

Table 1:	QT2032 Ball Arrangement	Top View	(through the package)
----------	-------------------------	----------	-----------------------

	Ρ	Ν	М	L	К	J	Н	G	F	Е	D	С	В	А	٠
1	TXPLL OUTP	GND	SREF CLKP	GND	VCXOI P	GND	VCXO- CNTL P	GND	EREF CLKP	PRTA D1	TxXM ON CVP	PRTA D2	PRTA D3	PRTA D4	1
2	TXPLL OUTN	GND	SREF CLKN	GND	VCXOI N	GND	VCXO- CNTL N	GND	EREF CLKN	PRTA D0	TxXM ON CVN	LEGA CY	TxXAU I3N	TxXAU I3P	2
3	GND	GND	GND	GND	GND	GND	GND	TRST_ N	LASI	LASI_ INTB	тск	TX FAULT	GND	XV1P2	3
4	TXLEV EL	TXIPM P	TXFN	TXFP	TV1P2 A	TV1P2 A	TXON	MDIO	MDC	LED1	LED2	TXOU T _SEL	TxXAU I2N	TxXAU I2P	4
5	TV1P2	TV1P2	TV1P2	TGND A	TGND A	CORE VDD	CORE VDD	CORE VDD	CORE VDD	TDCC _CLK	LED3	TxXAU I _SEL	GND	XV1P2	5
6	<no ball></no 	TXOU TP	GND	GND	GND	GND	GND	GND	GND	TDCC	TDI	PHOF F_EN	TxXAU I1N	TxXAU I1P	6
7	<no ball></no 	TXOU TN	GND	GND	GND	GND	GND	GND	GND	TMS	TDO	RxXA UI _SEL	GND	XV1P2	7
8	TV1P2	GND	GND	RGND A	GND	GND	GND	GND	GND	EQ_E N	reserv ed	EEPR OM_P ROT	TxXAU ION	TxXAU I0P	8
9	RV1P2	RV1P2	RV1P2	RV1P2	GND	GND	GND	GND	GND	reserv ed	LOSO UTB	REFS EL622	GND	XV1P2	9
10	<no ball></no 	RXIP	reserv ed	RV1P2 A	GND	GND	GND	GND	GND	RDCC	EEPR OM_S CL	XFP	RxXA UI3N	RxXA UI3P	10
11	<no ball></no 	RXIN	reserv ed	RV1P2 A	RGND A	CORE VDD	CORE VDD	CORE VDD	CORE VDD	RDCC _CLK	EEPR OM_S DA	RESE TN	GND	XV1P2	11
12	reserv ed	GND	reserv ed	PHAS E_OFF SET	reserv ed	reserv ed	reserv ed	VCXO SEL62 2	VCXO ONLY	LTIME OK	RXLO SB_I	TX ENAB LE	RxXA UI2N	RxXA UI2P	12
13	RXFN	ITH_L OS	RXICX P	reserv ed	reserv ed	reserv ed	VCXO B	RXPLL OUTP	XBIAS	reserv ed	RxXA UI0N	RXIN _SEL	GND	XV1P2	13
14	RXFP	RXIPM P	RXICX N	reserv ed	<no ball></no 	<no ball></no 	reserv ed	RXPLL OUTN	RxX LEVEL	LAN MODE	RxXA UIOP	GND	RxXA UI1N	RxXA UI1P	14
	Ρ	Ν	Μ	L	К	J	Н	G	F	Е	D	С	В	А	

4.2 QT2022 Ball Arrangement

The QT2022 comes in a 15x15 mm² LBGA package with 1.0 mm ball pitch. The pin arrangement is shown in Table 2 and the pin assignments are described in Table 3. The pin assignment is shared with QT2032 except for 14 balls which are unused in the QT2022. No ball locations are moved.

	Ρ	Ν	М	L	к	J	Н	G	F	Е	D	С	В	А	٠
1	TXPLL OUTP	GND	unuse d	GND	unuse d	GND	unuse d	GND	EREF CLKP	PRTA D1	TxXM ON CVP	PRTA D2	PRTA D3	PRTA D4	1
2	TXPLL OUTN	GND	unuse d	GND	unuse d	GND	unuse d	GND	EREF CLKN	PRTA D0	TxXM ON CVN	LEGA CY	TxXAU I3N	TxXAU I3P	2
3	GND	GND	GND	GND	GND	GND	GND	TRST_ N	LASI	LASI_ INTB	тск	TX FAULT	GND	XV1P2	3
4	TXLEV EL	TXIPM P	TXFN	TXFP	TV1P2 A	TV1P2 A	TXON	MDIO	MDC	LED1	LED2	TXOU T _SEL	TxXAU I2N	TxXAU I2P	4
5	TV1P2	TV1P2	TV1P2	TGND A	TGND A	CORE VDD	CORE VDD	CORE VDD	CORE VDD	unuse d	LED3	TxXAU I _SEL	GND	XV1P2	5
6	<no ball></no 	TXOU TP	GND	GND	GND	GND	GND	GND	GND	unuse d	TDI	PHOF F_EN	TxXAU I1N	TxXAU I1P	6
7	<no ball></no 	TXOU TN	GND	GND	GND	GND	GND	GND	GND	TMS	TDO	RxXA UI _SEL	GND	XV1P2	7
8	TV1P2	GND	GND	RGND A	GND	GND	GND	GND	GND	EQ_E N	reserv ed	EEPR OM_P ROT	TxXAU ION	TxXAU I0P	8
9	RV1P2	RV1P2	RV1P2	RV1P2	GND	GND	GND	GND	GND	reserv ed	LOSO UTB	REFS EL622	GND	XV1P2	9
10	<no ball></no 	RXIP	reserv ed	RV1P2 A	GND	GND	GND	GND	GND	unuse d	EEPR OM_S CL	XFP	RxXA UI3N	RxXA UI3P	10
11	<no ball></no 	RXIN	reserv ed	RV1P2 A	RGND A	CORE VDD	CORE VDD	CORE VDD	CORE VDD	unuse d	EEPR OM_S DA	RESE TN	GND	XV1P2	11
12	reserv ed	GND	reserv ed	PHAS E_OFF SET	reserv ed	reserv ed	reserv ed	unuse d	unuse d	LTIME OK	RXLO SB_I	TX ENAB LE	RxXA UI2N	RxXA UI2P	12
13	RXFN	ITH_L OS	RXICX P	reserv ed	reserv ed	reserv ed	unuse d	RXPLL OUTP	XBIAS	reserv ed	RxXA UI0N	RXIN _SEL	GND	XV1P2	13
14	RXFP	RXIPM P	RXICX N	reserv ed	<no ball></no 	<no ball></no 	reserv ed	RXPLL OUTN	RxX LEVEL	unuse d	RxXA UIOP	GND	RxXA UI1N	RxXA UI1P	14
	Ρ	Ν	М	L	К	J	Н	G	F	Е	D	С	В	А	

Ball	Signal Name	Dir.	Туре	Description	
CML O	utputs				
N6 N7	TXOUTP TXOUTN	0	CML	9.95 - 10.5 Gb/s transmit differential voltage outputs. 100 Ω differential impedance.	
D14 D13	RxXAUI0P RxXAUI0N	0	CML	3.125 Gb/s differential output data from QT2022/32 to XAUI interface - lane 0	
A14 B14	RxXAUI1P RxXAUI1N	0	CML	3.125 Gb/s differential output data from QT2022/32 to XAUI interface - lane 1	
A12 B12	RxXAUI2P RxXAUI2N	0	CML	3.125 Gb/s differential output data from QT2022/32 to XAUI interface - lane 2	
A10 B10	RxXAUI3P RxXAUI3N	0	CML	3.125 Gb/s differential output data from QT2022/32 to XAUI interface - lane 3	
G13 G14	RXPLLOUTP RXPLLOUTN	0	CML	Clock output from receive input data PLL Used for monitoring only. Leave unconnected.	
P1 P2	TXPLLOUTP TXPLLOUTN (REFCLK2P, REFCLK2N)	0/1	CML	Configurable as either a differential transmit clock driver (default) or as a reference clock input instead of EREFCLK (with MDIO bit 1.C001h.7=1). The output clock frequency is controlled by MDIObit 1.C001h.2. The default frequencies are: With XFP=1: divide-by-64, can be used as reference clock to the XFP module; 161.13 MHz (10GE) or 164.355 MHz (10GFC) With XFP=0: divide-by-66; 156.25MHz (10GE) or 159.375 (10GFC) Enabling the driver circuitry is controlled by MDIO bit 1.C001h.3. By default: With XFP=1, the driver is enabled With XFP=0, the driver is disabled Note: for the case where the pin is configured as a reference clock input, the driver circuitry is disabled.	
H1 H2	VCXOCTLP VCXOCTLN	0	CML	<i>QT2032:</i> Output of phase-frequency detector which drives the external loop filter as part of the VCXO control. <i>QT2022:</i> Unused. Leave unconnected.	
CML In	puts				
F1 F2	EREFCLKP EREFCLKN	I	CML	LAN reference clock input for fiber-side TXPLL. 156.25 MHz (10GE) or 159.375 (10GFC) On chip 50Ω terminations to 1.2V. Requires external AC coupling.	
M1 M2	SREFCLKP SREFCLKN	1	CML	QT2032: SONET reference clock input for fiber-side TXPLL in WAN-mode 155.52MHz or 622.08MHz selected by REFSEL622 pin; AC coupled with on chip 50Ω terminations to 1.2V QT2022: Unused. Leave unconnected.	

Table 3: QT2022/32 Ball Assignment & Signal Description

Ball	Signal Name	Dir.	Туре	Description	
K1 K2	VCXOIP VCXOIN	I	CML	QT2032: Input clock from VCXO when an external VCXO is used for the fiber side TXPLL reference clock input in WAN-mode; 155.52MHz or 622.08MHz selected by VCXOSEL622 pin; AC coupled with on chip 50 Ω terminations to 1.2V.	
				<i>QT2022:</i> Unused. Leave unconnected.	
N10 N11	RXIP RXIN	I	CML	10Gb/s receive data in, 100 Ω differential impedance.	
A8 B8	TxXAUI0P TxXAUI0N	I	CML	Transmit 3.125Gb/s data to QT2022/32 from XAUI interface - lane 0	
A6 B6	TxXAUI1P TxXAUI1N	I	CML	Transmit 3.125 Gb/s data to QT2022/32 from XAUI interface - lane 1	
A4 B4	TxXAUI2P TxXAUI2N	I	CML	Transmit 3.125 Gb/s data to QT2022/32 from XAUI interface - lane 2	
A2 B2	TxXAUI3P TxXAUI3N	I	CML	Transmit 3.125 Gb/s data to QT2022/32 from XAUI interface - lane 3	
DC Mor	nitor Points				
D1	TxXMONCVP	0	analog	Monitor test point for the transmit XAUI interface (DC signal). Used for monitoring only. Leave unconnected.	
D2	TxXMONCVN	0	analog	Monitor points for the transmit XAUI interface (DC signal) Used for monitoring only. Leave unconnected.	
Connec	tion Points for Extern	al Comp	onents		
M13	RXICXP		analog	Connection point for external 100nF cap to ground	
M14	RXICXN		analog	Connection point for external 100nF cap to ground	
L12	PHASE_OFFSET		analog	For test purposes only.	
N13	ITH_LOS		analog	Internal fiber receive path loss of signal (LOS) detector threshold adjust. See Section 8.7.1 on page 72 for details.	
F14	RxXLEVEL		analog	connection point for external resistor to set receive XAUI drivers' output level.	
F13	XBIAS		analog	XAUI bias current control 6.49 kΩ resistor to GND.	
P14 P13	RXFP RXFN		analog	Receive charge pump filter connection points see "External Components" on page 209 for external component connections	
N14	RXIPMP		analog	Receive charge pump current control $6.49 \text{ k}\Omega$ resistor to GND	
P4	TXLEVEL		analog	external resistor used to control 10.3125 Gb/s output data amplitude.	
L4 M4	TXFP TXFN		analog	Transmit loop filter - see "External Components" on page 209 for external components	

Table 3: QT2022/32 Ball Assignment & Signal Description (Continued)



Ball	Signal Name	Dir.	Туре	Description	
N4	TXIPMP		analog	Transmit charge pump current control 6.49kΩ resistor to GND	
CMOS	Inputs (note all CMOS	6 inputs	are 3.3V tolerant and all	CMOS inputs with pullups are to 1.2V)	
E6	TDCC	1	CMOS	QT2032: Transmit data communication channel input for both section and line SONET overhead data; clocked in using the TDCC_CLK output. Please see Section 7.3.8, "Transport Overhead Serial Interface," on page 48. QT2022: Unused. Connect to GND.	
E14	LANMODE	1	CMOS with 50kΩ pullup	QT2032: LAN/WAN Mode select 0 = WAN mode enabled 1 = LAN mode enabled (default) When LANMODE = 1, the chip will not operate in WAN mode and access to all WIS registers is disabled. When LANMODE = 0, the chip will default to WAN mode operation but can be set to operate in LAN mode by setting MDIO register bit 2.7.0 to 0. QT2022: Unused. Leave unconnected.	
C9	REFSEL622	I	CMOS with 50kΩ pulldown	QT2032: SREFCLK frequency selection 0 = 155.52MHz (default) 1 = 622.08MHz QT2022: Unused. Leave unconnected.	
G12	VCXOSEL622	I	CMOS with 50kΩ pulldown	QT2032: VCXO frequency selection 0 = 155.52MHz (default) 1 = 622.08MHz QT2022: Unused. Leave unconnected.	
H13	VCXOB	I	CMOS with 50kΩ pullup	QT2032: VCXO control loop enable pin. A low-level configures the chip to implement a PLL using an external VCXO - see description in Section 6.2.4, "VCXO PLL," on page 32. 0 = enabled 1 = disabled (default) QT2022: Unused. Leave unconnected.	
F12	VCXOONLY	I	CMOS with 50kΩ pulldown	QT2032: Input to indicate that the VCXO is the only reference clock available (i.e. there is no SREFCLK input - so in non-linetiming mode, there is no switchover to it) 0 = there is a SREFCLK input in WAN mode (default) 1 = there is no SREFCLK input in WAN mode (i.e. VCXO alone. Also set REFSEL622 = VCXOSEL622) QT2022: Unused. Leave unconnected.	

Table 3: QT2022/32 Ball Assignment & Signal Description (Continued)

Table 3:	QT2022/32 Ball Assig	nment & Signal Des	scription (Continued)

Ball	Signal Name	Dir.	Туре	Description	
C6	PHOFF_EN	1	CMOS with 50kΩ pulldown	Phase Offset Enable pin (NEW). Enables adjustment of Receive CDR decision phase from nominal. Used in conjunction with the PHASE_OFFSET pin. For test purposes only. 0 = phase offset control disabled (default) 1 = phase offset control enabled.	
C2	LEGACY	I	CMOS with $50k\Omega$ pulldown	0 (default) = new register map definitions 1=reverts to 2021 register map definitions (see LEGACY mode description)	
C13	RXIN_SEL	I	CMOS with 50k Ω pulldown	Polarity control for RXI, 50 kΩ pulldown RXIN_SEL=0 default polarity RXIN_SEL=1 inverted polarity	
C5	TxXAUI_SEL (SCAN_EN)	I	CMOS with 50kΩ pulldown	XAUI Transmit path lane order control, 50kΩ pulldown 0 = default lane ordering 1 = inverted lane ordering Enable scan in scan mode	
C7	RxXAUI_SEL	I	CMOS with $50k\Omega$ pulldown	XAUI receive path lane order control, 50kΩ pulldown 0 = default lane ordering 1 = inverted lane ordering	
D12	RXLOSB_I (XFPRXLOS)	1	CMOS with 50kΩ pullup to 1.2V	Receive optical signal loss indicator input (can be driven directly by LOSOUTB or by an external source) When XFP=0, active low indicates RX signal loss with XFP=1, active high indicates RX signal loss (See Section 8.2.2 on page 54)	
C10	XFP	I	CMOS with 50kΩ pulldown	XFP application mode select; 0 = non-XFP application, default; high-sensitivity input selected on 10Gb/s input 1 = XFP application; equalization option selected on 10Gb/s input (can be over-ridden via MDIO register bit 1.C030h.6 - 'override_xfp_eqn'). Also changes function of TXPLLOUT, LOSOUTB, TXFAULT, TXON, TXENABLE, EEPROM_PROT, RXLOSB_I and TRST_N.	
E8	EQ_EN	I	CMOS with 50kΩ pulldown	Receive Equalizer Enable pin (NEW). Allows receive equalizer to be enabled. 0 = equalizer state determined by XFP pin (default) 1 = equalizer on.	
C8	EEPROM_PROT (XFPMODABS)	I	CMOS with 50kΩ pullup to 1.2V	With XFP=0, EEPROM interface write protection pin; Scan enable when in scan mode 1 (default) = no writes to protected EEPROM registers allowed ; With XFP=1, high level indicates XFP module absent	
F4	MDC	I	CMOS	MDIO interface clock	
C4	TXOUT_SEL	I	CMOS with 50k Ω pulldown	TXOUT polarity control, 50 kΩ pulldown 0 = default polarity 1 = inverted polarity	
E3	LASI_INTB (XFPINTB)	I	CMOS with 50kΩ pullup to 1.2V	With XFP=0, Active low interrupt input to LASI; (See Section 8.2.12 on page 57). With XFP=1, active low interrupt input indicating XFP module fault condition.	

Ball	Signal Name	Dir.	Туре	Description	
C3	TXFAULT (XFPMODNR)	I	CMOS with 50kΩ pullup to 1.2V	With XFP=0, External laser or laser-driver fault indicator as per XENPAK MSA logic low = normal operation logic high = fault condition (See "Laser Driver Enable Pin (TXENABLE)" on page 69.) With XFP=1, high level indicates XFP module not ready	
E2 E1 C1 B1 A1	PRTAD<0> PRTAD<1> PRTAD<2> PRTAD<3> PRTAD<4>	I	CMOS no pullup or pulldown	Port address for MDIO transactions. See "Management Frame Format" on page 74. for more information on the MDIO/C interface.	
C11	RESETN	I	CMOS with hysteresis 25kΩ pullup	reset, active low logic low = reset condition logic high = normal operation Note: the TAP port controller is only reset by the TRST_N pin and is unaffected by RESETN Note: in a module application XFP=0 & the external cap for the powerup reset must be connected to the TRST_N input. For further details, please see Section 18.5 on page 210	
			CMOS	Test pins for Test Access Port (or internal scan testing when SCAN instruction written to TAP).	
D6 D3 G3	TDI TCK TRST_N	 	36kΩ pullup (no pullup/dn) 25kΩ pullup	Test data input (<i>scan in</i>) Test clock input (<i>scan clock</i>) Test reset, active low (<i>hold high for scan</i>) with XFP=0, also resets the core and is to be used as the connection point for an external cap to GND for a powerup reset.	
E7	TMS	I	36kΩ pullup	Test mode select, active low (hold high for scan)	
CMOS	Outputs (note: all CM	OS outp	uts are 3.3V tolerant ope	n drain)	
E12	LTIMEOK	0	CMOS open drain (see note1)	QT2032: Line-timing internal enable indication. logic high = conditions are valid for line-timing operation and it is internally enabled. A low level can be used to center the external VXCO in a VXCO-only application. (see Section 6.2.4, "VCXO PLL," on page 32 for a description of the logic) QT2022:	
				Unused. Connect to GND.	
E10	RDCC	0	CMOS open drain (see note1)	Q72032: Receive data communication channel output for both section and line SONET overhead data; timed from the RDCC_CLK clock output. Please see Section 7.3.8, "Transport Overhead Serial Interface," on page 48.	
				QT2022: Unused. Connect to GND.	
E11	RDCC_CLK	0	CMOS open drain (see note1)	QT2032: Gapped clock used for timing RDCC output. Please see Section 7.3.8, "Transport Overhead Serial Interface," on page 48.	
				QT2022: Unused. Connect to GND.	

Ball	Signal Name	Dir.	Туре	Description	
E5	TDCC_CLK	0	CMOS open drain (see note1)	QT2032: Gapped clock used for timing TDCC input. Please see Section 7.3.8, "Transport Overhead Serial Interface," on page 48	
				QT2022: Unused. Connect to GND.	
D7	TDO	0	CMOS open drain (see note1)	Test data output (scan out when SCAN instruction written to TAP).)	
F3	LASI	0	CMOS open drain	Link Alarm Status Interrupt (LASI) logic low = Interrupt asserted logic high =No alarm interrupt asserted See "Link Alarm Status Interrupt Pin (LASI)" on page 62.	
C12	TXENABLE (XFPTXDIS)	0	CMOS open drain	With XFP=0, Active high laser driver enable as per XENPAK MSA (see "Laser Driver Enable Pin (TXENABLE)" on page 69) With XFP=1, drives TX_DIS input of XFP module	
D9	LOSOUTB (XFPPDN)	0	CMOS (see note1) open drain	With XFP=0, low level indicates when the input signal applied at RXIP/N is below a threshold which can be adjusted via the resistor connected to the ITH_LOS pin With XFP=1, drives P_DOWN/RST input of XFP module	
Bidirect	ional CMOS IO (note:	all CM	DS I/O are 3.3V tolerant &	& outputs are open drain)	
D10	EEPROM_SCL	I/O	CMOS (see note1) bidirectional open drain hysteresis	EEPROM serial interface clock. can be tristated via MDIO register 1.C024h.0 This is a bidirectional pin to allow an external device to take control of the EEPROM I2C interface. With XFP=1, drives the XFP module I2C interface.	
D11	EEPROM_SDA	I/O	CMOS (see note1) bidirectional open drain hysteresis	EEPROM interface serial address/data. With XFP=1, drives the XFP module I2C interface.	
G4	MDIO	I/O	CMOS bidirectional open drain	MDIO Interface serial data signal External pullup to 1.2V required. Please see Section 9.5 on page 74 for details.	
H4	TXON (XFPMODDESEL)	I/O	CMOS bidirectional open drain with 50kΩ pullup to 1.2V (output in XFP mode)	With XFP=0, low power mode control input 0 = low power mode (only the MDIO, EEPROM and DOM functions are active with an external reference clock applied at EREFCLKP/N) 1 = normal operating mode, default With XFP=1, output to drive the MOD_DESEL input of an XFP module	
Miscella	aneous	-			
E4	LED1	I/O	CMOS input or 10mA open drain output	LED driver and General Purpose I/O: Can be configured as a LED driver output or as a GPIO via MDIO register bits 1.D006h.2:0. The default configuration is as a LED driver. As an input, its state is displayed in MDIO register bit 1.D006h.5; as an output it can be driven by MDIO register bits 1.D006h.2:0 or other internal status signals (see Section 8.6 on page 70)	

 Table 3:
 QT2022/32 Ball Assignment & Signal Description (Continued)



Ball	Signal Name	Dir.	Туре	Description
D4	LED2	I/O	CMOS input with 50kΩ pullup to 1.2V, or 10mA open drain output	LED driver and General Purpose I/O: Can be configured as a LED driver output or as a GPIO via MDIO register bits 1.D007h.2:0. The default configuration is as a LED driver. As an input, its state is displayed in MDIO register bit 1.D006h.5; as an output it can be driven by MDIO register bits 1.D007h.2:0 or other internal status signals (see Section 8.6 on page 70) If this pin is held low during a hard reset, it will enable 'two-byte' addressing of an peripheral I2C device. Please see Section 10.6 on page 89 for details.
D5	LED3	I/O	CMOS input or 10mA open drain output	LED driver and General Purpose I/O: Can be configured as a LED driver output or as a GPIO via MDIO bits 1.D008h.2:0. The default configuration is as a LED driver. As an input, its state is displayed in MDIO register bit 1.D008h.5, as an output it can be driven by MDIO bits 1.D008h.2:0 or other internal status signals (see Section 8.6 on page 70)
Reserve	ed pins			
D8 E9 M10 M11 H12 J12 K12 P12 E13 J13 K13 L13 H14 L14				Reserved. Leave unconnected.

Table 3: QT2022/32 Ball Assignment & Signal Description (Continued)

Note1: All CMOS pins are compatible with 3.3V logic. All CMOS inputs with internal pullups are to 1.2V. All CMOS outputs are open drain.

		balls		
Supply (#)	Description	15x15 mm ² package		
TV1P2 (4)	1.2V Supply for transmit fiber side circuits	M5,N5,P5,P8		
GND (54)	Ground	G1,J1,L1,N1,G2,J2,L2,N2,B3,H3,J3 K3,L3,M3,N3,P3,B5,F6,G6,H6,J6,K6 L6,M6,B7,F7,G7,H7,J7,K7,L7,M7,F8 G8,H8,J8,K8,M8,N8,B9,F9,G9,H9,J9 K9,F10,G10,H10,J10,K10,B11,N12 B13,C14		
TV1P2A (2)	1.2V Supply for transmit PLL	K4,J4		
RV1P2 (4)	1.2V Supply for fiber receive side circuits	L9,M9,N9,P9		
RV1P2A (2)	1.2V Supply for receive PLL	L10,L11		
XV1P2 (6)	1.2V supply for XAUI side	A3,A5,A7,A9,A11,A13		
COREVDD (8)	1.2V Supply for CMOS digital logic	F5,G5,H5,J5,F11,G11,H11,J11		
RGNDA (2)	Receive Analog Ground	K11,L8		
TGNDA (2)	Transmit Analog Ground	K5,L5		

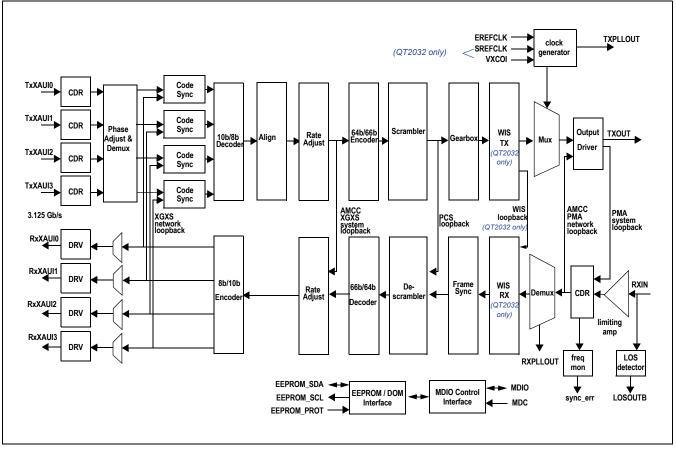
 Table 4:
 Supply Pad and Ball Assignment and Description



5 Datapath Description

This section describes the functional blocks of the QT2022/32. These are illustrated in Figure 2.





5.1 Transmit Path

5.1.1 XAUI CDR and Demultiplexer

At the transmitter XAUI interface, clock and data are recovered for each of the four 3.125Gb/s input lanes. The differential receivers used at this interface have 100Ω differential input impedance and are intended to be AC coupled or 1.2V CML DC coupled. The data on each channel is then demultiplexed/deserialized before being passed to the next block. A clock is recovered for each lane. Each lane outputs a status bit, *xtxlock<3:0>*, which is high when the CDR circuit is in lock. A phase-adjust FIFO aligns the four lanes using the Lane 1 recovered clock.

5.1.2 XAUI Code Synchronization

The XAUI interface demultiplexer has no prior knowledge of code word boundaries and must determine where each 8B/10B character starts and ends. To achieve this, the code synchronization block searches the data stream for the unique comma character, /K/, in order to determine the 10 bit code word boundaries for each lane. The delimited code words are passed to the Frame Deskew block. The code synchronization status is displayed in Register bits 4.18h.3:0.

The comma characters, /K/, are found in the XAUI data stream in the IPG between packets.

If any single lane loses signal (no transitions detected), the code synchronization block will not attempt to achieve alignment on the XAUI input lanes. The QT2022/32 will report 'loss of sync' on all 4 lanes.

However, when valid data is received on all 4 lanes, the code synchronization block is fully active. If no /K/ characters are detected on a given lane, the QT2022/32 will report 'loss of sync' independently for each lane.

5.1.3 XAUI Lane Align

The incoming XAUI data may be skewed due to varying off-chip transmission delays between the four lanes. The deskew operation is done by aligning the /A/ code characters on all four lanes. The /A/ codes appear randomly in the idle data stream and are transmitted simultaneously at the source on all four channels as a single column of data, ||A||. The alignment is done by placing the data from each channel in a FIFO and adjusting the read pointer of each FIFO so that the /A/ codes are read out simultaneously when they occur.

The QT2022/32 can tolerate a skew of up to 5 code words, or 50 bits between any two lanes at the TxXAUI input pins. (The IEEE 802.3 requirement is for a maximum of 40 bit skew between lanes.)

5.1.4 8B/10B Decoding

Each 10 bit code word is decoded into 8 data bits and 1 control bit. The 8 data bits and 1 control bit are then passed on to the rate adjust function.

Any 8B/10B coding errors are counted on a per lane basis. For each lane, errors are reported in an 8 bit, non-rollover counter that is cleared on read. The four counters for Lane 0 to Lane 3 are located in the lower byte of MDIO registers 4.C030h - 4.C033h respectively.

5.1.5 Transmit Rate Adjust

Data is written into a rate compensation FIFO. The outgoing data is read out using a clock derived from the external reference clock. Since these clocks are derived from different sources, a rate adjust operation needs to be performed. The rate compensation block accomplishes this by either adding or dropping idle codes or sequence ordered sets from the data stream. The minimum inter packet gap (IPG) of five characters and sequence ordered set messages are always maintained.

Proper rate compensation will always be performed when the clock rates are within 200ppm (total). The QT2022/ QT2032 can tolerate up to 2 back-to-back 9600 byte jumbo frames with minimum IPG. If the clock rate difference exceeds 200ppm or multiple back-to-back jumbo frames are transmitted, one or more packets may be corrupted.

Transmit rate adjust operation is monitored in MDIO register 4.C002h. This register flags idle code removal and insertion in bits 15:14 (normal operation), as well as overflow/underflow in bits 9:8 (fault condition).

5.1.6 64B/66B Encoding

The encoder takes 64 bits of input data and the associated 8 bit control word and creates a new 66 bit data bus. The 66 bits are composed of 2 sync bits followed by 64 bits of data. The sync bits are used to synchronize the data stream on a frame boundary. The sync bits <1:0> are 10 if 64 bit data bus is composed solely of data words. If the bus contains 1 or more control words, the sync bits <1:0> are set to 01 and are followed by a 8 bit type data. The type word indicates the content of the following 56 bits of data. The sync bit values of 00 or 11 are invalid for the sync bits.

Incoming control words are converted from 8 bits to 7 bits. Data words are not altered. When combinations of data and control words are used in a bus, extra bits are inserted if needed at the boundary between the data and control words to make the total number of bits 64. Ordered set control codes are encoded using a combination of the block's type field and a 4 bit O code for each ordered set.

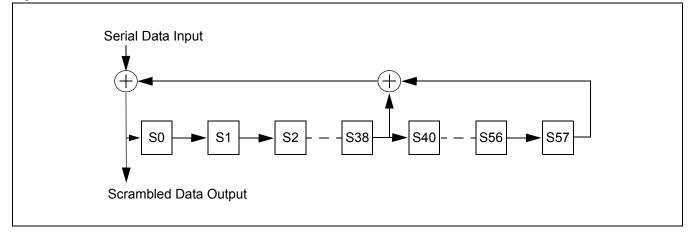
5.1.7 Scrambler

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The scrambler polynomial is $1+x^{39}+x^{58}$. Only the 64 data bits pass through the scrambler. The sync bits are not scrambled. The scrambler can be bypassed by setting the MDIO register bit 3.C000h.2.

applied micro

Figure 3: Transmit Scrambler



5.1.8 Gear Box

The gear box converts the data from a 66 bit wide data bus at 156.25 Mb/s to a 64 bit wide bus at 161.1328 Mb/s. This step is required to prepare the data for serialization in the next functional block.

5.1.9 Transmit WAN Interface Sublayer (WIS) (QT2032 Only)

The TX WIS block accepts data from the gear box and maps it into the payload of the transmitted STS-192C WIS frame stream. Fixed stuff octets are added, together with a set of Path Overhead octets, to create a Synchronous Payload Envelope (SPE). Line and Section Overhead octets are combined with the SPE and then scrambled using the frame-synchronous scrambler to produce the final transmitted WIS frame. The WIS continuously generates one WIS frame every 125μ s.

5.1.10 Transmit Multiplexer and Clock Generation

A clock divider generates the clock frequencies required to multiplex the 64 bit wide bus coming from the TX WIS into a single 10Gb/s output, from the locally generated 10GHz clock.

5.1.11 Output Data Driver

The output driver has a nominal output voltage of 250 mVpp per side. TXOUTN and TXOUTP are both terminated on chip with 50Ω to 1.2V. The output level can be adjusted via an external resistor connected to TXLEVEL. The output polarity can be inverted by pulling pin TXOUT_SEL high.

5.1.12 Line Timing Mode

Line timing is used in the QT2032 to ensure the transmitted data is synchronized to the SONET network. In line timing mode, the reference clock used for the transmit PLL is derived from the recovered receive clock. Line timing mode is enabled by the Line Timing Control Register. Please see Section 6, "Datapath Clocking," on page 26 for details.

Line timing is not supported in the QT2022.



5.2 Receive Path

5.2.1 Limiting Amp

The receiver input contains a limiting amplifier designed for a differential CML voltage across the RXIN inputs. The input polarity can be selected by pin RXIN_SEL. The input sensitivity is good enough to eliminate the need for an external limiting amp in many applications. For a system card application, the XFP input pin is set high and an input equalization circuit is activated to allow for longer FR4 traces. It can be deactivated by asserting MDIO register bit 1.C030h.6.

AC coupling of the 10Gb/s input signal(s) is required to achieve good sensitivity as it reduces the amount of 1/f noise at the input to the QT2022/32.

5.2.2 Loss of Signal Detector

The RX input limiting amplifier also incorporates a loss of signal detector. The loss of signal detector is disabled if the input equalization circuit is activated (see Section 5.2.1 above). The LOSOUTB signal is available as an output. The loss of signal threshold (in mVpp) is controlled by adjusting the value of the external resistor connected to the ITH_LOS pin. The threshold includes built-in hysteresis to prevent LOSOUTB chatter. The LOSOUTB signal can be externally connected to the RXLOSB_I input (this allows for the option of using an external TIALA with its own loss of signal detector).

5.2.3 Clock Recovery

The output of the limiting amp goes to a clock and data recovery (CDR) circuit. When the PLL is frequency locked to the incoming data, the internal signal, frxlock is asserted. When frxlock is low the receive data outputs RxX-AUI<0:3> will transmit idle frames and error codes. The state of frxlock is reflected in the 'PMA receive link status' bit, 1.1.2, a latched low register bit whose value is determined by the equation {frxlock AND RXLOSB_I}. The state of the RXLOSB_I input is shown separately in Register bit 1.10.0.

The PLL uses an external loop filter. See Section 18.1, "External Components," on page 209 for the loop filter components and values.

Recovered Clock Frequency Monitoring and RXCLK

When the receive recovered clock is more than 500 ppm from the transmit reference clock, a synchronization error is declared and the internal signal *sync_err* goes high. *sync_err* can be viewed at MDIO register 1.C001h.1. This is a latched high register bit that is cleared on read. On powerup or reset, the register must be read to clear it.

5.2.4 Demultiplexer and Clock Divider

All clocks needed for the demultiplexer and the reset of the receive path are generated in this block by dividing down the 10GHz recovered clock. The demultiplexer converts the 10 Gb/s serial incoming data into 64 parallel bits. A divide-by-64 recovered clock can be output at RXPLLOUT by setting MDIO register bit 1.C001h.6 = 1.

5.2.5 Receive WAN Interface Sublayer (WIS) (QT2032 Only)

The RX WIS block receives data from a SONET link and extracts the Ethernet payload from the STS-192c SPE. It also monitors the integrity of data at the Section, Line and Path levels and monitors both near and far end faults. The WIS receive and transmit blocks can be bypassed by setting MDIO register 2.7.0 to 0 or if LANMODE = 1.





5.2.6 Frame Synchronization

The frame synchronizer takes the 64 bit wide data bus output from the demultiplexer and converts it to a 66 bit wide data bus. The 66 bits are composed of 2 sync bits followed by 64 bits of data. The sync bits are used to synchronize the data stream on a frame boundary. The bus rate at each stage will depend on the selected protocol.

The chip also monitors invalid sync header bits. Valid sync bits include '01' and '10'. The combinations '11' and '00' are invalid. When an invalid sync header is detected, a 6-bit counter is incremented. This counter is located in MDIO register bits 3.33.13:8. This is a read only, non-rollover counter that is cleared when read. The counter will count a maximum of 16 sync header errors in a 125 μ s window.

When there are 16 or more sync header errors in a 125μ s window, the 'hi_ber' flag is set to 1 in MDIO register bit 3.32.1 (3.20h.1). This is a read only register bit that is cleared when read. The algorithm for counting sync header errors and detecting 'hi_ber' follows the 'BER monitor state machine' described in IEEE 802.3 Figure 49-13.

5.2.7 Descrambler

The descrambler processes the payload to reverse the effect of the scrambler on the payload. The descrambler is self-synchronizing. It calculates the inverse of the scrambler function using the polynomial $1+x^{39}+x^{58}$. Only the 64 data bits are passed through the descrambler. The descrambler is bypassed when the scrambler bypass mode is enabled through MDIO register 3.C000h.1.

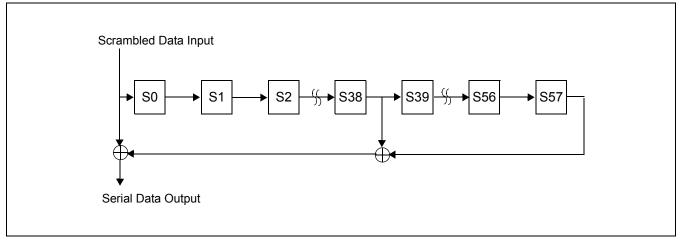


Figure 4: Receive Descrambler

5.2.8 66B/64B Decoder

The decoder performs the inverse function of the encoder. This block converts the 64 bit payload back into the original eight 8-bit codes. Valid code word formats are described in IEEE 802.3-2005 Figure 49-7.

5.2.9 Receive Rate Adjust

Data from the 66B/64B decoder is written into a rate compensation FIFO using the fiber recovered clock. The outgoing data is read out using the XAUI reference clock. Due to the fact that these clocks are derived from different sources, a rate adjust operation needs to be performed. The rate compensation block accomplishes this by either adding or dropping Idle ordered_sets, as required, from the data stream. The minimum inter packet gap of five characters and sequence ordered set messages are maintained.

Receive rate adjust operation is monitored in MDIO register 4.C002h. This register flags idle code removal and insertion in bits 13:12 (normal operation), as well as overflow/underflow in bits 7:6 (fault condition).

5.2.10 8B/10B Encoder

The data bus is divided into four 8-bit wide data channels. Each of the four channels has independent 8B/10B encoders which will convert the 8 bit data lanes into 10 bit code words. Either a positive or negative disparity 10 bit code word will be selected, depending on the running disparity.

5.2.11 Receive Multiplexer and XAUI Interface

After 8b/10b encoding has been added, the receive multiplexer serializes data words to form four 3.125Gb/s output data lanes. The XAUI output drivers provide low-swing differential outputs with 100Ω differential output impedance and are intended to be AC coupled. The 3.125 GHz timing is derived from the reference clock, EREFCLK.

6 Datapath Clocking

This section explains the clocking architecture and features of the QT2022 & QT2032.

6.1 LAN Application Timing Modes (QT2022 and QT2032)

6.1.1 Timing Architecture in LAN Mode

This section describes the timing of the QT2022. The QT2032 will follow this timing architecture when placed in LAN mode.

In LAN mode, the RxXAUI and TX Fiber quadrants share timing references, but are generally independent of the TxXAUI and RX Fiber quadrants. The timing architecture and timing paths in LAN mode are illustrated in Figure 5.

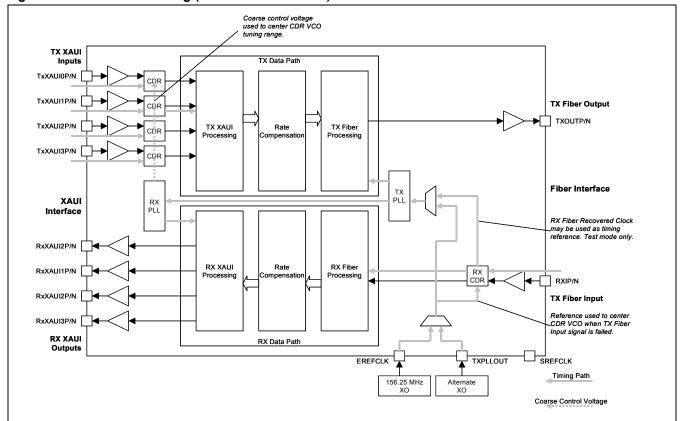


Figure 5: LAN Mode Timing (QT2022 and QT2032)



The TX Fiber Output derives timing from a 156.25MHz reference applied at EREFCLK or an alternate reference applied at TXPLLOUT. When applying an alternate reference to TXPLLOUT, the TXPLLOUT output driver must be disabled using MDIO bit 1.C001h.3. Selection of the desired reference is determined by the state of MDIO bit 1.C001h.7. Refer to Table 7 on page 35 for details. The TX PLL generates a 10 GHz clock from the reference by multiplying the frequency. The TX PLL output provides a clock for the TX Fiber Processing Block and Outputs.

The RX Fiber CDR locks to the received signal and generates a recovered clock. The recovered clock provides timing to the RX Fiber Processing Block. When a SYNCERR is generated, the RX Fiber Input CDR will lock to the reference applied to the selected reference, either EREFCLK or TXPLLOUT, to pull the frequency back to nominal. Once the SYNCERR has cleared, the CDR will attempt to lock to the RX Fiber Input signal.

The RxXAUI Outputs derive timing from the TX PLL. The RX PLL generates the 3.125 GHz clock from a reference from the TX PLL. The RX PLL output provides a clock for the RX XAUI Processing Block and Outputs.

For each TxXAUI Input, a CDR locks to the received signal and generates a recovered clock. The recovered clock from lane 1 (TxXAUI1) provides a clock for the TxXAUI Processing Block.

Transfer of data across clock boundaries along each data path is accomplished through rate compensation blocks.

6.1.2 Forced Line Timing Mode

The Forced Line Timing mode forces the TX Fiber Output to derive timing from the RX Fiber Input recovered clock. The Forced Line Timing mode is useful for various test scenarios or implementations where the timing is controlled externally. Forced Line Timing is controlled by MDIO register bit 1.C001h.9.

6.2 WAN Application Timing Modes (QT2032 Only)

This section describes additional timing modes supported only by the QT2032. The timing paths through the QT2032 vary depending upon the mode of the device. Some modes that affect these paths include:

- 1. Fiber Interface Mode: either LAN or WAN, see Section 8.3.1 on page 59.
- 2. VCXO PLL Mode: enabled or disabled, see Section 6.2.4 on page 32.
- 3. Line Timing Mode: Disabled, Automatic, or Forced, see Section 6.2.2 on page 30.

In order to understand the relationship between timing reference and the behavior of input and output signals it is important to understand the general timing architecture of the QT2032. In the following sections, the timing architecture in the WAN mode is explained.

6.2.1 Timing Architecture in WAN mode (QT2032 Only)

In WAN mode, each quadrant TxXAUI, RxXAUI, RX Fiber, and TX Fiber is independently timed. The typical timing architecture and timing paths in WAN mode are illustrated in Figure 5. An optional configuration in VCXOONLY mode (VCXOB = 0 and VCXOONLY = 1) where the VCXO can provide a reference frequency is also illustrated in Figure 7.

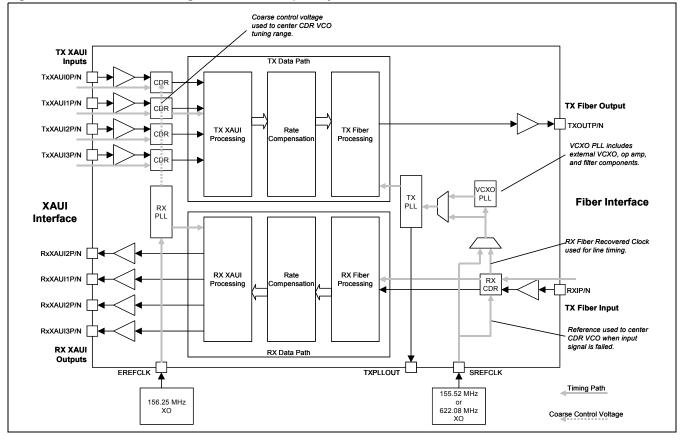


Figure 6: WAN Mode Timing with Fixed Frequency Reference

applied

micro



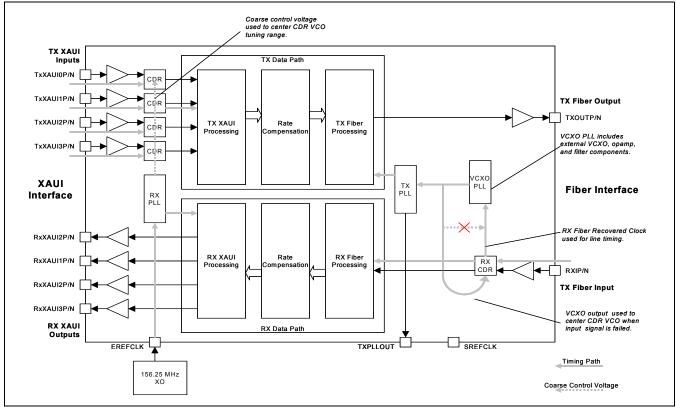


Figure 7: WAN Mode Timing without Fixed Frequency Reference

The TX Fiber Output derives timing either from a 155.52MHz or 622.08MHz reference applied at SREFCLK (or VCXOI when in VCXOONLY mode) or the received signal on the RX Fiber Input. The TX PLL generates a 10 GHz clock from the selected reference by multiplying the frequency. The TX PLL output provides timing for the TX Fiber Processing Block and Output. By default the TX PLL will lock to the reference applied at SREFCLK (or VCXOI when in VCXOONLY mode), however it may optionally lock to the recovered clock from the RX Fiber CDR as explained in Section 6.2.2 on page 30. In order to reduce phase noise from the selected reference and consequently on the TX Fiber Output, an optional VCXO PLL may be used to filter phase noise on the selected reference, as explained in Section on page 32.

The RX Fiber CDR locks to the received signal and generates a recovered clock. The recovered clock provides a clock to the RX Fiber Processing Block and provides an optional reference for the TX Fiber Output. When the recovered clock deviates by >500ppm from the reference clock, the RX Fiber Input CDR will then lock to the reference from SREFCLK (or VCXOI when in VCXOONLY mode) to pull the VCO frequency to nominal frequency. The CDR will lock to the RX Fiber Input signal when the clock rate is <500ppm from the reference.

The RX XAUI Outputs derive timing from a 156.25 MHz reference applied at EREFCLK. The RX PLL generates the 3.125 GHz reference from the reference by multiplying the frequency. The RX PLL output provides a clock for the RX XAUI Processing Block and Outputs.

For each TX XAUI Input, a CDR locks to the received signal and generates a recovered clock. The recovered clock from lane 1 (TxXAUI1) provides timing to the TX XAUI Processing Block.

Transfer of data across clock boundaries along each data path is accomplished through rate compensation blocks.

6.2.2 Line Timing

Line timing permits the TX Fiber Output to derive timing from the RX Fiber Input. This mode is useful for applications where it is necessary or desirable for the TX Fiber Output to be synchronous with equipment at the far end. For example, the Fiber Interface may connect to a SONET ADM (Add/Drop Multiplexer) which directs synchronous SONET payloads to one of several line outputs.

Three line timing control modes are provided: Line Timing Disabled, Automatic Line Timing, and Forced Line Timing. The Automatic Line Timing control mode is supported only in WAN mode. The line timing control mode is determined by the MDIO line timing control bits 1.C001h.9 and 1.C001h.14 which are interpreted as described in Table 5, "Line Timing Control Modes".

Force Line Timing 1.C001h.9	Automatic Line Timing 1.C001h.14	Line Timing Mode
0	0	Line Timing Disabled In WAN mode the TX Fiber Output always derives timing from SREFCLK (or VCXOI in VCXOONLY mode). In LAN mode the TX Fiber Output always derives timing from EREFCLK or TXPLLOUT. Refer to section Section on page 30.
0	1	Automatic Line Timing In WAN mode only, the TX Fiber Output derives timing from the recovered clock from the RX Fiber Input when the RX Fiber Input is not failed. When the RX Fiber Input is failed, the TX Fiber Output derives timing from SREFCLK (or VCXOI in VCXOONLY mode). Refer to section Section on page 31.
1	x	Forced Line Timing In WAN or LAN mode, the TX Fiber Output always derives timing from the recovered clock from the RX Fiber Input. Refer to section Section 6.2.3 on page 32.

 Table 5:
 Line Timing Control Modes

In WAN mode, by default for all Line Timing Control Modes, the synchronization status message (SSM) in the transmitted WIS S1 byte is DUS "Don't Use for Synchronization" (1111). This indicates to the far end equipment that this timing signal should not be used as a timing reference, e.g, for line timing. For more information on SSMs see Telcordia GR-253-CORE Issue 3 Section 5.4.2.

To meet SONET jitter transfer requirements, the external VCXO must be implemented and used in Line Timing mode. See Section 6.2.4 on page 32 for details.

Line Timing Disabled Mode

The Line Timing Disabled mode is the default Line Timing mode. In this mode, line timing is fully disabled. This mode is used in applications where the TX Fiber Output is intended to always derive timing from a local frequency source such as a crystal oscillator. In WAN mode, the TX Fiber Output will always derive timing from SREFCLK or VCXOI in VCXOONLY mode. In LAN mode, the TX Fiber Output will always derived timing from either EREFCLK or TXPLLOUT.





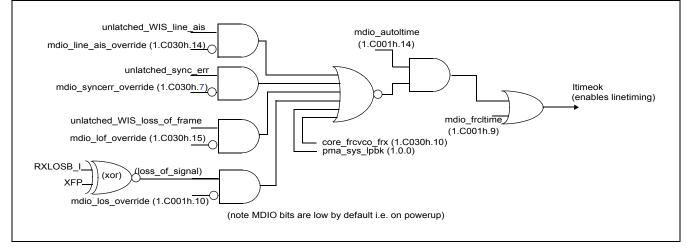
Automatic Line Timing Mode

The Automatic Line Timing mode allows the TX Fiber Output to derive timing from a valid recovered clock from the RX Fiber Input. When the RX Fiber Input is not valid, the TX Fiber Output derives timing from SREFCLK (or from VCXOI in VCXOONLY mode). The QT2032 deems the recovered clock from the RX Fiber Input to be valid when all of the following conditions are TRUE:

- 1. RX Fiber CDR VCO is not in forced mode (MDIO 1.C030h.10 = 0)
- 2. Fiber Interface is not in PMA System Loopback (MDIO 1.0.0 = 0)
- PMA LOS defect is clear RXLOSB_I = 1 (visible in MDIO 1.10.0) or LOS Override is Set (MDIO 1.C001h.10 = 1). This condition assumes that XFP = 0. If XFP = 1 then the RXLOSB_I is inverted.
- PMA SYNCERR unlatched defect is clear (latched version visible in MDIO register 1.C001h.1) or SYNCERR Override is Set (MDIO register 1.C030h.5:4 = '01')
- 5. WIS LOF unlatched defect is clear (latched version visible in MDIO register 2.33.7) or LOF Override is Set (MDIO register 1.C030h.15)
- 6. WIS Line AIS unlatched defect is clear (latched version visible in MDIO register 2.33.4) or AIS Override is Set (MDIO register 1.C030h.14)

For each defect used to disable line timing, an override capability is provided. By default, the override for each defect is Clear. However, the override for each defect may be independently set to prevent the associated defect from disabling line timing. The effective logic used to generate the internal signal enabling line timing, *ltimeok*, is represented in Figure 8.





Further qualification of the signal may be required by external software. For example, it must be determined whether the use of the received signal as a line timing reference will result in a timing loop. This may happen if the far end is also in line timing mode. Qualification of the received signal may be achieved using the Synchronization Status Message (SSM) in the WIS S1 byte. Refer to section Section 7.3.3 on page 47.

6.2.3 Forced Line Timing Mode

The Forced Line Timing mode forces the TX Fiber Output to derive timing from the RX Fiber Input recovered clock. The Forced Line Timing mode is useful for various test scenarios or implementations where the timing is controlled externally. This mode is supported in WAN and LAN modes.

Support for External Line Timing Control

In order to support external control (e.g., by firmware) of the line timing the LASI may be configured to interrupt on any of the relevant receiver conditions. Refer to Section 8.4.1 on page 62. Relevant defects and conditions include:

- 1. PMA LOS defect RXLOSB_I = 0 (visible in MDIO 1.10d.0). This condition assumes that XFP = 0. If XFP = 1 then the RXLOSB_I active state is inverted.
- 2. PMA sync_err defect (MDIO register 1.C001h.1)
- 3. WIS LOF defect (MDIO register 2.33d.7)
- 4. WIS Line AIS defect (MDIO register 2.33d.4)
- 5. Validated Synchronization Status message in received WIS S1 byte has changed. Refer to section Section 7.3.3 on page 47.

A separate interrupt enable bit for each of the conditions listed above is provided. By default, each enable bit is clear. The enable bit for each condition may be set as required by the implementation.

6.2.4 VCXO PLL

As discussed in Section 6.2.1 on page 27, the QT2032 provides support for a VCXO based PLL to filter phase noise on the SREFCLK or recovered clock to ensure compliant jitter generation and jitter transfer performance as measured on the TX Fiber Output. The VCXO PLL is supported only in WAN mode. The QT2032 further supports a self-centering VCXO to reduce board cost by eliminating the need for a fixed frequency XO driving SREFCLK when the VXCO PLL is used.

VCXO PLL Interface

The QT2032 VCXO PLL interface is illustrated in Figure 9.

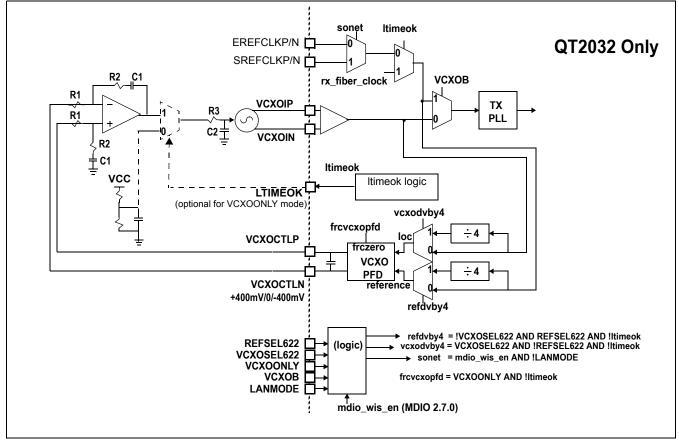
When using the VCXO PLL, VCXOB is set low, and the VCXO drives the reference input of the TX PLL. The onchip VCXO phase-frequency detector (VCXO PFD) compares the phase and frequency of the VCXO clock with that of a reference clock and generates a tri-state output which drives an external opamp configured as a differential integrator. The external opamp and power supply are chosen to provide the appropriate voltage swing for the VCXO. The reference clock input to the VCXO PFD may be from either SREFCLK or the RX Fiber Input recovered clock (rx_fiber_clock). The selectable divide-by-4 blocks at the VCXO PFD inputs allow for any combination of 155 MHz or 622 MHz reference clock and VCXO frequencies based on the settings of REFSEL622 and VCXOSEL622. For implementation details refer to Section 6.2.5 on page 34.

The LTIMEOK output indicates that line timing conditions are valid and that line timing is internally enabled. In a linetiming application with no reference applied to SREFCLK, indicated by pulling VCXOONLY high, the LTIMEOK output being low may be used to force the VCXO to its center frequency; when the LTIMEOK output is low, the VCXO PFD differential output is coincidentally forced to 0 V. The logic which generates LTIMEOK is illustrated in figure 8 on page 31.

QT2032 VCXO interface parameters are specified in Table 74 on page 202.







6.2.5 VCXO PLL Implementation Recommendations

VCXO PLL Pin Settings

Recommended pin settings for each potential application of the VCXO PLL are listed in Table 6 on page 34.

Table 6:	VCXO PLL	Control	Pin Settings
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Implementation			QT2032 Pin Settings			
VCXO PLL	SREFCLK Frequency (MHz)	VCXO Frequency (MHz)	VCXOB	VCXOONLY	REFSEL622	VCXOSEL622
No	155.52	х	1	х	0	x
No	622.08	x	1	x	1	x
Yes	155.52	155.52	0	0	0	0
Yes	155.52	622.08	0	0	0	1
Yes	622.08	155.52	0	0	1	0
Yes	622.08	622.08	0	0	1	1
Yes	No source ¹	155.52	0	1	0	0
Yes	No source ¹	622.08	0	1	1	1

1. If no SREFCLK is implemented, and 20ppm operation for SONET applications is required, then the VCXO will likely need to be temperature-compensated.

6.2.6 VCXO Usage for QT2032 in LAN Mode

Usage of an external VCXO is not supported in LAN mode. When a VCXO is implemented and the chip is switched to LAN mode, the VCXO must be disabled by setting pin VCXOB=1. If external control to the VXCOB pin is not available, the polarity of the pin logic can be inverted. This is accomplished by setting MDIO register bit 1.D003h.9=1.

Control of the operating mode (WAN or LAN) is described in Section 8.3.1 on page 59.



6.3 TXPLLOUT Output Clock Driver

A clock from the transmit PLL can be output at pins TXPLLOUTP/N to serve as a reference clock to the XFP module in an XFP host board application or for test purposes. The output driver is a CML type.

In XFP mode (XFP=1), the output driver is enabled by default and can be disabled by setting 1.C001h.3=1. In non-XFP mode (XFP=0), the output driver is disabled by default and can be enabled by setting 1.C001h.3=1. The driver is also automatically disabled when 1.C001h.7=1 to allow the TXPLLOUTP/N pins to serve as the input for a second reference source in a multi-rate module. The TXPLLOUT control logic is detailed in figure 7 on page 35.

	Inputs	State			
LAN Reference Select MDIO 1.C001h.7 XFP Pin		TXPLLOUT Driver Enable MDIO 1.C001h.3	TXPLLOUT Driver State	Selected LAN Reference Input	
0	0	0	OFF	EREFCLK	
0	0	1	ON	EREFCLK	
0	1	0	ON	EREFCLK	
0	1	1	OFF	EREFCLK	
1	x	x	OFF	TXPLLOUT	

 Table 7:
 TXPLLOUT Driver Control and LAN Reference Selection

For the QT2032, the frequency of TXPLLOUTP/N depends on several pin settings as shown in Table 8. For the QT2022, the frequency is solely determined by the XFP pin (shown in bold text).

Table 8:	TXPLLOUT Output Frequency vs TXOUT Baud-rate
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XFP ¹	SONET ²	VCXOB	VCXOSEL622	REFSEL622	divide by	note
1	Х	Х	Х	х	64	(CMOS source, results in higher jitter in this mode)
0	0	Х	Х	х	66	(CML source, results in lower jitter in this mode)
0	1	0	0	Х	64	(CML source, results in lower jitter in this mode)
0	1	0	1	Х	16	(CML source, results in lower jitter in this mode)
0	1	1	Х	0	64	(CML source, results in lower jitter in this mode)
0	1	1	Х	1	16	(CML source, results in lower jitter in this mode)

1. The indicated polarity of the XFP input can be reversed by asserting bit 1.C001h.2.

2. SONET = bit_2.7.0 AND not(LANMODE).

7 WAN Interface Sublayer (WIS) Description (QT2032 Only)

This section describes the function and extended features of the WIS block in the QT2032. The WIS block is enabled and the chip will operate in WAN mode when LANMODE = 0. The WIS block can be bypassed by setting MDIO register 2.7.0 to 0 or if LANMODE = 1. When bypassed, the QT2032 will be 10GE (or 10GFC) protocol compliant.

7.1 WIS Transmitter

The WIS transmitter functionality is illustrated in Figure 10 and is fully compliant with IEEE 802.3-2005 Clause 50. Additionally, extended features have been provided for APS Channel, synchronization status, line BIP-8 signal fail & degrade, pointer justification event counters, 64-byte J1 messaging, and transport overhead (TOH) serial interface. These features are described in Section 7.3, "Extended WIS Features," on page 46.

7.1.1 WIS Frame

Figure 10 illustrates the structure of an STS-192c WIS frame, which is comprised of transport overhead and a payload. The overhead fields are described in the following sections.

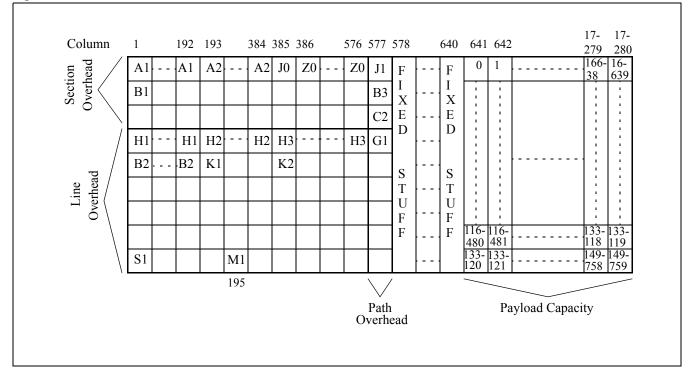


Figure 10: WIS Frame Structure



7.1.2 Path Overhead

The main function of this overhead is to provide error monitoring and connectivity checks between Path Terminating Equipment (PTE).

Table 9: Path Overhead Definitions

Overhead Octet	Description	Value (Bits 18)	Function
J1	Path Trace	Varies	Used to continuously send a repeating Trace Message which may be 16 octets (or 64 octets, see Section 7.3.7 Extended J1 Trace Messaging (64 bytes)) in length. This information is obtained from the Layer Management block.
B3	Path BIP-8	Varies	Used for path error monitoring functionality. This is a bit-interleaved parity-8 code using even parity and is calculated over all bits of the previous STS-192c SPE before scrambling.
C2	STS Path Signal Label	00011010	Identifies the construction and content of the STS-192c SPE as a 10 Gigabit Ethernet stream.
G1	Path Status	Varies	Used to convey back information regarding status and performance to an originating STS-192c PTE. Bits [14] - Remote Error Indication (REI) - These four bits count the number of B3 errors that have been detected. There are nine legal values which are 0000, 0001,0010,0011, 0100, 0101, 0110, 0111, 1000. Any other value will be interpreted by the originating PTE as 0000. Bits [58] - Remote Defect Indication (RDI) - These bits are used to convey error information to the remote PTE.
F2	Path User Channel	00000000	Unsupported, not required by IEEE 802.3aClause 50.
H4	Multiframe Indicator	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
Z3	Growth	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
Z4	Growth	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
N1	Tandem connection maintenance/Path data channel	0000000	Unsupported, not required by IEEE 802.3 Clause 50.

7.1.3 Line Overhead

The Line layer is responsible for the reliable transport of the Path layer payload and overhead. Line overhead is accessed where SPEs are multiplexed or protection switching is performed.

Overhead Octet	Description	Value (Bits 18)	Function
H1-H2	Pointer	NDF field = 0110 SS field = 00 Pointer = 10000 01010	The pointer marks the beginning of the STS-192c SPE. It also indicates a concatenated payload. On reset the New data flag is also set.
H3	Pointer action	0000000	This byte is provided for frequency justification purposes. In the transmit direction this byte serves no purpose. In the receive direction if a negative stuff operation has been indicated by the pointer bytes this byte will contain valid payload data.
B2	Line BIP-8	Varies	Used for line error monitoring functionality. This is a bit-interleaved parity-8 code using even parity and is calculated over all bits of the line overhead and STS-1 Envelope capacity of the previous STS-1 frame before scrambling. The computed B2 is placed in the line overhead of each STS-1 frame before scrambling. When using the TOH Serial interface, the inserted value of B2 represents an inversion mask. An inserted value of all zeroes preserves the calculated B2 octet.
K1-K2	Automatic Protection Switch (APS) Channel	K1 - 00000001 K2[15] - 00010 K2[68] - Varies	These bytes are allocated for APS signalling between Line level entities. These bytes are only defined for STS-1 number 1 in the STS-192c frame. K2[68] transports either an RDI-L encoding or is set to 000.
D4-D12	Line Data Communications Channel (DCC)	All octets set to 00000000	Unsupported, not required by IEEE 802.3 Clause 50.
S1	Synchronization messaging	00001111	Unsupported, not required by IEEE 802.3 Clause 50.
MO	STS-1 Line Remote Error Indication (REI)	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
M1	STS-N line REI	Varies	This octet is used for conveying the number of errors detected by the Line BIP-8 (B2) bytes. The count has legal values from 0 to 255. If greater than 255 errors are detected by the Line BIP-8 the count is set to 255.
Z1	Reserved for line growth	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
Z2	Reserved for line growth	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
E2	Orderwire	0000000	Unsupported, not required by IEEE 802.3 Clause 50.

Table 10: Line Overhead Definitions



7.1.4 Section Overhead

This layer is responsible for reliable transport of an STS-N frame across the physical medium. Its functions include framing, scrambling and error monitoring.

Overhead Octet	Description	Value (Bits 18)	Function
A1, A2	Framing	A1 - 11110110 A2 - 00101000	These bytes are allocated in each STS-1 for framing purposes. A1, A2 bytes are never scrambled.
JO	Section Trace	Varies	This byte is defined only for STS-1 of the STS-192c frame. It is used to transmit one fixed byte so as to allow a receiving terminal to check its connection to an intended transmitter. This byte is specified in the Layer Management block. J0 byte is never scrambled.
Z0	Section Growth	11001100	Unsupported, not required by IEEE 802.3 Clause 50.
B1	Section BIP-8	Varies	This byte is used for the section error monitoring function. This is a bit- interleaved parity 8 code using even parity. It is calculated over all bits of the previous STS-192c frame after scrambling. When using the TOH Serial interface, the inserted value of B1 represents an inversion mask. An inserted value of all zeroes preserves the calculated B1 octet.
E1	Orderwire	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
F1	Section User Channel	0000000	Unsupported, not required by IEEE 802.3 Clause 50.
D1-D3	Section Data Communication channel (DCC)	All octets set to 00000000	Unsupported, not required by IEEE 802.3 Clause 50.

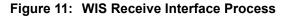
Table 11: Section Overhead Definitions

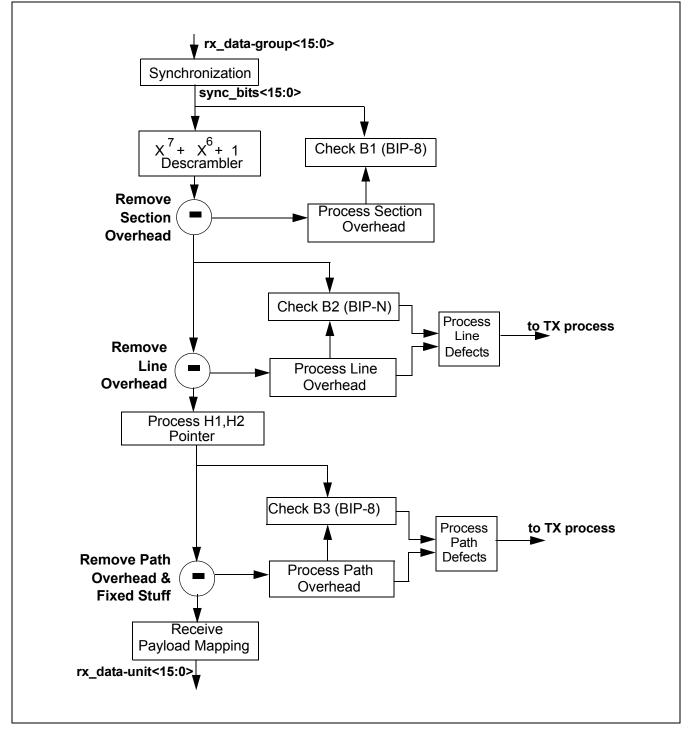
7.1.5 Test Pattern Generation

The QT2032 provides WIS compliant test pattern generation features. Please refer to Section 11.5, "WIS Test Features (QT2032 only)," on page 102 for details.

7.2 WIS Receiver

The WIS receiver functionality is illustrated in Figure 11. This is fully compliant with IEEE 802.3 Clause 50. There are additional extended features described in Section 7.3, "Extended WIS Features," on page 46.





The Synchronization process accepts data from the PMA (via the PMA Service Interface, depicted as rx_datagroup<15:0> in Figure 11) and performs an alignment operation to delineate both octet and frame boundaries within the received data stream. Aligned and framed data is passed to the WIS Receive process (depicted as sync_bits<15:0> in Figure 11), where Section and Line Overhead octets are extracted from the WIS frames and processed after descrambling the frame data. The payload pointer within the Line Overhead is used to delineate the start and end of received SPE, and the Path Overhead is extracted from the SPE and processed. Finally, the fixed stuff is removed from the SPE and the resulting data stream is conveyed to the PCS via the WIS Service Interface (depicted as rx_data-unit<15:0>).

7.2.1 WIS Synchronization (Octet and Frame Delineation)

The WIS Synchronization process delineates both octet and WIS frame boundaries in the received signal. Delineation of these boundaries and alignment of the received data are done prior to performing the descrambling function. (The SPE delineation process is done after descrambling the received data.)

The WIS Synchronization process monitors the last 64 A1 octets and the first 64 A2 octets in the Section Overhead, forming the synchronization pattern. WIS Sync is achieved after 4 frames with valid synchronization patterns are received. A loss of WIS synchronization (WIS Loss of Sync) is triggered when any bit errors are detected within the synchronization pattern for 4 consecutive frames. When the WIS receiver is not in the Sync state all other WIS processes are suspended. This includes all further alarm processing, including SEF and LOF alarms. The WIS Synchronization process follows the state diagrams detailed in IEEE 802.3-2005 Figures 50-15 and 50-16.

A loss of WIS synchronization is reported by the chip as a WIS Local Fault in MDIO register bit 2.1.7. It is also linked to LASI alarm bit 1.9003h.9. The parameter values for the WIS Synchronization state diagram are listed in Table 12 on page 41.

Parameter	Value	Purpose
f	64	Controls width of Sync_Pattern pattern
i	128	Controls width of Hunt_Pattern pattern
j	64	Controls width of Presync_Pattern pattern
k	64	Controls width of Presync_Pattern pattern
m	4	Controls hysteresis for SYNC state entry
n	4	Controls hysteresis for SYNC state exit

Table 12: WIS Synchronization Process Parameters

7.2.2 SEF Defect Generation

The device monitors for an SEF defect by checking *all* 192 A1 and A2 octets in the Section Overhead. This is a separate monitoring process from WIS Synchronization and uses a larger framing pattern. An SEF defect is raised when any bit errors are detected within the framing pattern for 5 consecutive frames. An SEF defect is terminated when two contiguous error-free frame words are detected.

The SEF framing pattern is a superset of the WIS Synchronization framing pattern. If bit errors are detected within the WIS Synchronization framing pattern, a WIS Loss of Sync alarm will be raised after 4 frames. In this case an SEF defect will not be raised. If bit errors are detected in the wider SEF framing pattern then an SEF defect will be raised but a WIS Loss of Sync alarm will not. ¹

^{1.} Consult the Errata for additional details.

7.2.3 LOF Defect Generation

An LOF defect occurs when a Severely Errored Frame (SEF) persists for a period of 3ms. The LOF defect is terminated when no SEF defects are detected for a period T, where $1ms \le T \le 3ms$.

7.2.4 LOS Defect Generation

An LOS defect occurs upon detection of no transitions on the incoming signal for time T, where T = $41.6667 \mu s$ (three row periods). An LOS defect is terminated after a time period equal to the greater of $125 \mu s$ or 2.5 T containing no transition-free intervals of length T, where T = three row periods.

Note: If no signal is applied to the fiber input, the WIS Synchronization process loses SYNC before the LOS, or LOF alarms are raised. Since the WIS suspends normal processes when there is a loss of WIS Sync, the LOS and LOF alarms will be masked. The WIS Synchronization alarm can be treated as an effective replacement for the LOS/LOF alarms.



7.2.5 Descrambler

The descrambler processes the frame to reverse the effect of the scrambler using the same polynomial as scrambler, with the exception of the A1,A2,J0 and Z0 octets (576 octets in total, per WIS frame), which bypass the descrambler.

7.2.6 Section Overhead Extraction and B1 Check

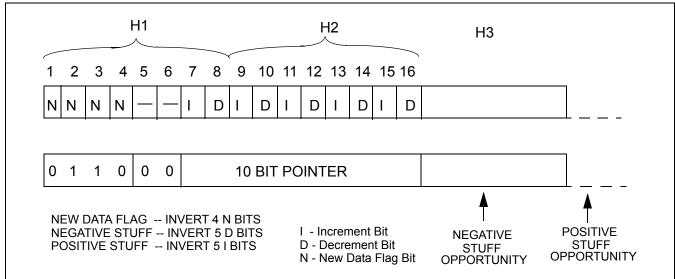
Section Overhead extraction extracts J0, Z0 and B1 and also removes the Section Overhead from the input data stream. The J0 and Z0 will be bypassed by the descrambler. The J0 octet is passed to the Station Management entity (MDIO block) via a specific register (J0 RX register).

The B1 octet is a bit-interleaved parity 8 code using even parity. It is extracted from the incoming WIS frame after the descrambler. The B1 octet is stored and compared with the calculated B1 of the previous frame. The B1 check performs the B1 calculation of the incoming WIS frame before descrambling and also performs the comparison between the calculated B1 octet and the received B1 octet extracted from the incoming frame.

7.2.7 Line Overhead Extraction, Pointer (H1,H2) Process, and B2 Check

Line Overhead extraction removes the H1, H2, H3, B2, K1, K2, S1 and M1 octets and also the Line Overhead from the WIS stream which does not include the Section Overhead. The M1 octet is passed to the MDIO block via a specific register (WIS M1 register).

RDI-L (Line Remote Defect Indication) signal is asserted by a 110 code in bit positions 6,7 and 8 of the K1 octet. And RDI-L signal is de-asserted by any code other than the 110 code in the bits 6,7 and 8 of K2 octet. The RDI-L is passed to the Station Management entity (MDIO block) via a specific register. The Pointer (H1,H2) process uses the H1 and H2 taken from Line Overhead extraction. The pointer marks the beginning of the STS-192c SPE. It also indicates a concatenated payload. The two bytes (H1,H2) allocated to the pointer function can be viewed as one word as shown in Figure 12. The last ten bits (bit 7-16) of the pointer word carry the pointer value.





The operations allowed by the pointer are listed below. Corresponding event flags are asserted high in Register 2.C000h:

- 1. positive stuff requires:
 - a) NDF=0110 (can support one bit corruption)
 - b) 3 or more I-bits inverted
 - c) less than 3 D-bits inverted
- 2. negative stuff requires:
 - a) NDF=0110 (can support one bit corruption)
 - b) 3 or more D-Bits inverted
 - c) less than 3 I-Bits inverted
- 3. pointer jump: there are 2 cases where the pointer can jump:
 - a) NDF = 1001 (can support one bit corruption) with 10 bits pointer in the range (0-782)

b) NDF =0110 (can support one bit corruption) with 3 consecutive frames with same 10 bits pointer value in range (0-782)

Note: In the case where the pointer signaling indicates both positive and negative stuff operations, the logic considers this an invalid pointer and ignores the pointer value.

The following list summarizes the rules for interpreting the pointer:

- 1. During normal operation, the pointer locates the start of the SPE (J1);
- 2. Any variation from the current pointer value is ignored unless a consistent new value is received three times consecutively or it is preceded by one of rules 4,5 or 6. Any consistent new value received three times consecutively overrides (i.e. takes priority over) rules 4,5 or 6;
- 3. If the pointer value contains the Concatenation Value, then the operations performed on the STS-1 are identical to those performed on the first STS-1 within the STS-Nc. Operations 4 and 5 do not apply to this pointer value.
- 4. If the majority of the I-bits of the pointer word are inverted, a positive stuff operation is indicated. Subsequent pointer values are incremented by one;
- 5. If the majority of the D-bits of the pointer word are inverted, a negative stuff operation is indicated. Subsequent pointer values are decremented by one;
- 6. If the New Data Flag is set to 1001, then the coincident pointer value will replace the current one at the offset indicated by the new pointer value regardless of the state of the receive.

The QT2032 receive pointer processor can react to any change in the pointer value, for example, the receiver can react to frame after frame of positive stuff, negative stuff.

Here are the cases where the pointer is considered as invalid:

- 1. NDF = 1001 with pointer value > 782
- 2. NDF = 0110 and consistent value is received 3 times consecutively with pointer value > 782
- 3. 2 bits corruption in the NDF bits.
- 4. The pointer value is asking for increment and decrement at the same time and value of the pointer > 782.

The QT2032 receive pointer processor checks the concatenation indicator in the H1H2 fields (after the first H1H2 bytes). A value of '93FF' is expected. Any other value will cause a LOP-P condition. The SS bits must have a value of '00'. In an SDH network, non-zero SS bits are allowed in the concatenation indicator. If non-zero values are used in the concatenation indicator an LOP-P defect will be triggered.

If the pointer is invalid the bit 1 of register 2.32768 with be set to 1.



The QT2032 implements the logic that detects when the far-end transmit side sends a pointer that does not follow the rules of pointer generation (ANSI- T1.105-1999 section 9.1.5 page 25).

The Pointer process will also generate the LOP-P signal as follows:

Either the logic received 8 consecutive frames with a pointer different than a valid pointer (active pointer) and none of the received pointer triggered:

- 1. Positive stuff
- 2. Negative stuff
- 3. NDF pointer change
- 4. AIS-P

or the logic received 8 consecutive frames with NDF set 1001.

The B2 octets (192 bytes) are extracted from the incoming WIS frame. The B2 octets are stored and compared with the calculated B2 octets of the previous frame. The B2 check performs the B2 octet calculation of the incoming WIS frame and also performs the comparison between the calculated B2 octets and the received B2 octets extracted from the incoming frame. The function of each B2 octet is a bit-interleaved parity 8 code using even parity. Each of the 192 B2 bytes represents the BIP parity of each of the 192 STS-1 in the previous frame, with Section Overhead excluded.

The B2 check also implements a counter to convey the count of errors detected by the Line B2 bytes. The count has 256 legal values (0 to 255). If greater than 255 errors are detected, a value of 255 is set. The counter is passed to TX for the purpose of generating the M1 octet. The WIS receiver monitors M1 to count the number of remote B2 errors. The near-end 32-bit counter value is stored in Registers 2.57 & 2.58 and the far-end 32-bit counter value is stored in 2.55 & 2.56.

7.2.8 Path Overhead Extraction and B3 Check

Path Overhead extraction extracts the J1, B3, C2 and G1 octets and also removes the Path Overhead and Fixed Stuff from the WIS stream which does not include the Section Overhead and Line Overhead.

The J1 octet in the received WIS frames are interpreted as transporting a 16-octet continuously repeating Trace Message. 64-octet Trace Messaging can be enabled. This Trace Message is extracted from the incoming WIS frame stream and passed to the Station Management entity (MDIO block) via dedicated registers within the WIS Layer Management register space (J1 RX registers). The WIS Receive process does not delineate Trace Message boundaries or process them in any way. Extraction of valid Trace Message data begins after the WIS Receive process has successfully synchronized to the incoming WIS frame stream. Each successive J1 octet received thereafter is placed in a successive octet of the WIS J1 RX register set, until all J1 octets have been received, after which the process repeats from the first octet of the register set. As the incoming Trace Message is 16 octets in size, the contents of the WIS J1 RX register set will remain static as long as the same message is being received. Extraction of Trace Message in this fashion is performed continuously as long as valid WIS frames are being received.

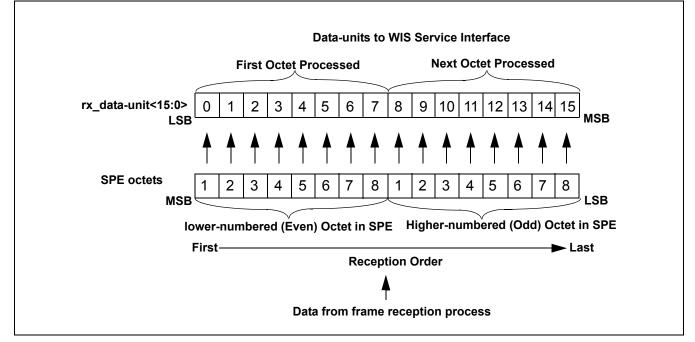
The PLM-P (Path Loss of Label Mismatch) is generated from the C2 octet which is extracted from the incoming frame. The PLM-P is asserted when the received STS Path Label (C2 octet of the STS Path Overhead) does not equal that assigned to 10G Ethernet (00011010) in five consecutive frames. The PLM-P signal is passed to the Station Management entity (MDIO block) and the WIS transmit block. The G1 octet (Path Status) is passed to the Station Management entity (MDIO block).

The B3 octet is stored and compared with the calculated B3 octet of the previous frame. The B3 octet is calculated for the incoming WIS frame and the comparison is performed between the calculated B3 octet and the received B3 octet extracted from the incoming frame. The function of B3 octet is a bit-interleaved parity 8 code using even parity. The B3 octet is calculated from the incoming frame which excludes Section Overhead and Line Overhead.

A 4-bit counter is implemented, which conveys the count of interleaved bit blocks that have been detected in error by the Path BIP-8 code (B3). This count has nine legal values, namely 0 to 8 errors. The counter is passed to the TX WIS for composing the G1 octet. The WIS receiver monitors G1 to count the number of remote B3 errors. The near-end 16-bit counter value is stored in 2.59 and the far-end 16-bit counter value is stored in 2.37.

7.2.9 Receive Payload Mapping





The Receive payload mapping maps the octets in the SPE payload capacity to a continuous stream of data-units that are supplied to the PCS via the rx_data-unit<15:0> parameter of the WIS_UNITDATA.indicate primitive of the WIS Service Interface. Within each data-unit, rx_data-unit<7:0> is mapped to a lower-numbered (even) octet in the SPE capacity, and rx_data-unit<15:8> is mapped to the next high-numbered (odd) octet.

A bit relabelling function is performed to map the bit numbering and ordering conventions followed by the Receive process (which follows the bit numbering and ordering conventions of SONET/SDH to those required by the WIS Service Interface. The relabelling function is performed as shown in Figure 13. Bit 1 of the lower-numbered (even) octet within the received SONET SPE is renumbered as bit 0 of rx_data-unit<15:0> at the WIS Service Interface, bit 8 of the high-numbered octet within the SONET SPE is renumbered as bit 15 of rx_data-unit<15:0>, and the rest of the bits are renumbered in corresponding sequence.

7.2.10 Test Pattern Checker

The QT2032 provides WIS compliant test pattern checking features. Please refer to Section 11.5, "WIS Test Features (QT2032 only)," on page 102 for details.

7.3 Extended WIS Features

The QT2032 integrates a series of features common for SONET framer that are not supported by the WIS Clause.



7.3.1 SS Bits (H1)

The SS bits in the STS-1 #1 transmit overhead can be programmed by the user. The SS bits are located in bits 5 and 6 of the H1 octet in the SONET overhead. This feature allows the QT2032 transmitted frame to be compatible with SDH networks, where the SS bits are typically set to '10'. For SONET networks, the default value of '00' should be used. To change the SS bit value, enter the required value in MDIO register field 2.C001h.7:6. To enable insertion of the new SS bits, set 2.C002h.9 to '1'.

In the 191 subsequent STS-1 fields of the transmit overhead, the SS bits are set to '00'.

The QT2032's WIS receive processor ignores the SS bits in the STS-1 #1 overhead field. For STS-1 #2-192, a value of '00' is expected.

7.3.2 APS Channel (K1 and K2)

The APS bytes are located in the first STS-1 of the STS-192 only and are used for automatic protection switching signaling.

A new value in either byte is only validated after it has been received in 3 consecutive frames. Upon validation of a new K1 or K2 byte, the respective K byte is stored in a status register and an interrupt is generated (the interrupt can be masked). The validation of the K bytes is not affected by any alarm or defect.

If 3 identical consecutive K bytes are not found in 12 frames, an inconsistent K byte interrupt is generated (the interrupt can be masked).

A programmable value for K1 and K2 can be transmitted by QT2032 if the feature is enabled (vendor specific register 2.C002h). For the K2 byte only the 5 MSB bits can be programmed. The 3 LSB bits are reserved for RDI-L alarm transmission. ¹

7.3.3 Synchronization Status (S1)

The synchronization status byte is located in the first STS-1 of the STS-192 only, and is used to convey the synchronization status of the network element.

A new value is only validated after it has been received in 8 consecutive frames. Upon validation of a new S1 byte, the S1 byte is stored in a status register and an interrupt is generated (the interrupt can be masked).

A programmable value for S1 can be transmitted by QT2032 if the feature is enabled (vendor specific register 2.C002h).

7.3.4 Line BIP-8 Signal Fail (SF)

QT2032 generates a Signal Failure (SF) alarm if the number of Line BIP-8 (B2) errors monitored during a programmable timing window (2.C410h) exceeds a programmable threshold (2.C411h). There is a second programmable threshold (2.C412h) which is used to provide hysteresis when removing the SF alarm. The user must specify the correct thresholds and timing window to achieve the desired BER monitoring. SF coding violations over the timing window are reported in 2.C413h, a 16 bit non-rollover counter.

At the end of each timing window, a time-out alarm is generated to notify the user that the timing window has ended. The number of coding violations is latched to 2.C413h at the end of each window. The time-out alarm can be programmed to trip the LASI interrupt by enabling the 'SF Timing Window Expired Flag' in the WIS Extended Alarm register (MDIO register bit 2.C502h.11). The LASI interrupt can then be used by system firmware to trigger periodic polling of the chip in order to monitor the SF error rate.

SF monitoring is enabled by setting MDIO register bit 2.C002h.8 to 1.

^{1.} In SONET, bit 8 is the LSB and bit 1 is the MSB.

7.3.5 Line BIP-8 Signal Degrade (SD)

QT2032 generates a Signal Degrade (SD) alarm if the number of Line BIP-8 (B2) errors monitored during a programmable timing window (2.C400h) exceeds a programmable threshold (2.C401h). There is a second programmable threshold (2.C402h) which is used to provide hysteresis when removing the SD alarm. The user must specify the correct thresholds and timing window to achieve the desired BER monitoring. SD coding violations over the timing window are reported in 2.C403h, a 16 bit non-rollover counter.

At the end of each timing window, a time-out alarm is generated to notify the user that the timing window has ended. The number of coding violations is latched to 2.C403h at the end of each window. The time-out alarm can be programmed to trip the LASI interrupt by enabling the 'SD Timing Window Expired Flag' in the WIS Extended Alarm register (MDIO register bit 2.C502h.9). The LASI interrupt can then be used by system firmware to trigger periodic polling of the chip in order to monitor the SD error rate.

SF monitoring is enabled by setting MDIO register bit 2.C002h.7 to 1.

7.3.6 Pointer Justification Event Counters

QT2032 implements an 8 bit counter incremented by one on every Positive Stuff event. This counter does not rollover and is cleared to 0 on read. The Positive Stuff event counter is located in the lower 8 bits of MDIO register 2.C020h.

Likewise, the QT2032 implements an 8 bit counter incremented by one on every Negative Stuff event. This counter does not rollover and is cleared to 0 on read. The negative Stuff event counter is located in the upper 8 bits of MDIO register 2.C020h.

7.3.7 Extended J1 Trace Messaging (64 bytes)

The QT2032 supports both 16 and 64 byte J1 trace messaging. The IEEE 802.3 compliant 16 byte J1 trace messaging is the default mode of operation. To use 64 byte J1 trace messaging, the user must enable this mode by writing to register 2.C002h: the WIS TX will then transmit the J1 bytes located in registers 2.C200h to 2.C217h and the WIS RX will store the received J1 bytes in registers 2.C100h to 2.C117h.

7.3.8 Transport Overhead Serial Interface

This feature allows Transport Overhead byte insertion in the WIS TX SONET frame and Transport Overhead byte extraction from the WIS RX SONET frame. This gives the user extra flexibility to use and process SONET overhead bytes that are not supported by the IEEE 802.3 Standard (Clause 50). This provides access to the Data Communication Channel (DCC). This feature supports 4 modes of operation on both RX and TX:

- insert/extract all STS-1 Transport Overhead Bytes (27 bytes per frame, corresponding to Section and Line overhead).
- insert/extract the D1 to D3 Bytes (3 bytes per frame).
- insert/extract the D4 to D12 Bytes (9 bytes per frame).
- insert/extract the D1 to D12 Bytes (12 bytes per frame).

The mode is controlled for both the Tx and Rx paths by MDIO register 2.C010h. The interface is enabled using register bits 2.C002h.3:2.

QT2032 has a 2 wire interface on the transmit path for byte insertion: an output clock pin (TDCC_CLK) that runs at 155MHz / 80 and an input data pin (TDCC) is used to sample the incoming data (serial OH bytes). QT2032 will sample the data at the falling edge of the clock (the external chip connected to the serial interface needs to drive a new data value after the rising edge of the clock). Note: B1/B2 byte insertion operations are achieved using an inversion mask, which will bitwise invert the calculated B1/B2 octets and is useful for debug purposes only. An inserted value of all zeroes preserves the calculated B1/B2 values.

Similarly, QT2032 has a 2 wire interface on the receive path for byte extraction: an output clock pin (RDCC_CLK) that runs at 155MHz / 80 and an output data pin (RDCC) is used to shift out the data (serial OH bytes). QT2032 will drive a new data value on the falling edge of the clock (the chip connected to the serial interface can safely latch



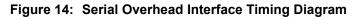
the data on the rising edge of the pin).

In "All STS-1 mode", QT2032 will kill/gate the clock for 27 clock cycles before driving the clock for 216 (3x9x8) clock cycles. The gap in the clock can be used for synchronization purposes. Also, the B1/B2 octets are:

In "D1-D3 mode", QT2032 will kill/gate the clock for 219 clock cycles before driving the clock for 24 (3X8) clock cycles. The gap in the clock can be used for synchronization purposes.

In "D4-D12 mode", QT2032 will kill/gate the clock for 171 clock cycles before driving the clock for 72 (9X8) clock cycles. The gap in the clock can be used for synchronization purposes.

In "D1-D12 mode", QT2032 will kill/gate the clock for a minimum of 90 clock cycles, then drive the clock for 24 (3X8) clock cycles (D1-D3), then kill/gate the clock for a minimum of 48 clock cycles, then finally drive the clock for 72 (9x8) clock cycles (D4-D12). The gaps in the clock can be used for synchronization purposes.



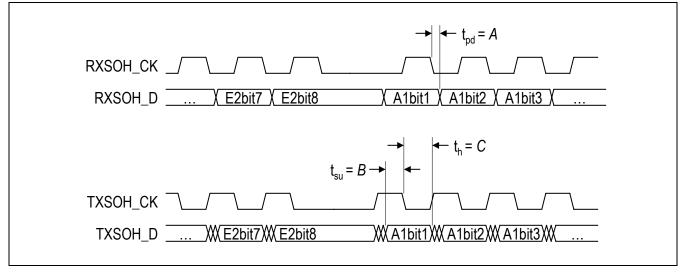


Table 13: Serial Overhead Interface Timing Parameters

Parameter	Value	Comment
Period	0.516µsec	243 clock cycles per frame
Framing Gap		27 clock cycles per frame in "All STS-1 mode"
Frequency	1.9375MHz	
A	0.1µsec	
В	0.1µsec	
С	0.1µsec	

7.3.9 Programmable Overhead Byte Insertion

This feature allows the insertion of 3 bytes in the WIS TX SONET frame. The insertion is limited to the transport / path overhead, fixed stuff and the first data of the payload until column 127. The location and number of frames is determined through 3 programmable registers, located at MDIO registers 2.C601h - 2.C603h.

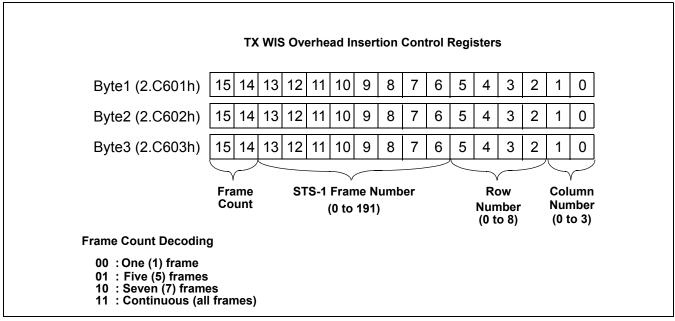
The programmable control register format is shown in Figure 15. For each byte, one register is used to control insertion the insertion mode. Two modes of insertion are available, as specified by bits 15:14 of the control register. If continuous insertion is selected ('11'), insertion will commence at the start of the next frame.

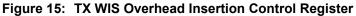
If a fixed number of frames is selected ('00', '01' or '10'), byte insertion is initiated by a control bit located in register bit 2.C600h.0. Once triggered, insertion will commence at the start of the next frame and will continue for the spec-

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ified number of frames. The control bit initiates byte insertion for all 3 bytes simultaneously. It will only trigger byte insertion if a fixed number of frames is selected. To initiate insertion multiple times, toggle the control bit.

The byte values to be inserted are stored in 3 separate registers, in the lower 8 bits of MDIO registers 2.C604h - 2.C606h.





To initiate insertion, first set the programmable registers then set the Control enable signals. The insertion will happen on the next frame. The priority of the insertion goes from Register 1 to 3.

If the registers are set for B1, B2, B3 locations the byte will be treated as a mask to corrupt specific bits in the Parity bytes.

Byte Insert Priority

The overhead byte insertion is prioritized, with Byte1 receiving the highest priority and Byte3 the lowest. This means that, in the event of a conflict in the byte insert settings the instructions for Byte1 will be executed preferentially, followed by Byte2 and then Byte3. A conflict arises when two different Bytes are programmed to overwrite the same overhead byte field.

This behavior can be used for testing purposes to generate more complex OH byte insert sequences. For example, Byte1, Byte2 and Byte3 can be programmed to insert different values to the same overhead byte. By selecting a finite Frame Count for Byte1 and Byte2, the WIS block will first execute the instructions for Byte1 for the programmed number of frames, followed immediately by Byte2 on the next frame and finally Byte3. In this example, Byte3 may be programmed to insert for either a finite or continuous Frame Count. If a continuous Frame Count is selected for Byte1 or Byte2, the WIS block will never execute the instructions for the subsequent Bytes.





Internal Limitations

The STS-1 overhead bytes are organized internally into groups of 8 bytes each. The STS-1 groups are [1..8], [9..16], [17..24] - [185..192]. For a given overhead byte within an STS-1, only one byte may be overwritten within a given group. For example, the A1 byte of STS-1 #1 and the A1 byte of STS-1 #2 cannot both be overwritten simultaneously. However, the A1 byte of STS-1 #1 and the A1 byte of STS-1 #9 *can* be overwritten simultaneously.

This rule does not affect bytes at different locations within the STS-1 (e.g. the A1 and K2 bytes of STS-1 #1 can be overwritten simultaneously).

7.3.10 Programmable Overhead Byte Extraction

This feature allows the extraction of 3 bytes in the WIS RX SONET frame. The extraction is limited to the transport overhead and path overhead bytes only. The location and number of frames is determined through 3 programmable registers, located at MDIO registers 2.C611h - 2.C613h. Three separate control bits are used to initiate extraction of each byte, located in register bits 2.C610h.2:0. After the bytes are extracted, their values are stored in 3 separate registers, using the lower 8 bits of MDIO registers 2.C614h - 2.C616h.

7.4 WIS Alarm Processing

The WIS block detects defects on the fiber input and processes them. The defects are summarized in Table 14 below.

Table 14: Summary of Defects Processed by WIS	
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Defect/Anomaly	Root Cause	Reported in	Actions	To PCS? ¹
LOS (Loss of Signal)	no optical signal failed optics	2.21h.6	RDI-L ² , RDI-P ³ Defects raised in Tx OH	no
LOF (Loss of Frame)	see LOS faults	2.21h.7	RDI-L, RDI-P ³ Defects raised in Tx OH	YES
Loss of WIS Synchronization	see LOS faults	1.9003h.9 linked to 2.1.7	RDI-L, RDI-P ³ Defects raised in Tx OH All WIS processes suspended	YES
SEF	degraded optical signal	2.21h.11	No action	no
AIS-L	LOS or LOF in far-end LTE	2.21h.4	RDI-L, RDI-P ³ Defects raised in Tx OH	no
Far End RDI-L	RDI-L defect flag transmitted by far-end LTE	2.21h.5	No action	no
LOP-P	Invalid pointer detected (see Section 7.2.7 on page 43)	2.21h.0	RDI-P ³ Defect raised in Tx OH	YES
AIS-P	LOS or LOF in far-end PTE	2.21h.1	RDI-P ³ Defect raised in Tx OH	YES
PLM-P	Path label does not match expected value (see Section 7.2.8 on page 45)	2.21h.2	RDI-P ⁴ Defect raised in Tx OH	YES
LCD-P	Received wrong type data in payload (not 64/66b encoded)	2.21h.3	RDI-P ⁴ Defect raised in Tx OH	no
Far end RDI-P (AIS-P/LOP-P)	AIS-P or LOP-P defect detected on far-end PTE	2.21h.9	No action.	no
Far end RDI-P (PLM-P/LCD-P)	PLM-P or LCD-P defect detected on far-end PTE	2.21h.10	No action.	no
Path BIP	Corruption over link	2.3Bh	Counter incremented by one on Path BIP errors Error count per frame transmitted in G1 byte of TX OH.	no
Line BIP	Corruption over link	2.39h-2.3Ah	Counter incremented by the number of Line on BIP errors Error count per frame transmitted in M1 byte of TX OH (max = 255).	no
Section BIP	Corruption over link	2.3Ch	Counter incremented by the number of Section on BIP errors	no

1. When a defect propagates to the PCS, local faults will be generated on the XAUI output to the upstream MAC.

2. RDI-L = [(LOS or LOF or AIS-L) and not(Reg 3.C010.8)] or [not(WIS Sync) and not(Reg 3.C010.9)]

3. RDI-\P (AIS-P/LOP-P) = [AIS-P and not (Reg 3.C010.6)] OR [LOP-P and not(Reg 3.C010.7)] OR [RDI-L and not (Reg 3.C010.10)]

4. RDI-P (LCD-P/PLM-P) = [PLM-P and not (Reg 3.C010.4)] OR [LCD-P and not(Reg 3.C010.5)]



7.4.1 Local Fault Generation

applied

Certain errors on the fiber input prevent delineation of valid data from the incoming WIS frame. These errors include: Loss of WIS Synchronization, LOF, LOP-P, AIS-P and PLM-P. When any of these errors are detected, the WIS receive process is unable to extract the payload. To handle this condition, the alarm is propagated to the PCS. The PCS layer generates a local fault signal embedded in an idle stream to notify the upstream MAC.

The error propagates immediately upon detection. The error propagation terminates within 125μ s of removal of all error conditions.

Mask bits are available to prevent each of the 4 alarms from propagating to the PCS. These are located in MDIO register bits 3.C010h.3:0. The errors will propagate by default.

7.4.2 WIS Alarm Masking

Mask bits are available to prevent alarms detected during reception from generating the expected alarm signal in the Transmit WIS OH. Mask bits for the following alarms are available: AIS-L/LOS/LOF, LOP-P, AIS-P, LCD-P, PLM-P, WIS Sync and RDI-L. The mask bits are located in MDIO register bits 3.C010h.10:4. The alarms are unmasked by default.



8 Control and Status Pins Detailed Description

8.1 General Notes

8.1.1 IO Polarity

The user can control the polarity of most low speed CMOS pins (MDIO registers 1.D003h, 1.D005h). Changing the polarity of a pin inverts the logic of the pin function.

8.1.2 IO Monitoring Via MDIO

For debugging purposes, the user can read MDIO register 1.D002h to see the state of most low speed CMOS inputs (value after PAD and after inversion if enabled). Exceptions are PRTAD<4:0>, LANMODE, RESETN. The state of most low speed CMOS outputs (value before PAD and before inversion if enabled) can be found in MDIO register 1.D004h. The state of the 3 LED pins can be checked in the LED Configuration Registers. See Section 8.6 on page 70 for details.

8.2 Control (Input) Pins (QT2022 and QT2032)

The pins described in this section are common to both the QT2022 and QT2032. All pins have the same function for both products.

The low speed control input pins are listed in Table 3, "QT2022/32 Ball Assignment & Signal Description," on page 13. The inputs have switching points which are compatible with 1.2V CMOS logic, but can tolerate up to 3.3V logic levels.

8.2.1 Laser Fault Control Pin (TXFAULT)

The TXFAULT fault input is used to indicate that there is a problem with the external laser or laser driver. TXFAULT does not have any effect on TXENABLE.

8.2.2 XFP Mode Control Pin (XFP)

The XFP input pin is used to configure the chip to support system cards interfacing with an XFP module (XFP mode). Several features of the chip are changed or disabled when the XFP pin is high. When the XFP pin is low, the chip follows the default behavior. The default logic should be used for XENPAK / XPAK / X2 module applications. There is an internal pulldown within the XFP input, so this is the default state if left unconnected.

The following features are changed or disabled when in XFP mode:

- TXPLLOUT default frequency changed to baudrate / 64 (161.13 MHz); output turned on by default
- RXLOSB_I input pin reassigned as RX_LOS input for XFP module; logic polarity is inverted
- TXON input pin redefined as an output to drive MOD_DESEL of XFP module
- EEPROM_PROT input pin reassigned to input Mod_ABS from XFP module
- TXFAULT input pin reassigned as Mod_NR from XFP module
- LASI_INTB input pin reassigned as interrupt from XFP module
- TXENABLE output pin reassigned to drive TX_DIS input of XFP module; logic polarity is inverted
- LOSOUTB output pin reassigned to drive P_DOWN/RST input of XFP module
- TRST_N pin no longer used as connection point for external powerup reset cap.



The following functions which are specifically for XENPAK EEPROMs are disabled in XFP mode:

- EEPROM checksum
- DOM capability
- EEPROM_PROT protect capability
- PMA/PMD type control through EEPROM
- *tx_flag* and *rx_flag* for generating LASI ALARM
- PMA/PMD Identifier (OUI)

Also see pin description in Table 3 on page 13.

8.2.3 Reset Control Pin (RESETN)

When the RESETN pin goes low it resets all the QT2022/32 registers to their default values. On power up, the RESETN pin must be held low until the power supplies have reach their nominal values. While RESETN is low, all high speed signal outputs are shut off. Once the RESETN pin goes high, the outputs will turn on (as appropriate).

Setting any of the MDIO reset registers 1.0.15, 3.0.15 and 4.0.15 to 1 will cause a soft reset. A soft reset will also reset all registers to their default values. During a soft reset, the high speed signals are not shut off. The soft reset is self-clearing. The reset event will occur sufficiently fast (within a few us) that no pause is required between MDIO commands to accommodate the reset.

8.2.4 Receive LOS Control Pin (RXLOSB_I)

The RXLOSB_I input goes low to indicate a loss of optical receive signal. Driving RXLOSB_I low sets the PMA Receive Local Fault bit in MDIO register 1.8.10, and causes MDIO register 1.10.0 (PMA Receive Signal Detected) to go low. If Legacy = 1, driving RXLOSB_I low will also trigger PMA Receive Local Fault (1.8.10). Local Fault ordered_sets will be output at RxXAUI when RXLOSB_I = 0.

For performing module diagnostics, the effect of the RXLOSB_I signal on the receive data path can be overridden by setting MDIO register 1.C001h.10 to 1. When this bit is set, RXLOSB_I=0 will not cause the generation of idle patterns at RxXAUI and will not trigger a PMA Receive Local Fault. MDIO register 1.10.0 is always controlled by RXLOSB_I, regardless of the state of MDIO register 1.C001h.10.

The logic of the RXLOSB_I input is automatically reversed using the XFP input pin. This is required when using the QT2022/32 in conjunction with an XFP module to match the logic of the RXLOS output from the XFP module. See Section 8.2.2 for details.

8.2.5 Port Address Control Pins (PRTAD<4:0>)

The PRTAD bits set the port address for MDIO/C transactions. See "Management Frame Format" on page 74. for more information on the MDIO/C interface.

8.2.6 Receive Polarity Control Pin (RXIN_SEL)

RXIN_SEL controls the 10 Gb/s receive path input polarity as defined at the QT2022/32 pins/balls. The default setting, RXIN_SEL=0, is compatible with XENPAK module requirements.

Signal		
RXIN_SEL=0	RXIN_SEL=1	
RXINP	RXINN	
RXINN	RXINP	

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8.2.7 Transmit Polarity Control Pin (TXOUT_SEL)

TXOUT_SEL controls the 10 Gb/s transmit data output polarity as defined at the QT2022/32 pins/balls. The default setting, TXOUT_SEL=0, is compatible with XENPAK module requirements.

Table 16: TXOUT Polarity

Signal		
TXOUT_SEL=0	TXOUT_SEL=1	
ТХОИТР	TXOUTN	
TXOUTN	TXOUTP	

8.2.8 Low Power Mode Control Pin (TXON)

TXON is the low power mode control pin. When TXON=1 the QT2022/32 will be in normal operating mode. When TXON=0, only the MDIO, EEPROM and DOM functions will be active. An external reference clock must be applied at EREFCLKP/N for these functions to be active.

8.2.9 XAUI Input Lane Ordering Control Pin (TxXAUI_SEL)

TxXAUI_SEL controls the transmit path XAUI lane ordering as defined at the QT2022/32 pins/balls. The default setting, TxXAUI_SEL=0, is compatible with XENPAK module requirements

When the QT2022/32 is in scan mode, the TxXAUI_SEL pin functions as a scan enable pin. If the input is high, scans are enabled.

Table 17: TxXAUI Lane Ordering

Signal		
TxXAUI_SEL=0	TxXAUI_SEL=1	
TxXAUI3P	TxXAUI0P	
TxXAUI3N	TxXAUI0N	
TxXAUI2P	TxXAUI1P	
TxXAUI2N	TxXAUI1N	
TxXAUI1P	TxXAUI2P	
TxXAUI1N	TxXAUI2N	
TxXAUI0P	ТхХАШЗР	
TxXAUI0N	TxXAUI3N	



8.2.10 XAUI Output Lane Ordering Control Pin (RxXAUI_SEL)

RxXAUI_SEL controls the transmit path XAUI lane ordering as defined at the QT2022/32 pins/balls. The default setting, RxXAUI_SEL=0, is compatible with XENPAK module requirements.

Table 18: RxXAUI Lane Ordering

Signal		
RxXAUI_SEL=0	RxXAUI_SEL=1	
RxXAUI3P	RxXAUI0P	
RxXAUI3N	RxXAUI0N	
RxXAUI2P	RxXAUI1P	
RxXAUI2N	RxXAUI1N	
RxXAUI1P	RxXAUI2P	
RxXAUI1N	RxXAUI2N	
RxXAUI0P	RxXAUI3P	
RxXAUI0N	RxXAUI3N	

8.2.11 EEPROM Write Protect Control Pin (EEPROM_PROT)

When XFP=0, this pin is used to provide write protection for the EEPROM memory space. When the EEPROM_PROT pin is low, full MDIO write access to MDIO registers 1.8007 - 1.8106h is allowed. When EEPROM_PROT is high it blocks MDIO writes to the registers corresponding to EEPROM registers 0 to *PL* and *PU* to 255 inclusive thereby preventing changes to these EEPROM registers. When EEPROM_PROT is high, it also blocks MDIO writes to the DOM register space from 1.9000 - 1.90FFh. I2C write access is also blocked (see Section 10.8 on page 93). For more information on the function of EEPROM_PROT, see Section 10 on page 79.

When XFP=1, the EEPROM_PROT definition is reassigned to indicate the absence of an XFP module. A high level indicates the XFP module is absent. When used in an XFP application, this pin should be connected to the XFP module 'Mod_ABS' pin.

The state of the EEPROM_PROT input can be read in Register 1.D002h.

8.2.12 LASI Interrupt Control Pin (LASI_INTB)

The LASI_INTB pin is an interrupt pin for raising a LASI alarm from an external device. This provides a method for an external device to rapidly trigger the LASI interrupt, such as a DOM. A logical low on this input is a fault condition.

The LASI_INTB alarm is mapped to the LASI alarm register bit 1.9005h.3. When the LASI_INTB input is asserted low (alarm condition), Register bit 1.9005h.3 is set to 1. This will cause the LASI output to be asserted.

When XFP=1, LASI_INTB is reassigned to the XFP module interrupt input pin. When used in an XFP application, this pin should be connected to the XFP module interrupt pin. The alarm behavior is the same in this mode as when XFP=0. That is, when the LASI_INTB input is asserted low (alarm condition), Register bit 1.9005h.3 is set to 1, causing the LASI output to be asserted.

8.2.13 Backwards Compatibility Control Pin (LEGACY)

The LEGACY pin is used to revert several key register map definitions to be compatible with the AMCC QT2021 SerDes. When the LEGACY pin is low, the new QT2022/32 register map definitions are used. When high, the QT2021 definitions are used.

Table 8 lists the register map definition differences affected by the LEGACY pin. Table lists all changes to chip function affected by the LEGACY pin. The state of the LEGACY pin is shown in MDIO register bit 1.D002h.15.

ltem	Register	Register Definition LEGACY = 0	Register Definition LEGACY = 1
1	1.9001h.6	TXFAULT Enable 0 = disabled (default) 1 = enabled	TXFAULT Enable 0 = disabled 1 = enabled (default)
2	1.9001h.7	Laser Output Power Fault Enable 0 = disabled 1 = enabled (default)	Reserved, RO
3	1.9001h.8	Laser Temp Fault Enable 0 = disabled 1 = enabled (default)	Reserved, RO
4	1.9001h.9	Laser Bias Current Fault Enable 0 = disabled 1 = enabled (default)	Reserved, RO
5	1.9003h.4	PMA Receive Local Fault, RO/LH Defined as: NOT(Receive PLL Lock)	PMA Receive Local Fault, RO/LH Defined as: NOT(Receive PLL Lock) or RXLOSB_I==0
6	1.9003h.5	Receive Optical Power Fault, RO linked to DOM alarm 1.A071h.7:6	Reserved, RO
7	1.9004h.0	PHY_XS Transmit Local Fault, RO/LH Defined as: NOT(TxXAUI Lane Align)	PHY_XS Transmit Local Fault, RO/LH Defined as: NOT(TxXAUI CDR lock<3:0>)
8	1.9004h.3	PCS Transmit Local Fault, RO/LH Defined as: Transmit FIFO overflow/underflow error	PCS Transmit Local Fault, RO/LH Defined as: NOT(TxXAUI Lane Sync) or NOT (TxXAUI Lane Align)
9	1.9004h.4	PMA Transmit Local Fault, RO/LH Defined as: Transmit PLL not locked	PMA Transmit Local Fault, RO/LH Defined as: (Transmit PLL not locked) OR (TXFAULT)
10	1.9004h.7	Laser Output Power Fault, RO linked to DOM alarm 1.A070h.1:0	Reserved, RO
11	1.9004h.8	Laser Temp Fault Enable, RO linked to DOM alarm 1.A070h.7:6	Reserved, RO
12	1.9004h.9	Laser Bias Current Fault, RO linked to DOM alarm 1.A070h.3:2	Reserved, RO

 Table 19:
 LEGACY Pin Register Map Definition Changes



Table 20: LEGACY Pin Changes to Chip Functions

lte	em	Function	Definition LEGACY = 1	Definition LEGACY = 0
1	E	x Jitter Test Pattern Enabled by setting Register 2.2A=000Eh	Output pattern is a square wave with 8 ones and 8 zeros (00FFh)	Output pattern is a square wave with 4 ones and 4 zeros (0F0Fh)

8.2.14 Receive Equalizer Enable Control Pin (EQ_EN)

The EQ_EN pin is used to enable the fiber receive equalizer. When the pin is high, the equalizer is enabled. When it is low, the equalizer state depends on the state of the XFP pin and the 'override_xfp_eqn' bit.

The control logic for the receive equalizer is shown in Table 21.

Table 21: Receive Equalizer Truth Table

EQ_EN Pin State	XFP Pin State	ʻoverride_xfp_eqn' bit 1.C030h.6	Equalizer State 1 = enabled; 0 = disabled
0	0	0	0
0	0	1	1
0	1	0	1
0	1	1	0
1	x	x	1

8.3 Control (Input) Pins (QT2032 only)

The pins described in this section apply to the QT2032 only. These pins are unused for the QT2022 product. Please see Table 3 for required connectivity information.

8.3.1 LAN Mode Control Pin (LANMODE)

The LANMODE Control Pin is used to force the QT2032 into LAN mode. This pin is used in conjunction with the MDIO "Port Type Selection" bit (address 2.7.0). When LANMODE is low, the mode is determined by the "Port Type Selection" bit. When LANMODE is high, the mode is forced to LAN mode regardless of the state of the WIS Select bit. The logic is summarized in Table 5.

When the LANMODE pin is high, access to the WIS register space (device 2) is disabled. MDIO writes to this space will have no effect and MDIO reads to this space will return all 0's.

The LANMODE pin is not defined for the QT2022.

Table 22: Application Mode Based on LANMODE Control Pin and WIS Select Bit

LANMODE Control Pin	"Port Type Selection" bit MDIO 2.7.0	Mode
0	0	LAN
0	1	WAN
1	x	LAN

8.3.2 SONET Clock Rate Control Pin (REFSEL622)

The QT2032 can accept a 155.52MHz or 622.08MHz reference clock on the SREFCLK input. This control pin is used to select the SONET input clock rate expected by the chip. When REFSEL622 is low, the chip expects a 155.52MHz clock. When it is high, the chip expects a 622.08MHz clock. The input uses 1.2V logic but is compatible with 3.3V logic.

The input has an 50k Ω internal pulldown, so the default expected clock rate is 155.52MHz if the input is not connected.

8.3.3 VCXO Clock Rate Control Pin (VCXOSEL622)

The QT2032 can accept a 155.52MHz or 622.08MHz reference clock on the VCXO input. This control pin is used to select the clock rate expected by the chip. When VXCOSEL622 is low, the chip expects a 155.52MHz clock. When it is high, the chip expects a 622.08MHz clock. The input uses 1.2V logic but is compatible with 3.3V logic.

The input has an 50k Ω internal pulldown, so the default expected clock rate is 155.52MHz if the input is not connected.

8.3.4 VCXOB Control Pin

The QT2032 provides support for a VCXO-based PLL to filter phase noise on the SREFCLK or fiber RX recovered clock to ensure compliant jitter generation and jitter transfer performance on the TX Fiber Output. The VCXOB pin is used to control the VCXO PLL.

When the VCXOB pin is high, the external VCXO PLL will not be used and the input signals on the VCXOIP/N pins will be ignored. When VXCOB is low, the external VCXO PLL is enabled and the input signals on the VCXOIP/N will be used to time the TX PLL.

The input has an $50k\Omega$ internal pullup, so the default configuration of the VCXOB pin is to disable the VXCO PLL if the pin is not connected.

8.3.5 VXCOONLY Control Pin

In a linetiming application where an external VXCO PLL has been implemented, the VXCOONLY control pin is pulled high to indicate that no clock has been provided at the SREFCLK input. When VXCOONLY is pulled low, the clock recovery circuitry will expect a valid SREFCLK. When a valid RX recovered clock is present (indicated by the LTIMEOK pin), the VXCO PLL will function normally.

When operating in VCXOONLY mode (VXCOONLY=1), set REFSEL622 = VCXOSEL622 for proper operation.

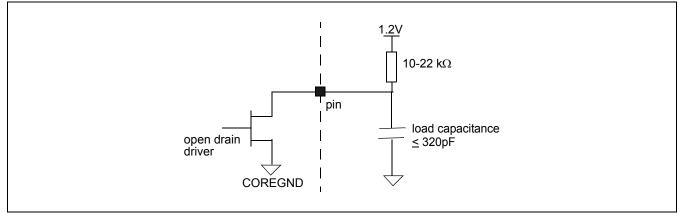


8.4 Low-Speed Output Pins (QT2022 and QT2032)

The pins described in this section are common to both the QT2022 and QT2032. All pins have the same function for both products.

All the low-speed output pins have the same type of open drain driver. An external $10-22 k\Omega$ pullup resistor to 1.2V is expected. The open drain configuration allows these signals to be wire ORed with other active low open drain disable signals on the module. There are no internal pullups or pulldowns on these pins.

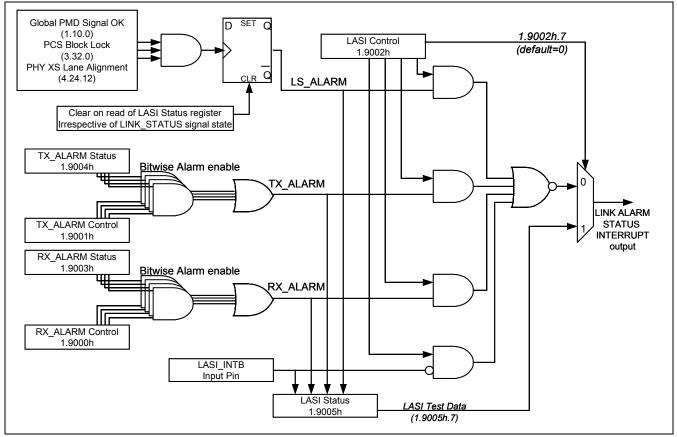
Figure 16: Open Drain Driver Configuration



8.4.1 Link Alarm Status Interrupt Pin (LASI)

The LASI pin is an active-low output used to indicate that a link fault condition has been detected in either the receive or transmit path. It can be used as an interrupt to a microcontroller. The block diagram for LASI is shown in Figure 17. Control registers are provided so LASI can be programmed to assert only for specific fault conditions.





LASI = {OR of (reg 1.9005h.n 'bit wise AND' reg 1.9002h.n) for n=0..15}, where register 1.9005h contains the alarm states, and register 1.9002h contains the enable bits for each alarm.

Register bit 1.9005h.7 is a writable 'LASI test data' register bit which can be used to test the LASI pin connectivity. It is enabled by setting register bit 1.9002h.7 1.9002h.3 to 1. When enabled, the LASI output state will be determined by the "LASI test data" value.

Table 23:	LASI Control	Registers
-----------	--------------	-----------

	MDIO Status	s Register	MDIO Enable	e Register
Description	16b hex	type	16b hex	default value
LS_ALARM	1.9005.0	RO/LH	1.9002.0	0
TX_ALARM	1.9005.1	RO	1.9002.1	0
RX_ALARM	1.9005.2	RO	1.9002.2	0



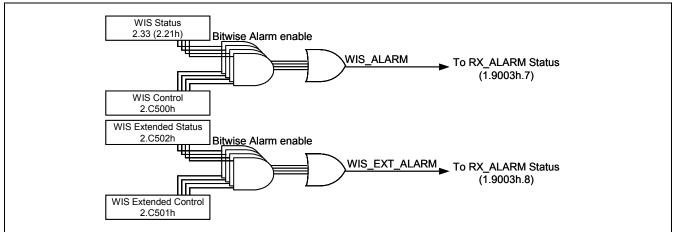
	MDIO Status Register		MDIO Enable Register		
Description	16b hex	type	16b hex	default value	
LASI_INTB interrupt	1.9005.3	RO	1.9002.3	0	
unused	1.9005.4	RO	1.9002.4	0	
unused	1.9005.5	RO	1.9002.5	0	
unused	1.9005.6	RO	1.9002.6	0	
LASI test data	1.9005.7	R/W	1.9002.7	0	
unused	1.9005.f:8	RO	1.9002.f:8	0	

The LS_ALARM signal is latched high each time any of the following signals changes state:

- PMD signal detect (MDIO 1.10.0)
- PCS block_lock (MDIO 3.32.0)
- PHY_XS lane alignment (MDIO 4.24.12)

When operating the QT2032 in WAN mode, additional WIS alarms can be programmed to assert LASI. These alarms are used to report a WIS-related link fault on the receive path. The block diagram for the WIS alarms is shown in Figure 18. The alarms feed into the RX_ALARM Status register shown in Figure 17.

Figure 18: Block diagram of WIS Alarms



RX_ALARM

RX_ALARM is used to indicate that a fault has occurred on the receive path. RX_ALARM is the bitwise OR of thereceive path status register bits in register 1.9003h. RX_ALARM can be programmed to assert only when specific receive path fault conditions are present. The programming is performed by writing to a mask register at address 1.9000h. The contents of register 1.9003h is AND'ed with register 1.9000h prior to application of the OR function to generate the RX_ALARM signal.

RX_ALARM = {OR of (reg 1.9003.n 'bit wise AND' reg 1.9000.n) for n=0..9})

	Definition		Definition (RO)		MDIO Enable Register (R/ W)		
Description	LEGACY=0	LEGACY=1	16b hex	type	16b hex	default value	
PHY_XS Receive Local Fault (MDIO 4.8.10 = 1.0008.a h)	NOT (XAUI PLL loci	ked)	1.9003.0	RO/LH	1.9000.0	1	
rx_flag	bitwise OR of rx_flag	g register, 1.9007h	1.9003.1	RO/LH	1.9000.1	0	
PCS Receive Code Violation	invalid 66b code wo	rd detected	1.9003.2	RO/LH	1.9000.2	0	
PCS Receive Local Fault	NOT(block_lock) (linked to 3.8.10)		1.9003.3	RO/LH	1.9000.3	1	
PMA Receive Local Fault	<i>NOT(Receive PLL Lock)</i> (linked to 1.8.10)	NOT(Receive PLL Lock) or RXLOSB_I==0 (linked to 1.8.10)	1.9003.4	RO/LH	1.9000.4	1	
Receive Optical Power Fault ¹	1.A071h.7 OR 1.A071h.6	Reserved, RO	1.9003.5	RO	1.9000.5	1, LEGACY=0 0, LEGACY=1	
PHY_XS Receive Rate Error	Receive FIFO overfi (4.C002h.7 OR 4.C0		1.9003.6	RO/LH	1.9000.6	0	
WIS Alarm Interrupt Flag ²		bitwise OR of WIS ALARM INTERRUPT register, 2.33 (2.21h)		RO	1.9000.7	0	
WIS Extended Alarm Interrupt Flag ²	bitwise OR of WIS EXTENDED ALARM INTERRUPT register, 2.C502h		1.9003.8	RO	1.9000.8	0	
WIS Local Fault ²	NOT(SONET frame sync) (linked to 2.1.7)		1.9003.9	RO/LH	1.9000.9	0	
Reserved, set to 0			1.9003.f:a	RO	1.9000.f:a	0	

Table 24: Receive Alarm Registers (RX_ALARM)

1. undefined if LEGACY = 1.

2. Valid in QT2032 WAN mode only. In QT2022, these alarms are Reserved, RO (including QT2032 in LAN mode).



rx_flag

rx_flag is used to flag a DOM receive alarm.

rx_flag = {OR of (reg 1.A071.n 'bit wise AND' reg 1.9007.n) for n=0 to 7}

Table 25: rx_flag Alarm Registers

Description	MDIO Status Register (RO,LH)	MDIO Enable Register (R/W)	MDIO Enable Register default value
Receive Optical Power High Alarm	1.A071h.7	1.9007h.7	0
Receive Optical Power Low Alarm	1.A071h.6	1.9007h.6	0
<pre>rx_flag alarm bits 0 through 5 *</pre>	1.A071h.5:0	1.9007h.5:0	0

* rx_alarm bits 0 through 5 are read from the DOM device and mapped to registers 1.A071h.5:0. The function of these bits is not specifically defined in the XENPAK MSA, but they are used in generating the rx_flag signal in order to allow for vendor specific alarms to be defined. These alarms should be disabled via the associated MDIO register bits 1.9007.5:0 when not is use.

TX_ALARM

TX_ALARM is used to indicate that a fault has occurred on the transmit path. TX_ALARM is the bitwise OR of the receive path status register bits in register 1.9004h. TX_ALARM can be programmed to assert only when specific receive path fault conditions are present. The programming is performed by writing to a mask register at address 1.9001h. The contents of register 1.9004h is AND'ed with register 1.9001h prior to application of the OR function to generate the TX_ALARM signal.

tx_alarm = {OR of (reg 1.9004.n 'bit wise AND' reg 1.9001.n) for n=0..10}

Table 26: Transmit Alarm Registers (TX_ALARM)

	Alarm Definition		MDIO Status Register (RO)		MDIO Enable Register (R/W)		
						def	ault
Description	LEGACY=0	LEGACY=1	16b hex	type	16b hex	LEGACY =0	LEGACY 1
PHY_XS transmit local fault	<i>NOT(TxXAUI Lane Align)</i> (linked to 4.8.11)	NOT(TxXAUI CDR lock<3:0>) (linked to 4.8.11)	1.9004.0	RO/LH	1.9001.0	1	
tx_flag	bitwise OR of tx_flag re	bitwise OR of <i>tx_flag</i> register, 1.9006h		RO/LH	1.9001.1	()
PHY_XS transmit rate error	<i>Transmit FIFO overflow/underflow error</i> (4.C002h.9 OR 4.C002h.8)		1.9004.2	RO/LH	1.9001.2	()
PCS transmit local fault (MDIO 3.8.11)	Transmit FIFO overflow/underflowNOT(TxXAUI Lane Sync) or NOT (TxXAUI Lane Align) (linked to 3.8.11)(linked to 3.8.11)(linked to 3.8.11)		1.9004.3	RO/LH	1.9001.3	1	

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	Alarm [Alarm Definition		MDIO Status Register (RO)		MDIO Enable Register (R/W)		
					def	ault		
Description	LEGACY=0	LEGACY=1	16b hex	type	16b hex	LEGACY =0	LEGACY 1	
PMA transmit local fault	Transmit PLL not locked (linked to 1.8.11)	(<i>Transmit PLL not</i> <i>locked</i>) <i>OR</i> (<i>TXFAULT</i>) (linked to 1.8.11)	1.9004.4	RO/LH	1.9001.4		1	
latched version of txlock	NOT(Fiber transmit PL (reflects value in 1.CO		1.9004.5	RO/LH	1.9001.5	0		
latched version of TXFAULT (based on input pin)	TXFAULT		1.9004.6	RO/LH	1.9001.6	0	1	
Laser Output Power Fault ¹	DOM alarm 1.A070h.1:0	Reserved, RO	1.9004.7	RO	1.9001.7	1	n/a	
Laser Temperature Fault ¹	DOM alarm 1.A070h.7:6	Reserved, RO	1.9004.8	RO	1.9001.8	1	n/a	
Laser Bias Current Fault ¹	DOM alarm 1.A070h.3:2	Reserved, RO	1.9004.9	RO	1.9001.9	1	n/a	
PHY_XS code error	<i>TxXAUI invalid 8b/10b</i> (logical OR of <u>4.C006</u>		1.9004.a	RO/LH	1.9001.a	0		
reserved, set to 0			1.9004.f:b	RO	1.9001.f:b	n	/a	

Table 26: Transmit Alarm Registers (TX_ALARM) (Continued)

1. undefined if LEGACY = 1.

tx_flag

tx_flag is used to flag a DOM transmit alarm.

tx_flag = {OR of (reg 1.A070.n 'bit wise AND' reg 1.9006.n) for n=0 to 7}

Table 27: tx_flag Alarm Registers

Description	MDIO Status Register (RO/ LH)	MDIO Enable Register (R/W)	MDIO Enable Register default value
Transmit Temperature High Alarm	1.A070h.7	1.9006h.7	0
Transmit Temperature Low Alarm	1.A070h.6	1.9006h.6	0
tx_flag alarm bits 4 and 5*	1.A070h.5:4	1.9006h.5:4	0
Laser Bias Current High Alarm	1.A070h.3	1.9006h.3	0
Laser Bias Current Low Alarm	1.A070h.2	1.9006h.2	0
Laser Output Power High Alarm	1.A070h.1	1.9006h.1	0
Laser Output Power Low Alarm	1.A070h.0	1.9006h.0	0

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* tx_alarm bits 4 through 5 are read from the DOM device and mapped to registers 1.A070h.5:4. The function of these bits is not specifically defined in the XENPAK MSA, but they are used in generating the tx_flag signal in order to allow for vendor specific alarms to be defined. These alarms should be disabled via the associated MDIO register bits 1.9006h.5:4 when not is use.

WIS_ALARM

WIS_ALARM is used to indicate that a WAN-related fault has occurred on the receive path. WIS_ALARM is the bitwise OR of the WIS Status 3 Register bits in register 2.21h. WIS_ALARM can be programmed to assert only when specific receive path fault conditions are present. The programming is performed by writing to a mask register at address 2.C500h. The contents of register 2.21h is AND'ed with register 2.C500h prior to application of the OR function to generate the WIS_ALARM signal.

tWIS_ALARM = {OR of (reg 2.21h.n 'bit wise AND' reg 2.C500.n) for n=0..11}

Table 28: WIS Status 3 Register (WIS_ALARM)

		MDIO Status Register (RO)		MDIO Enable Register (R/W)	
Description	Definition	16b hex	type	16b hex	default value
LOP-P	Loss of Pointer	2.21.0	RO/LH	2.C500.0	0
AIS-P	Alarm Indication Signal	2.21.1	RO/LH	2.C500.1	0
PLM-P	Loss of Label Mismatch	2.21.2	RO/LH	2.C500.2	0
LCD-P	Path Loss of Cell Delineation	2.21.3	RO/LH	2.C500.3	0
AIS-L	Line Alarm Indication Signal	2.21.4	RO/LH	2.C500.4	0
RDI-L	Line Remote Defect Indication	2.21.5	RO/LH	2.C500.5	0
LOS	Loss of Signal (based on no transitions as described in ANSI T1.416-1999)	2.21.6	RO/LH	2.C500.6	0
LOF	Loss of Frame	2.21.7	RO/LH	2.C500.7	0
Reserved, set to 0		2.21.8	RO	2.C500.8	0
Far End AIS-P/LOP-P	Far-end Alarm Indication Signal	2.21.9	RO/LH	2.C500.9	0
Far End PLM-P/LCD-P	Far-end Loss of Label Mismatch	2.21.a	RO/LH	2.C500.a	0
SEF	Severely Errored Frame	2.21.b	RO/LH	2.C500.b	0
Reserved, set to 0		2.21.f:c	RO	2.C500.f:c	0

WIS_EXT_ALARM

WIS_EXT_ALARM is used to indicate that a WAN-related fault has occurred on the receive path. WIS_EXT_ALARM is the bitwise OR of the WIS Extended Alarms Status Register bits in register 2.C502h. WIS_EXT_ALARM can be programmed to assert only when specific receive path fault conditions are present. The programming is performed by writing to a mask register at address 2.C501h. The contents of register 2.C502h is AND'ed with register 2.C501h prior to application of the OR function to generate the WIS_ALARM signal.

tWIS_ALARM = {OR of (reg 2.C501h.n 'bit wise AND' reg 2.C502.n) for n=0..11}

		MDIO Status Register (RO)		MDIO Enable Register (R/W)	
Description	Definition	16b hex	type	16b hex	default value
K1 Validated Byte Flag	Incorrect K1 Validated Byte	2.C502.0	RO/LH	2.C501.0	0
K2 Validated Byte Flag	Incorrect K2 Validated Byte	2.C502.1	RO/LH	2.C501.1	0
Received Inconsistent K1 Bytes Flag	Received Inconsistent K1 Bytes	2.C502.2	RO/LH	2.C501.2	0
Received Inconsistent K2 Bytes Flag	Received Inconsistent K2 Bytes	2.C502.3	RO/LH	2.C501.3	0
S1 Validated Byte Flag	Incorrect S1 Validated Byte	2.C502.4	RO/LH	2.C501.4	0
Reserved	Reserved	2.C502.5	RO	2.C501.5	0
Received <u>New</u> J0 Trace <u>Message</u> Mismatch Flag	New J0 Trace Message detected Received J0 Trace Mismatch	2.C502.6	RO/LH	2.C501.6	0
Received <u>New</u> J1 Trace <u>Message</u> Mismatch Flag	New J1 Trace Message detected Received J1 Trace Mismatch	2.C502.7	RO/LH	2.C501.7	0
SD Alarm Flag	Detected Signal Degrade Alarm	2.C502.8	RO/LH	2.C501.8	0
SD Timing Window Expired Flag	Signal Degrade Timing Window Expired	2.C502.9	RO/LH	2.C501.9	0
SF Alarm Flag	Detected Signal Fail Alarm	2.C502.a	RO/LH	2.C501.a	0
SF Timing Window Expired Flag	Signal Fail Timing Window Expired Flag	2.C502.b	RO/LH	2.C501.b	0
Reserved		2.C502.f:c	RO	2.C501.f:c	0

 Table 29:
 WIS Extended Alarms Status Register (WIS_EXT_ALARM)



8.4.2 Receive Loss-of-Signal Pin (LOSOUTB)

LOSOUTB indicates when the input signal applied at RXIN/P is below a threshold which can be adjusted via the resistor connected to the ITH_LOS pin. LOSOUTB=0 indicates that the signal is below the threshold.

The logic of the LOSOUTB output may be reversed using the XFP input. This may be required when using the QT2022/32 in conjunction with an XFP module. See Section 8.2.2 for details.

8.4.3 Laser Driver Enable Pin (TXENABLE)

The TXENABLE Status Pin is used to enable or disable an external laser driver. The state of the XFP Control pin inverts the logic TXENABLE output logic.

When XFP is LOW, the TXENABLE output is non-inverted. In the enable state, the open drain output is off allowing an external pull-up resistor to pull the TXENABLE output high. In this state, a driver on another device may pull the external TXENABLE signal low to disable the laser driver. In the disable state, the open drain output is on pulling the TXENABLE output low.

When XFP is HIGH, the TXENABLE output is inverted. In the disable state, the open drain output is off allowing an external pull-up resistor to pull the TXENABLE output high. In this state, a driver on another device may pull the external TXENABLE signal low to enable the laser driver. In the enable state the open drain output is on, pulling the TXENABLE output low. This pin should be connected to the XFP module "TX_DIS" pin.

The truth table showing the TXENABLE logic when XFP =0 is presented in Table 30. The truth table when XFP =1 is presented in Table 31. Note that the TXON pin state is not in the truth table in XFP mode because its function is changed to an output.

TXON Control Pin	Transmit Disable MDIO 1.9.0	Low Power Mode MDIO 1.0.11	Low Power Mode MDIO 3.0.11	Low Power Mode MDIO 4.0.11	TXENABLE Logical State	TXENABLE Driver State
0	х	х	х	х	Disabled	Low
х	1	х	х	х	Disabled	Low
х	х	1	х	х	Disabled	Low
х	х	х	1	х	Disabled	Low
x	х	х	х	1	Disabled	Low
1	0	0	0	0	Enabled	Float

Table 30: TXENABLE Logic (XFP = 0)



Table 31:	TXENABLE Logic (XFP = 1)
-----------	--------------------------

Transmit Disable MDIO 1.9.0	Low Power Mode MDIO 1.0.11	Low Power Mode MDIO 3.0.11	Low Power Mode MDIO 4.0.11	TXENABLE Logical State	TXENABLE Driver State
x	х	x	х	Disabled	Float
1	x	x	x	Disabled	Float
x	1	х	х	Disabled	Float
x	x	1	x	Disabled	Float
x	x	x	1	Disabled	Float
0	0	0	0	Enabled	Low

8.5 Low-Speed Output Pins (QT2032 only)

The pins described in this section apply to the QT2032 only. These pins are not defined for the QT2022 product.

All the low-speed output pins have the same type of open drain driver. An external $10-22 k\Omega$ pullup resistor to 1.2V is expected. The open drain configuration allows these signals to be wire or'ed with other active low open drain disable signals on the module. There are no internal pullups or pulldowns on these pins.

8.5.1 Line Timing Okay Status Pin (LTIMEOK)

The LTIMEOK pin is used in a WAN application using line timing mode where an external VXCO PLL circuit has been implemented and a fixed reference is not provided on SREFCLK, as explained in Section 6.2.4, "VCXO PLL," on page 32. The LTIMEOK pin is to be used to force the external VCXO to its center frequency when line timing conditions are not valid or line timing is disabled. When linetiming conditions are valid and linetiming is enabled, a logic HIGH on LTIMEOK indicates that the VCXO may lock to the Fiber RX recovered clock. When linetiming conditions are not valid or linetiming is disabled, a logic low on the LTIMEOK output pin will force the VCXO to its center frequency.

Refer to Section 6.2.4, "VCXO PLL," on page 32 for detailed information on the operation of the VCXO PLL.

8.6 LED/GPIO Driver Pins (LEDx)

The QT2022/32 incorporates three bidirectional I/Os. One of the primary applications for these pins is as direct LED drivers in hostboard applications. They can also be used for general purpose input or output.

Each LED driver may be programmed to one of several different modes using the LED Configuration Registers 1.D006h, 1D007h and 1.D008h (for LED1, LED2 and LED3 respectively).

Each LED can be programmed to indicate one of the following conditions:

- RX or TX Link Status Only
- RX or TX Activity Status Only
- RX or TX Link Status/Activity Status Combined
- LED on
- LED off



Each LED driver can be independently programmed to monitor either the transmit path or the receive path, controlled by bit 3 of the LED Configuration Registers. LED1 monitors the transmit path by default, while LED2 and LED3 monitor the receive path by default.

TxXAUI lane alignment is used as the link status indication on the transmit path. PCS block_lock is used as the link status indication on the receive path. A packet activity event will be generated when the packet start code ||S|| is detected in the PCS encoder for transmit path or in the PCS decoder for the receive path.

In 'Activity Status' mode the LED will be off normally and flash on for 50 or 100ms on at each activity event, and will be subsequently turned off for 25 or 50ms. Any packet activity events that occur before the LED toggle cycle finishes will be ignored. figure 19 on page 71 shows the LED stretching behavior for activity only mode.

In 'Link Status / Activity Status Combined' mode the LED is ON to indicate the link is up and OFF to indicate the link is down. When the link is up, the LED will turn off for 25 or 50ms for each activity event, and will be subsequently turned on for 50 or 100ms. Any packet activity events that occur before the LED toggle cycle finishes will be ignored. figure 20 on page 72 shows the LED stretching behavior for link/activity combined mode.

The stretch time is controlled by bit 4 of the LED Configuration Registers. This determines the amount of time the LED will flash on during a packet activity event. When set to a 0 (default) the stretch time is 50ms; when set to a 1, the stretch time is 100ms. The time the LED is turned off during the packet activity event is equal to half the stretch time.

When in Link Status Only mode, the LED is OFF when the link is down. The LED is ON when the link is up.

The LED driver pins are open drain circuits (10mA max current rating). When the LED is ON, the driver pin is driven low (control register bits 2:0 = (101')). When the LED is OFF, the driver pin is high impedance (control register bits 2:0 = (100').

LED1 and LED2 are in "Link Status and Activity" monitor mode by default. LED3 is in "Link Status Only" mode by default.

The LED2 pin is also used to enable 'two-byte' indirect addressing on the I2C bus. To enable this feature, the LED2 pin is held low during a hard reset (using RESETN pin).

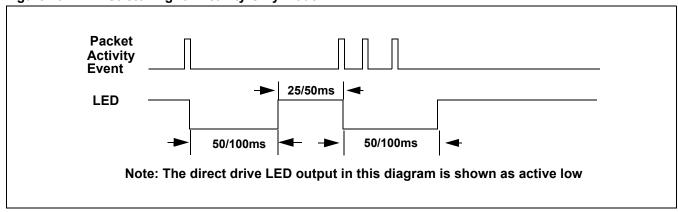
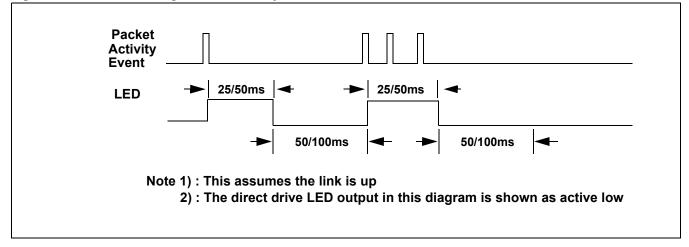


Figure 19: LED Stretching for Activity Only Mode







8.7 Analog Control Pins

This section describes the low-speed analog control pins on the product.

8.7.1 Loss of Signal Threshold Adjust Pin (ITH_LOS)

The ITH_LOS pin is used to set the analog loss of signal (LOS) alarm threshold. The LOS alarm includes hysteresis. An LOS alarm is declared when the peak-to-peak signal at the fiber receiver drops below the assert threshold level (signal level 'A' in Section 50, "LOSOUTB Hysteresis," on page 198). The LOS alarm is cleared when the peak-to-peak signal increases above the deassert threshold level (signal level 'B' in Section 50, "LOSOUTB Hysteresis," on page 198).

The analog LOS alarm drives the LOSOUTB signal output to indicate an alarm state. Refer to Section 8.4.2, "Receive Loss-of-Signal Pin (LOSOUTB)," on page 69 for details. The analog LOS alarm does not perform any other actions.

The alarm threshold is set by connecting a resistor between the pin and ground. The resistor value determines the threshold. The hysteresis is fixed for a given alarm threshold.

The analog LOS detector is always enabled. If the pin is left open (no resistor to ground) the LOS detector will never assert.

Please consult AMCCs' Application Note "Implementing LOS for the QT2022/QT2032" for more information on design practices with the LOS feature.



9 MDIO Interface

The management data input output (MDIO) interface provides a simple, two wire, serial interface to connect a station management entity (STA) and a managed PHY for the purpose of controlling the PHY and gathering status from the PHY. The management interface consists of the two wire physical interface, a frame format, a protocol specification for exchanging the frames and a register set that can be read and written using these frames. The two wires of the physical interface are the Management Data Clock (MDC) and the Management Data I/O (MDIO).

9.1 Management Data Clock (MDC)

The MDC is sourced by the Station Management entity to the PHY as the timing reference for transfer of information on the MDIO signal. MDC is an aperiodic signal that has no maximum high or low times. Please see Table 61, "MDIO AC Parameters," on page 189 for minimum high and low times.

9.2 Management Data I/O (MDIO)

MDIO is a bidirectional signal between the PHY (QT2022/32) and the STA. It is used to transfer control and status information. Data is always driven and sampled synchronously with respect to MDC.

9.3 MDIO Timing Relationship to MDC

MDIO is a bidirectional signal that can be sourced by the STA or the QT2022/32. When the STA sources the MDIO signal, the STA shall provide a minimum of 10ns of setup time and a minimum of 10ns of hold time referenced to the rising edge of MDC.

When the MDIO signal is sourced by the QT2022/32, it is sampled by the STA synchronously with respect to the rising edge of MDC. Please see Table 61, "MDIO AC Parameters," on page 189 for the clock output delay.

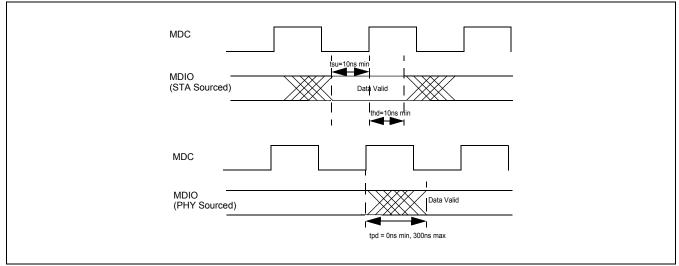


Figure 21: MDIO/MDC Timing

9.4 MDIO Bus Initialization

The MDIO bus requires a valid LAN reference clock to be supplied to the EREFCLK input to initialize after powerup or hard reset. The chip will not respond as expected to MDIO commands until a valid reference clock is present.

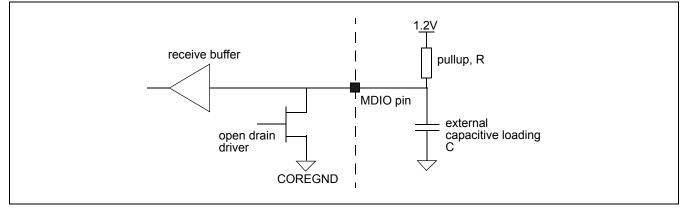
Once the MDIO bus has initialized, the reference clock supplied to EREFCLK can be removed and the MDIO bus will continue to function normally. If the power is cycled or a hard reset is applied to the chip, the LAN reference clock must be present to re-initialize the bus.

The MDIO bus does not require re-initialization after a soft reset (x.0.15 = 0).

9.5 MDIO Pin

The MDIO output has an open drain driver. An external pull resistor to 1.2V is expected as per Annex 45A of the IEEE standard.





9.6 Management Frame Format

The QT2022/32 has an internal Address register which is used to store the address for MDIO reads and writes. This MDIO Address register is set by sending an MDIO Address frame which specifies the register address to be accessed within a particular logical device.

After an Address frame has been sent, the following Write, Read or a Post-Read-Increment-Address frame to the same logical device accesses the register whose address is stored in the QT2022/32 MDIO Address register. An Address frame should be followed immediately by the associated Write, Read or Post-Read-Increment-Address frame.

Upon receiving a Post-Read-Increment-Address frame and having completed the read operation, the QT2022/32 shall increment the stored address in the MDIO Address register. If no Address frame is received before the next Write, Read or Post-Read-Increment-Address frame, then the QT2022/32 shall use the incremented address currently stored in the Address register.

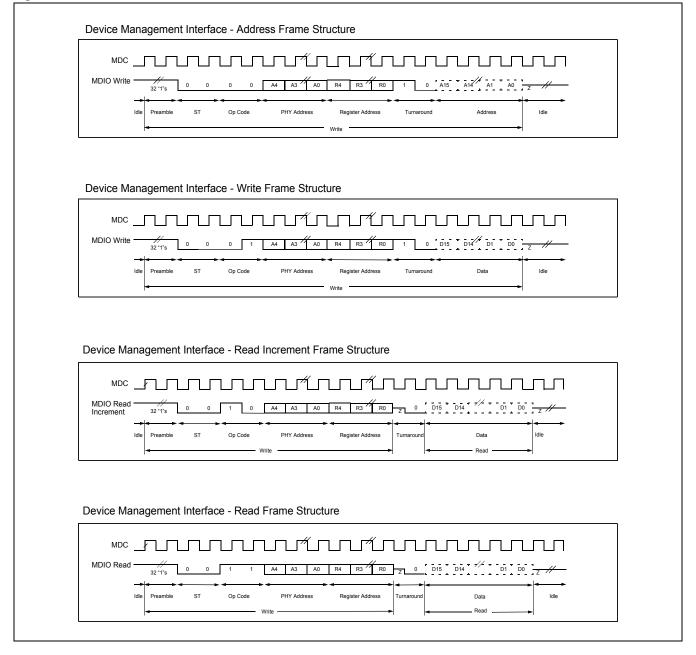
The Management Frame Format for Indirect Access is specified below.



Table 32: Management Frame Format

Management Frame Fields								
FRAME	PRE	ST	OP	PRTAD	DEVAD	ΤΑ	ADDR/DATA	IDLE
ADDRESS	11	00	00	PRTAD[4:0]	DA[4:0]	10	D[15:0]	Z
WRITE	11	00	01	PRTAD[4:0]	DA[4:0]	10	D[15:0]	Z
READ	11	00	11	PRTAD[4:0]	DA[4:0]	ZO	D[15:0]	Z
READ-INC	11	00	10	PRTAD[4:0]	DA[4:0]	ZO	D[15:0]	Z

Figure 23: MDIO Frame Structure



9.6.1 Preamble Field (PRE)

At the beginning of each transaction the STA shall send a preamble sequence of 32 contiguous logic one bits on MDIO with 32 corresponding cycles on MDC, to provide the QT2022/32 with a pattern that it can use to establish synchronization. The QT2022/32 must observe this preamble sequence before it responds to any transaction.

9.6.2 Start Field (ST)

The Start of Frame is indicated by a <00> pattern.



9.6.3 Operation Code Field (OP)

The Operation Code field describes the major function of the frame. Four frame types are supported, corresponding to the frames shown in figure 23 on page 76. The OP Codes for each frame type are shown in figure 33 on page 77.

Table 33: OP Code Definitions

OP Code	Operation
00	Register Address
01	Write Data
11	Read Data
10	Post Read Data + Increment

9.6.4 Port Address Field (PRTAD)

The Port Address is five bits, allowing 32 unique port addresses. The QT2022/32 port address is set through pins PRTAD<4:0>.

9.6.5 Device Address Field (DEVAD)

The Device Address is five bits, allowing 32 unique devices per port. The QT2022/32 supports device addresses 1 (PMA/PMD), 3 (PCS) and 4 (PHY XS).

9.6.6 Turnaround Field (TA)

The Turnaround time is a two bit time spacing between the Register Address field and the Data field of a management frame to avoid contention during a read transaction.

9.6.7 Data/Address Field

The Data/Address field is 16 bits. For the "Register Address" frame, this field contains the register address. For all other field types, it contains data. The first bit transmitted/received is bit 15, MSB, and the last bit is bit 0, LSB.

9.6.8 Idle Field (IDLE)

The IDLE condition on MDIO is a high-impedance state. The open drain driver will be turned off and the external pull-up resistor will pull the MDIO line to a logic one.

9.7 XFP Module Access Through MDIO

In an XFP application, the I2C bus of the QT2022/32 can be connected to the XFP module. The chip can communicate with the XFP module using the same read/write control register and memory space as the XENPAK NVR EEPROM defined in Section 10 on page 79. The XFP module I2C interface must be connected to the EEPROM_SCL and EEPROM_SDA clock and data lines. The XFP module address is 1010000x. The 256 byte XFP address space will be automatically read upon powerup or reset of the QT2022/32.

Read and write access to the XFP module uses the same register commands that apply to the EEPROM device. The control register for read/write access is Register 1.8000h. The XFP address space will be mapped to the QT2022/32 EEPROM memory space located in Register 1.8007-1.8106h.

When the QT2022/32 is in XFP mode any XENPAK interpretation of the address space is deactivated. For example, no DOM access will be performed and DOM-related LASI alarms are not triggered.

Each XFP module has a 2-wire serial interface which is an I2C interface. The QT2022/32 acts as the bus master to read from or write to the XFP module. Since the XFP module has the same slave address as the EEPROM slave address for XENPAK mode, the EEPROM and XFP module cannot exist at the same time. The XFP mode is selected using the XFP control pin. All the XFP module access through MDIO is indirect access. The detailed description of XFP module access is described in the EEPROM section (See "Two Wire (EEPROM) Interface" on page 79.). Single byte and 256 byte read and write are supported for XFP module access through the QT2022/32.

The following functions, which are specifically for XENPAK EEPROMs, are disabled in XFP mode:

- EEPROM checksum
- DOM capability
- · EEPROM protect capability
- PMA/PMD type control through eeprom
- *tx_flag* and *rx_flag* for generating LASI ALARM
- PMA/PMD Identifier (OUI)

See "QAN0026: QT2022C1 & QT2032A1 Implementation and Usage Tips for XFP Applications", referenced in Table 77, for more information.



10 Two Wire (EEPROM) Interface

The EEPROM interface is a standard two-wire interface that can be used as a master to control peripheral devices or as a slave to allow control by other devices. The primary application for this interface is in a module application to support an external EEPROM device for module NVR configuration and a DOM device for optical performance monitoring. This feature is based on the XENPAK MSA. In XFP mode, this interface can be used to communicate with an XFP module. An external microcontroller is able to control and access the QT2022/32 memory space via this interface.

The EEPROM serial interface consists of pins EEPROM_SCL and EEPROM_SDA. The logic levels for this interface are 0 and 1.2 Volts and is 3.3V tolerant. The EEPROM_SCL output clock is only active when accessing a peripheral device. The default clock rate is 37kHz. Clock stretching is supported.

The bidirectional EEPROM_SDA pin is an open drain active pull down driver for data transfer and may be wire-Or'ed with other open drain devices. It requires an external pullup resistor to 3.3V.

EEPROM_SCL is an output during normal operation. It requires an external pullup resistor to 3.3V. When the EEPROM_SCL clock signal is inactive, it is in a high impedance state. EEPROM_SCL is also bidirectional to allow an external device to control the I2C bus. The multi-master mode is supported through bus arbitration. The QT2022/32 can act as a slave device.

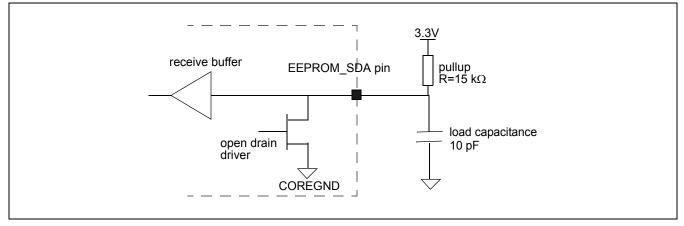


Figure 24: EEPROM_SDA Open Drain Driver Configuration

The EEPROM slave address for the XENPAK NVR is hardwired to 1010000. Data bytes are 8 bits. The word address bytes are 8 bits for a total of 256 word addresses. Each EEPROM device register is mirrored in an MDIO register within the QT2022/32. EEPROM registers 0-255 are mapped to MDIO registers 1.8007h to 1.8106h.

When the control pin EEPROM_PROT is high writes are blocked to the MDIO registers corresponding to EEPROM registers 0 to *PL* and *PU* to 255 inclusive. *PL* is set equal to one less than the customer field address, which is read from EEPROM register 6 and stored in MDIO register 32781 (800dh). *PU* is set equal to the vendor field address which is read from EEPROM register 7 and stored in MDIO register 32782 (800eh). If the uploaded customer field address is greater than or equal to the vendor field address then *PL* and *PU* will revert to their default values. The default value for *PL* is 82 (this corresponds to MDIO register 32857, 8059h). The default value for *PU* is 167 (this corresponds to MDIO register 80AEh).



Table 34: XENPAK EEPROM Register Map

		MDIO register					
	OM reg Iress	address		bits 7:0 default value ^a	XENPAK MSA Description		
0	0	32775 8007 00		00	first register, first register used for checksum calculation		
:				00			
6	6	32781	800D	00	customer field address		
7	7	32782	800E	00	vendor field address		
:				00			
17	11	32792	8018	00	10GBASE type		
:				00			
43	2B	32818	8032	00	Package Identifier OUI mapped to MDIO register 1.14 upper byte		
44	2C	32819	8033	00	Package Identifier OUI mapped to MDIO register 1.14 lower byte		
45	2D	32820	8034	00	Package Identifier OUI mapped to MDIO register 1.15 upper byte		
46	2E	32821	8035	00	Package Identifier OUI mapped to MDIO register 1.15 lower byte		
:				00			
82	52	32857	8059	00			
:				00			
99	63	32874	806A	00			
:				00			
115	73	32890	807A	01	DOM capability		
116	74			00			
117	75	32892	807C	00	last register used for checksum calculation		
118	76	32893	807D	00	basic field checksum value, default last lower protected EEPROM register (<i>PL</i>)		
119	77	32894	807E	00	start of customer writeable area		
:				00			
166	A6	32941	80AD	00	end of customer writeable area		
167 :	A7	32942	80AE	00	start of vendor specific registers, default start of upper prot reg (PU)		
200	C8	32975	80CF	00	Register upload configuration capability (See Section 10.7 on page 91) Bit 1: Register value upload enable control for two external EEPROMs. '1' indicates upload enable. Bit 4:2: Slave address for the first 256x8 external EEPROM which stores the registers upload values. If this value is '000' or '111' take no action. Bit 7:5: Slave address for the second 256x8 external EEPROM which stores the register upload values. If this value is '000' or '111' take no action.		



Table 34: XENPAK EEPROM Register Map (Continued)

		MDIO register			egister	
	EEPROM reg address		addi	address bits 7:0 default value ^a		XENPAK MSA Description
	•					
Ī	255	FF	33030	8106	00	

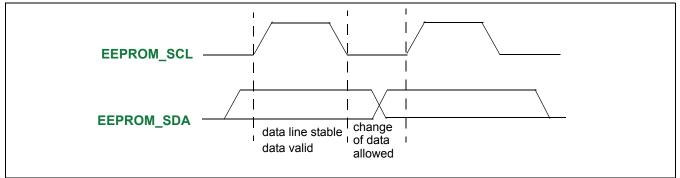
^a bits 15:8 of the MDIO registers are reserved (RO) and will return a value of 0 when read.

10.1 EEPROM Data Transfer Timing

10.1.1 Data Transfer

The data on the EEPROM_SDA line must be stable during the HIGH period of the clock EEPROM_SCL. The HIGH or LOW state of the data line can only change when EEPROM_SCL is LOW.

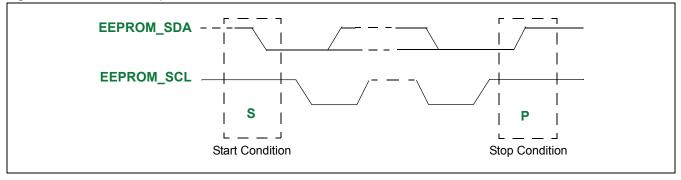
Figure 25: Data Bit Transfer



10.1.2 Start and Stop Conditions

A HIGH to LOW transition on the EEPROM_SDA line while EEPROM_SCL is high defines a START condition. A LOW to HIGH transition on the EEPROM_SDA line while EEPROM_SCL is high defines a STOP condition. START and STOP conditions are generated by the bus master

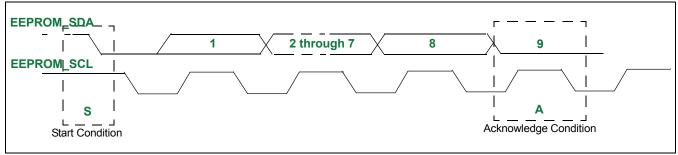
Figure 26: Start and Stop Conditions



10.1.3 Acknowledge

The transmitting device releases the EEPROM_SDA line after transmitting eight data or address bits. During the ninth cycle the receiving device will pull the EEPROM_SDA line low to acknowledge that it received the bits.





10.1.4 Bus Rate Control

The default clock rate for the EEPROM bus is 37kHz when the chip is the bus master. The QT2022/32's master bus rate can be increased to 74kHz or 600kHz-using the bus rate control bits 1.C003h.15:14.

10.2 EEPROM 256 Byte Read Cycle

The EEPROM 256 Byte Read Cycle is initiated by setting the MDIO register bits 1.32768.0:1 and clearing bit 1.32768.5 (1.8000h.5). Bits 0 and 1 are self clearing after the EEPROM 256 Byte Read Cycle is complete. MDIO registers 1.32768.3:2 (1.8000h.3:2) indicate when the read has been completed. The EEPROM command status register must be in the idle state, 1.8000h.2:3=00, for an EEPROM read command to be accepted.

The completion of a hard reset via the RESETN pin or a software reset via the MDIO also triggers the 256 byte read cycle. When powering up the QT2022/32, a hard reset will be applied, and the EEPROM registers will be automatically uploaded. The upload is part of the initialization sequence for the QT2022/32 and must be completed before the device is ready for use. The EEPROM command status register, MDIO 1.8000h.2:3, can be monitored to see when the upload has been completed. A complete upload of 256 bytes requires approximately 60 ms, when the burst read size is set to the default value of 256 bytes.

The timing for the 256 Byte Read Cycle is shown in the figure figure 28 on page 83. The EEPROM internal address counter is first set to 0 by a dummy write cycle. This is followed by a random access read from word address 0. The reception of the 8 data bits is followed by an acknowledgement (ACK) from the QT2022/32. The ACK indicates to the EEPROM that data from the next word address will be read. An ACK is supplied after the reception of each data byte until a total of 256 bytes have been read. No ACK is given after data byte 255 followed by a STOP (P) to terminated the sequential read cycle.

The data which is read is stored in 256 MDIO registers starting at address 1.8007h through to address 1.8106h. The 8 bit bytes from the EEPROM are mapped onto the 8 LSB's of the associated MDIO register. The other 8 bits are unused. They cannot be written to, and will return a value of 0 if read.

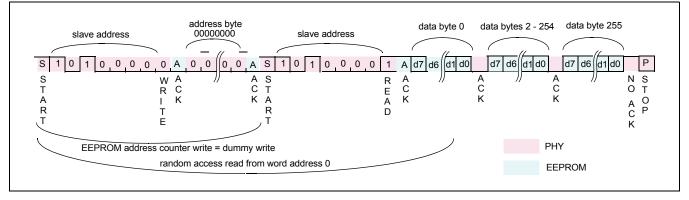


Figure 28: EEPROM 256 Byte Read Cycle Timing

The MDIO interface transmits and receives bit 15 first. The EEPROM protocol has bit 7 transmitted first. MDIO data bits are numbered from 0 to 15. EEPROM bits are numbered from 0 to 7. EEPROM bit 0 is mapped to MDIO register bit 0, EEPROM bit 7 is mapped to MDIO register bit 7. The upper 8 MDIO register bits are hard wired to 0.

The EEPROM slave address is hard wired to 1010000. The first 4 bits of the slave address (1010) are the EEPROM device type identifier portion and 000 is the EEPROM device address.

The EEPROM must provide an acknowledgement (ACK) when presented with its slave address before any reads or writes can occur. Upon reception of the ACK, the sequential read can commence. The EEPROM must also provide an ACK after the address byte field and slave address field are sent. If any of the three expected ACKs is not provided by the EEPROM, the QT2022/32 will restart the read cycle. If proper ACKs are not received after 16 polling sequences the error flag EEPROM_ACK_error is set and the read sequence is aborted. This error flag can be accessed at MDIO register address 1.C003h.12. It is cleared upon a read of this register or a QT2022/32 chip reset.

10.2.1 EEPROM Checksum Checking

The QT2022/32 will perform a checksum calculation and compare after every successful 256 byte read. The checksum for comparison is in EEPROM register 118 = 1.32893 (1.807Dh). The checksum is equal to the 8 LSB's of the sum of bytes 0 to 117 of the EEPROM. The calculated checksum is stored in MDIO register 1.C004h.15:8. The result of the comparison of the calculated checksum with the one read from the EEPROM is placed in MDIO register 1.C003h.7.

10.3 EEPROM 256 Byte Write Cycle

An EEPROM 256 Byte Write Cycle is initiated by setting MDIO bits 1.8000h.0,1 and 5 to 1.

The EEPROM command status register must be in the idle state, 1.8000h.2:3=00, for an EEPROM write command to be accepted.

The information to be written to the EEPROM is stored in the same 256 MDIO registers where the data read from the EEPROM is placed. Data must be placed in MDIO registers 1.8007h to 1.8106h via the MDIO interface before starting the EEPROM 256 byte write sequence.

Page write mode is used to transfer 1, 8 or 16 bytes (set by MDIO register 1.C003h.1:0) to the EEPROM at a time. It is done sequentially 256, 32 or 16 times in order to transfer all 256 bytes. In between page writes, the QT2022/32 polls the EEPROM for an ACK, which indicates that the EEPROM internal write cycle is completed. If no ACK is received, the QT2022/32 waits for 1.7ms and then repeats the poll for an ACK. After 16 tries without an ACK, the write cycle is aborted and the EEPROM_ACK_error flag is set. An ACK must be received after each data word is written or the write cycle is aborted and the EEPROM_ACK_error flag is set. MDIO registers 1.32768.3:2 (1.8000h.3:2) indicate when the write has been completed.

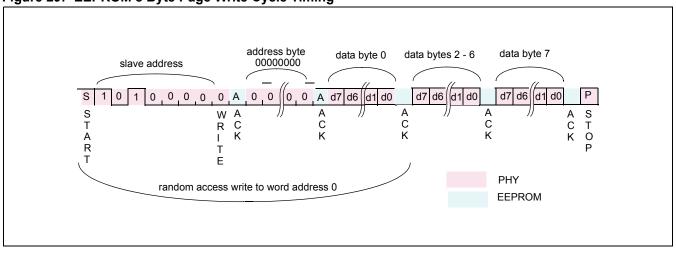


Figure 29: EEPROM 8 Byte Page Write Cycle Timing

10.4 EEPROM Single Byte Read or Write Cycle

An EEPROM Single Byte Read/Write Cycle is initiated by setting MDIO EEPROM control register bits 1.32768.1:0 (1.8000h.1:0) to 10. As for the 256 byte read/write commands, MDIO register 1.8000h.5 determines if a read or a write cycle will be performed. The single byte EEPROM address is read from EEPROM control register bits 1.8000h.15:8. The data is read to or from the associated MDIO register.

If an NVR command is in progress, then no new NVR command will be accepted. The NVR command register must be in the idle state for any new NVR commands to be accepted. A DOM command request will be queued if an NVR command is in progress.

10.5 XENPAK Diagnostic Optical Monitoring (DOM)

Diagnostic Optical Monitoring (DOM) is performed using an external device, hereafter referred to as the DOM device. All analog signal measurement and calibration will be done by the DOM device. No analog signal measurement is done by the QT2022/32.

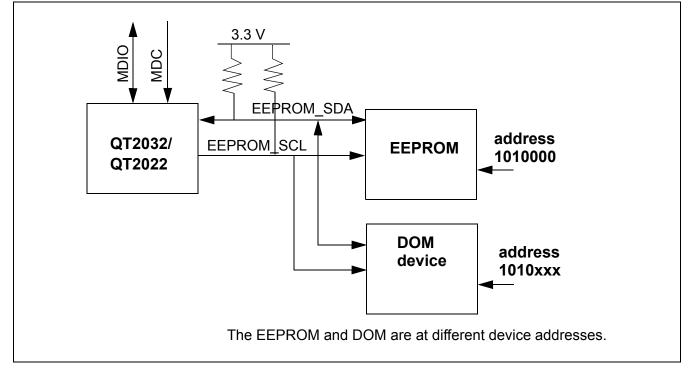
NOTE: This feature applies only to XENPAK type applications (XFP=0). For an XFP application, the QT2022/32 will disable the XENPAK DOM functionality when the XFP pin is driven high (XFP=1). The XFP DOM information will be stored in the QT2022/32 EEPROM memory space (Register 1.8007-1.8106h).

The 256 8-bit registers of the DOM device will be accessed via the QT2022/32 EEPROM bus and transferred to MDIO registers 1.A000-1.A0FFh.

Communication between the Station management Entity (STA) and the module will be done via the QT2022/32 MDIO interface only.







The current 256 NVR registers will continue to be read from an external EEPROM with device address 1010000. NVR register mapping and update control conform to the XENPAK MSA.

MDIO device number 1 is used for the NVR registers and DOM registers on QT2022/32.

The presence of an external DOM device is indicated by NVR register 1.807Ah.6. This bit must be set to 1 to enable the QT2022/32 DOM logic. The lower 3 bits of the DOM device address are read from NVR register 1.807Ah.2:0 (defaults to 001 after reset). The upper 4 device address bits are hardwired to 1010. The DOM device address must be in the range 1010001x to 1010111x.

The default frequency of the serial interface clock, EEPROM_SCL, is 37kHz. This will result in an upload time of approximately 62ms for 256 bytes assuming for no wait times for the DOM device to respond. Clock stretching is supported.

Refer to Section 18.10, "DOM Memory Behavior," on page 216 for details on DOM Memory usage.

10.5.1 DOM Upload on Reset

Both the NVR and DOM registers are set to their default values by a hardware or software reset. The NVR registers are automatically uploaded after a reset is applied to the QT2022/32. The upload begins 250 ms after the reset function is completed. This delay is to allow the external devices time to stabilize after power up. After the NVR registers are successfully uploaded, and if a DOM device is present, the DOM registers will be uploaded. The DOM update frequency defaults to a single upload (1.A100h.1:0=00). If a reset occurs in the middle of a DOM or EEPROM transaction, the transaction is stopped immediately, the QT2022/32 releases the EEPROM_SDA pin and drives the EEPROM_SCL pin high.

The EEPROM and DOM upload sequence is presented in figure 36 on page 92.

10.5.2 rx_flag and tx_flag DOM Alarm Fields

rx_flag and *tx_flag* alarm signals will be generated by the QT2022/32 using information read from MDIO DOM diagnostic alarm registers 1.A070h and 1.A071h and MDIO NVR diagnostic alarm enable registers, 1.9006h and 1.9007h. The default state for registers 1.9006h and 1.9007h is 0.

rx_flag = {OR of (reg 1.A071h.n 'bit wise AND' reg 1.9007.n) for n=0 to 7}

tx_flag = {OR of (reg 1.A070h.n 'bit wise AND' reg 1.9006.n) for n=0 to 7}

 rx_flag is placed in bit 1 of the MDIO RX_ALARM register, 1.9003h.1. tx_flag is placed in bit 1 of the MDIO TX_ALARM register, 1.9004h.1. These register bits are latched when high and cleared on read. The RX_ALARM register values, 1.9003h.0:15, along with their corresponding enable bits, 1.9000h.0:15, are used to create the rx_alarm signal. The TX_ALARM register values, 1.9004h.0:15, along with their corresponding enable bits, 1.9001h.0:15, are used to create the tx_alarm signal.

tx_alarm = {OR of (reg 1.9004.n 'bit wise AND' reg 1.9001.n) for n=0 to 9}

rx_alarm = {OR of (reg 1.9003.n 'bit wise AND' reg 1.9000.n) for n=0 to 5}

The default value for the *tx_flag* alarm enable register, 1.9001h.1, will be 0. The default value for the *rx_flag* alarm enable register, 1.9000h.1, will be 0.

QT2022/32 will generate the LASI signal.

Since the 1.A071h and 1.A070h registers are read only registers, a diagnostic alarm condition will not be cleared until the DOM registers are updated with alarm free information followed by a read of RX and TX ALARM latched high registers to clear them.

10.5.3 DOM Updates

The DOM register update rate will be set by MDIO DOM register 1.A100h.1:0 contents. Writing 00 to these bits will initiate a single upload of the DOM registers. If these bits are set to any other state the DOM registers be periodically updated.

A100h.1:0	
00	write of 00 initiates a single update of MDIO DOM registers
01	periodic update of MDIO DOM registers every 60 seconds
10	periodic update of MDIO DOM registers every 10 seconds
11	periodic update of MDIO DOM registers every 1 second

Table 35: DOM Update Rates

The EEPROM bus protocol transmits bit 7 first. EEPROM/DOM bits are numbered from 0 to 7. EEPROM/DOM bit 0 is mapped to MDIO register bit 0, EEPROM/DOM bit 7 is mapped to MDIO register bit 7. The upper 8 MDIO register bits are hard wired to 0.

If a DOM update is requested while a NVR register read or write is in progress, the NVR transaction will be allowed to complete and the DOM update will begin when the NVR transaction completes. While the DOM update is waiting to happen the DOM command register will indicate a transaction in progress. The same applies if an NVR transaction is requested while a DOM update is in progress. While an NVR or DOM update is queued, the associated command register will be put in the command in progress state.

For a single update of the DOM registers the command status register, 1.A100h, functions the same way as the NVR command status register - see XENPAK MSA Figure 19.

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When the DOM automatic upload mode is selected, the 'command complete' or 'idle' state will be changed to the 'command in progress' state upon the start of a new self initiated upload. This is so an STA read of the MDIO DOM command status register, 1.A100h, is not needed to clear the 'command complete' state. If the 'command failed' state is entered, a read of 1.A100h must be performed to clear the failure state. A 'command failure' will cause the automatic uploading of DOM registers to stop. If 00 is written to the DOM update frequency control bits, the QT2022/32 will complete a DOM update in progress, or if it is in the periodic update wait state it will immediately perform a DOM update. In either case the device will no longer be in periodic update mode.

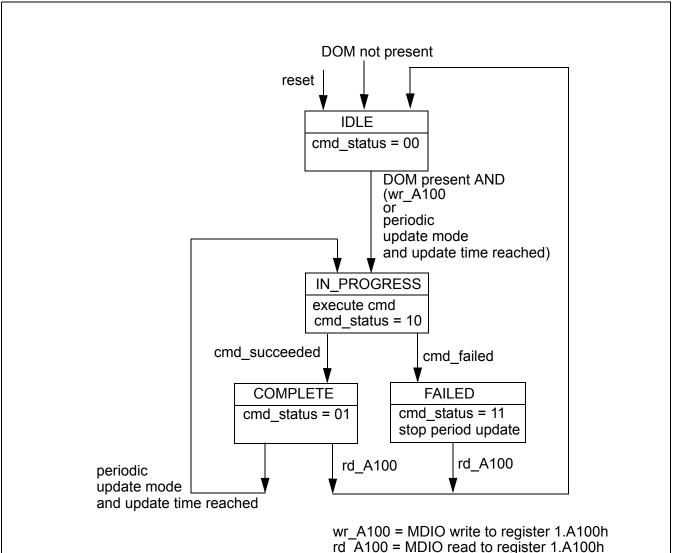


Figure 31: DOM Access State Diagram

A DOM or NVR command failure is declared after 16 polling sequences spaced by 1.7 ms without an acknowledgement from the external device. (The total elapsed time for this sequence is 16*10bits*1bit/37kHz+15*1.ms = 30 ms)

A AMCC-specific DOM write command has been added. The write control is via MDIO vendor specific register 1.C004h. The write can be a full 256 byte write or a single byte write to the address specified in MDIO register bits 1.C002h.7:0. The write command status registers have been added to the unused/undefined upper bits of the DOM read command register. This allows for clearing of either read or write command failures with a single MDIO register read. The QT2022/32 EEPROM_PROT pin must be pulled low to enable writing to the DOM MDIO registers and to the DOM device registers.

Table 36:	DOM	Control	Registers
-----------	-----	---------	-----------

Bit	PMA/PMD Vendor Specific DOM Control/Status Register 1.A100h	PMA/PMD Vendor Specific EEPROM Checksum/ DOM Write Control Register 1.C004h
0	DOM Read Commands / Update Rate (R/W) bit1 bit0 Command 0 0 write of 00 initiates a single update of MDIO DOM registers 0 1 periodic update of MDIO DOM registers every 60 seconds 1 0 periodic update of MDIO DOM registers every 10 seconds	DOM Write Command (R/W) bit 11 bit10 Command 0 0 idle, default 0 1 reserved 1 0 write 1 byte
2 3	1 1 periodic update of MDIO DOM registers every 1 second DOM Read Command Status (RO, LH) bit3 bit2 Command Status 0 0 no command 0 1 command completed 1 0 command in progress 1 1 previous command failed	1 1 write 256 bytes DOM 256 byte write cycle burst size (R/W) size bit 15 bit 14 1 0 0 8 0 1 default 16 1 0 1 1 1 1 1
4	reserved (RO)	reserved (RO)
5	reserved (RO)	reserved (RO)
6	reserved (RO)	reserved (RO)
7	reserved (RO)	reserved (RO)
8	reserved (RO)	reserved (RO)
9	reserved (RO)	EEPROM calculated checksum
10	reserved (RO)	(RO)
11	reserved (RO)	
12 13	DOM Write Command Status (RO, LH)bit 13bit12Command status00no command01command completed10command in progress11previous command failed	
14	reserved (RO)	
15	reserved (RO)	

Before doing a DOM MDIO register write and subsequent DOM device write, the DOM must be idle and not be in periodic update mode. This is to ensure that a DOM read does not overwrite the DOM MDIO registers before data has been transferred to the DOM device.

If a DOM (NVR) device access is queued and an NVR (DOM) device access which is in progress fails, then the NVR (DOM) command failure flag is set and the DOM (NVR) device access is allowed to proceed. No NVR (DOM) commands are accepted while the NVR (DOM) command failure state is set. this state must be cleared before another NVR (DOM) command can take place.



10.6 Two-byte Addressing of Peripheral I2C Devices

To allow a single device on the I2C bus to store the entire DOM and EEPROM memory space, the QT2022/32 can be configured to support 64kB rather than 256 bytes within an I2C device. This requires 2 bytes rather than 1 for the addressing within the I2C device. To enable 2-byte addressing, the LED2 pin must be held low during a hard reset. The device address must be 1010000 as defined in the XENPAK MSA for the EEPROM.

The read/write cycle will now contain two 8-bit address bytes. The upper word address is the most significant. When executing a read/write command to the EEPROM memory space, the first word address will be all 0's. This means that the first 256 bytes of memory (address range 0000 - 00FFh) in the peripheral I2C device must be reserved for the EEPROM memory. A sample 8 byte page write transaction to the EEPROM space is shown in Figure 32. A sample 8 byte page read transaction to the EEPROM space is shown in Figure 33.

When performing a read/write command to the DOM memory space, the upper address byte will specify the base address of the equivalent DOM memory in the peripheral I2C device. The lower three bits of this word are taken from the 'DOM capability' register 1.807Ah, bits 2:0. The upper 5 bits are set by MDIO register bits 1.C023h.4:0 (default 0b00000). A sample 8 byte page write transaction to the DOM space is shown in Figure 34. A sample 8 byte page read transaction to the DOM space is shown in Figure 35.

In this mode, the QT2022/32 supports the same read and write commands as with standard 8-bit addressing. The commands are initiated in the same manner.

10.6.1 Behavior on Startup/Reset

On startup or reset, the QT2022/32 will follow the boot sequence shown in figure 36 on page 92. The QT2022/32 will first initialize the bus and then pause for 250ms. The chip will then automatically read the NVR memory space. The secondary EEPROM memories and the DOM memory space are then read, if enabled.

Bus Initialization

The QT2022/32 initializes the two wire interface by sending 9 STOP conditions on the bus. This clears any transactions that are in progress on the bus. In particular, this prevents bus conflicts if any previous transactions are interrupted by reset events.

Reset Behavior with Two-Byte Addressing

This behavior is not changed when two-byte addressing is enabled. The value of MDIO register bits 1.C023h.4:0 will revert to their default value on startup or reset. Therefore, the upper address byte will be in the range 0x01 to 0x07. Thus, the DOM memory space must be located in the lower 2kB of I2C device memory for the automatic read to work properly on startup/reset.

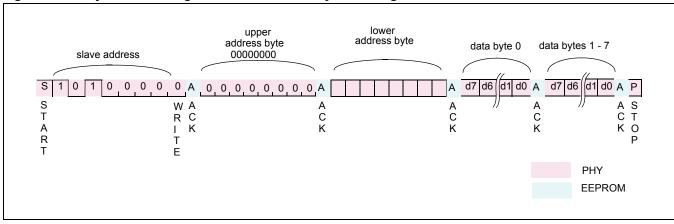
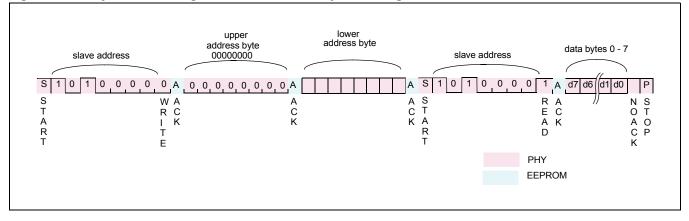
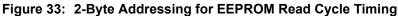


Figure 32: 2-Byte Addressing for EEPROM Write Cycle Timing







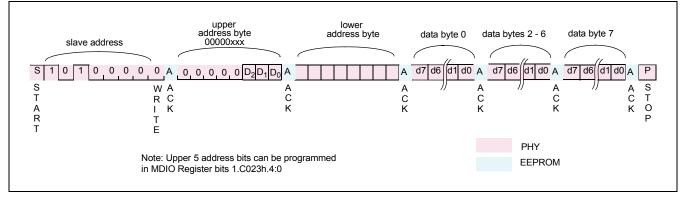
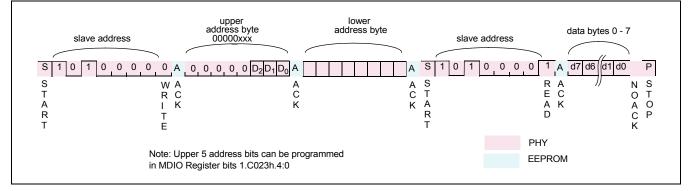


Figure 35: 2-Byte Addressing for DOM Read Cycle Timing





10.7 Register Configuration from External EEPROM

All MDIO registers can be configured through upload from external EEPROMs. This feature can be used to change the value of any MDIO register from the default without requiring an MDIO command. The new values are uploaded automatically after chip powerup or reset. This can be used for changing the chip settings from their default to customize module operation.

Up to two 256-byte external EEPROM devices can be used to configure the MDIO registers. The configuration of each MDIO register requires 5 bytes of EEPROM space. The maximum number of MDIO registers which can be configured is 256/5 = 51 per EEPROM device (maximum of 102 registers with two devices). The data structure in the EEPROM for the MDIO register configuration is shown in Table 37, "Data structure of MDIO register configuration".

The 5 bytes of EEPROM memory for each MDIO register must be contiguous. The values must be stored in the order shown in Table 37. The EEPROM memory space is logically divided into blocks of 5 bytes each, starting at memory locations 0, 5, 10, 15...250. The 5 bytes of register data must be stored in one of these logical blocks. Any of these 51 logical blocks may be used. Any block may be used to store data for any valid register. Unused registers should be set to 00h or FFh. The QT2022/32 will ignore fields where the Device ID or Register Address fields do not correspond to a defined register.

Location	FIELD
0	Device ID [7:0]
1	Register Address[15:8]
2	Register Address[7:0]
3	Register Data[15:8]
4	Register Data[7:0]

Table 37: Data structure of MDIO register configuration

The MDIO registers upload configuration capability is indicated by NVR vendor specific register 1.80CFh. Bit 1 is the register upload configuration enable control for two 256x8 EEPROMs. The lower 3 bits of the first register configuration EEPROM device address are read from 1.80CFh.<4:2> and the lower 3 bits of the second EEPROM device address are read from 1.80CFh.<7:5>. The upper 4 device address bits are hard-wired to 1010. These two devices address must not be the same as that of the EEPROM NVR device (i.e. 000) or DOM device as defined in 1.807A.

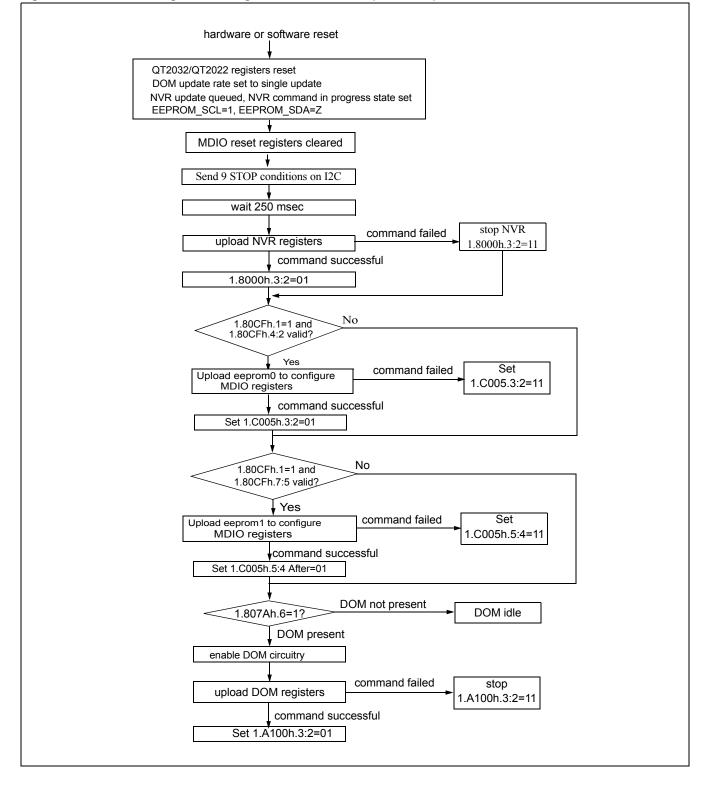
The upload sequence after powerup is shown in figure 36 on page 92. The EEPROM NVR registers are automatically uploaded after a reset is applied to the QT2022/32. The upload begins 250 ms after the reset function is completed. This delay allows the external EEPROM NVR device time to stabilize after power up.

After the NVR registers are successfully uploaded following a reset, the QT2022/32 will check if the first EEPROM and/or the second EEPROM device are configured as present by checking the contents of NVR register 1.80CFh (EEPROM address C8h). When bit1 is set to 0, it indicates additional EEPROM devices are present. Bits 4:2 store the address of the first EEPROM device and bits 7:5 store the address of the second EEPROM device. If the EEPROM devices are indicated as present with valid addresses, the devices will be read and the MDIO registers set accordingly. If the stored address for either EEPROM device is 000 or 111, the QT2022/32 will not attempt to read from that device.

When the EEPROM read sequence is complete, the DOM registers will then be uploaded if the DOM device is present. After reset has completed, the MDIO registers can also be uploaded at any time by issuing a MDIO register write of 11 to register 1.C005h.1:0.







Bit	Registers upload command and Status 1.C005h
0	Register upload Commands (R/W)
1	bit1 bit0 Command 0 0 Reserved 0 1 Reserved 1 0 Reserved 1 1 write-> Upload the MDIO registers from external EEPROM.
2	Register upload Command Status for the first EEPROM (RO, LH)
3	bit3 bit2 Command 0 0 idle, no command 0 1 command completed 1 0 command in progress 1 1 previous command failed
4	Register upload Command Status for the second EEPROM (RO, LH)
5	bit3 bit2 Command 0 0 idle, no command 0 1 command completed 1 0 command in progress 1 1 previous command failed
15:6	Reserved (RO)

Table 38: Upload Command and Status Register 1.C005h

10.8 I2C Slave Mode for Register Configuration

The MDIO register space can be accessed through the 2-wire serial interface (TWI) bus. This allows the QT2022/ 32 to be controlled by an external microprocessor. MDIO register read or write access through the 2-wire interface is indirect access. The EEPROM_SCL and EEPROM_SDA clock and data pins are used for this feature.

10.8.1 Register Address Mapping

The normal 256 byte I2C address space is divided into lower and upper blocks of 128. The lower block of 128 bytes is directly available and is used for defining the MDIO device ID and MDIO register starting address. Address location 125 (7Dh) stores the MDIO device ID (for the QT2032 devices 1, 2, 3 and 4 are supported; for the QT2022 only devices 1, 3 and 4 are supported). Address 126 (7Eh) stores the upper byte of the register address to be accessed, while address 127 (7Fh) stores the lower byte. Address locations 0 - 124 are not used (Reserved - RO).

The upper 128 bytes of the I2C address space are mapped directly to the MDIO registers. The first two bytes in this range are mapped to the QT2022/32 memory register address defined by the values in I2C address locations 125 - 127 (above); address 128 is mapped to the upper byte of the register and address 129 is mapped to the lower byte. The following two bytes are mapped directly to the next register in the QT2022/32 register space. Similarly, each subsequent pair of bytes is mapped to the following QT2022/32 register. In this way, the I2C upper 128 bytes are mapped to 64 contiguous QT2022/32 memory registers. The memory mapping between the I2C address space and the MDIO registers is shown in Figure .

For example, if the MDIO address is set to Register 1.C000 (i.e. Device 1, Address C000h), then the I2C address space 128 - 255 will be mapped to the QT2022/32 register addresses in the range 1.C000h - 1.C063h.

Many of these memory address locations are not defined in the QT2022/32. Reads from these address locations will return 0; writes to these address locations will be ignored.

10.8.2 Reading and Writing Using the I2C Interface

To initiate read or write transactions to an MDIO register, the Device ID and Register Address must be set. Three I2C write commands must be performed to set these values in the correct memory locations 125-127 (see Table on page 95). Burst writing is supported.

I2C memory location 124 is the Command Status register. When there are simultaneous read requests to the MDIO registers from both the MDIO bus and the I2C bus (slave mode), access through the I2C interface may fail since MDIO bus access always has the highest priority. If a failure occurs, it will cause the Command Status bit 0 to be set to '1' (failed). To ensure read commands from the I2C bus are successful, always check the Command Status register after every read.

A similar case occurs when there are simultaneous write requests from the MDIO bus and I2C bus. If a failure occurs, it will cause the Command Status bit 1 to be set to '1' (failed). To ensure write commands from the I2C bus are successful, always check the Command Status register after every read.

Once the Register address is fully defined, an I2C read command to any address in the range 128 - 255 will return the QT2022/32 register contents, according to the mapping in Table on page 95. For MDIO register read access, the lower byte of the MDIO register data is latched when the upper MDIO register data byte is read i.e. the contents of lower byte are stored until it is read. It is recommended that the upper byte be read first.

For MDIO write access, the MDIO register in the QT2022/32 will be updated after the lower byte of register data has been written to the I2C register space. This ensures that complete words which represent a single 16 bit MDIO register data value are kept intact. Write to the upper byte memory space first to a guarantee the proper value is set.

The slave address for I2C access is hard-wired as 0x7E. The MDIO registers can be accessed by either the MDIO bus or the I2C bus.



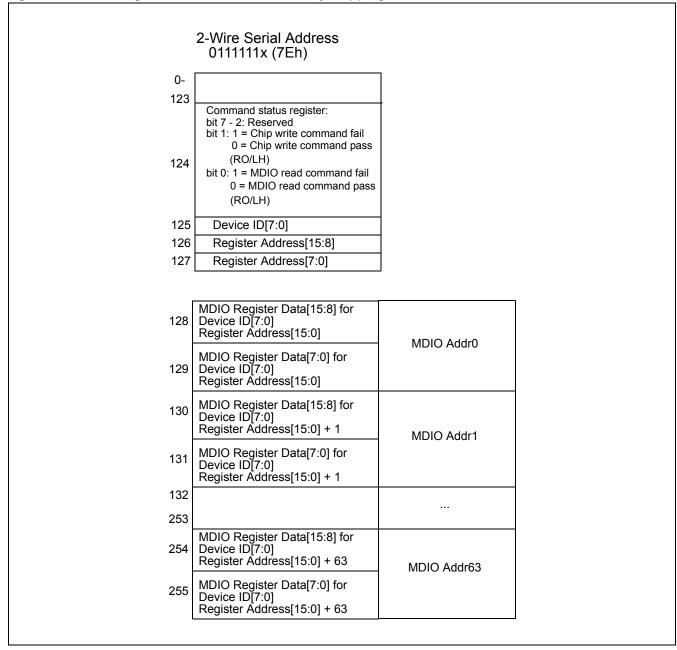


Figure 37: MDIO Register Indirect Access Memory Mapping for I2C Access

11 Diagnostic and Test Features

11.1 Loopback Modes

Loopback name	Loopback Enable	Loopback Data Override	TXOUT output when data override=0 (default) ¹	TXOUT output when data override=1
PMA system loopback	1.0.0	1.C001h.15	all 0's (null)	transmit data
WIS system loopback (QT2032 only) ²	2.0.14	2.C001h.4	0F0F	transmit data
PCS system loopback	3.0.14	3.C000h.5	00FF	transmit data
XGXS system loopback	4.C000h.14	4.C000h.15	all 1's	transmit data
XGXS analog loopback	4.C007h.3:0	n/a	n/a	transmit data

Table 39: System Loopback Modes and MDIO Control Registers

1. The Loopback Data Override bits are set to 0 by default for all system loopbacks

2. The WIS system loopback feature is available on the QT2032 product only.

When in any system (PMA, PCS or XGXS system) loopback mode the QT2022/32 shall accept data from the transmit path and return it on the receive path. During PMA system loopback, the PMA transmit data will default to an all 0's pattern at TXOUTP/N. During XGXS system loopback, the PMA transmit data will default to an all 1's pattern at TXOUTP/N. In PCS or WIS system loopback mode a continuous pattern of 0x00FF will be output. In all modes, transmit data will be output if the associated 'loopback data out enable bit' is set high for the enabled loopback mode.

 Table 40:
 Network Loopback Modes and MDIO Control Registers

Loopback name	Loopback Enable	Loopback Data Override	RxXAUI output when data override=0	RxXAUI output when data override=1 (default) ¹
XGXS network loopback	4.0.14	4.C000h.13	all 0's	received data
PMA network loopback	1.C001h.4	1.C001h.5	idle at RxXAUI	received data

1. The Loopback Data Override bits are set to 1 by default for all network loopbacks

When in PMA network loopback mode, the recovered and retimed 10Gb/s data is looped to the transmitter output driver and output at TXOUTP/N. The clock output at TXPLLOUTP/N is still synchronous to the Tx path PLL 10GHz clock. To lock the Tx PLL to the receive data, use line timing mode. The receive path XAUI output data will be received data. XAUI idle codes will be output instead of the received data if the 'network loopback data out enable bit' is set high. In IEEE 802.3 standard XGXS network loopback the received data is looped back to the transmit path in the XAUI block.

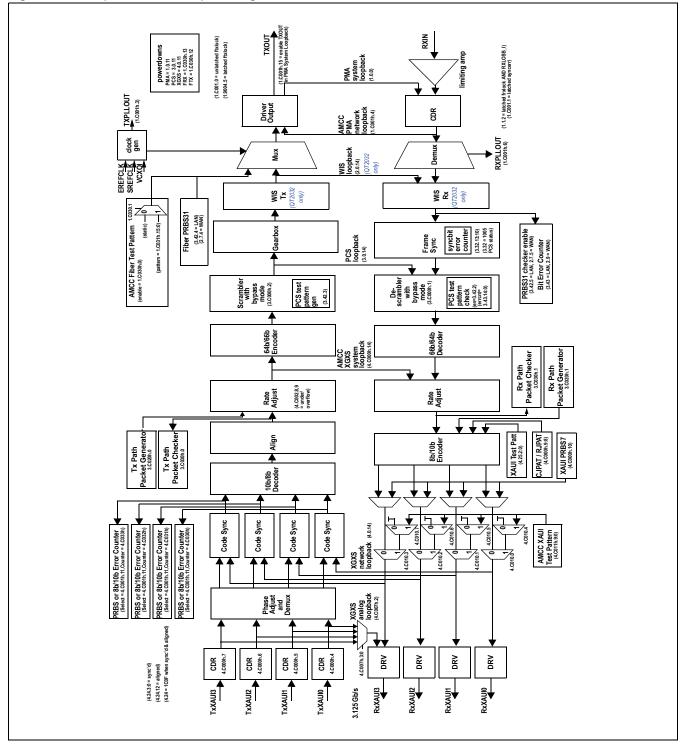
The chip will not prevent multiple loopbacks from being enabled but the result is undefined and these modes are not supported.

11.1.1 XGXS Analog Loopback

The signal from any of the four TxXAUI CDRs can be looped back to the RxXAUI3 output by setting 4.C007h.2=1 and selecting the lane via 4.C007h.1:0. By default, the recovered data is output. The recovered clock can be output instead by setting 4.C007h.3=1.



To use this feature, ensure that RxXAUI_SEL = 0. If RxXAUI_SEL = 1 while the analog loopback feature is enabled, the RxXAUI3 output may have additional jitter.





11.2 XAUI Interface Test Features

11.2.1 XAUI PRBS7 Pattern Generator

XAUI PRBS, or XAUI BIST, test mode enables the 2^{7} -1 PRBS generator on the XAUI outputs on each XAUI input lane. The PRBS pattern is generated using the polynomial $1+x^{6}+x^{7}$. The generator is enabled by setting MDIO register bit 4.C000h.10 to a 1. This will cause a PRBS7 pattern to be output on all 4 XAUI output lanes simultaneously.

11.2.2 XAUI PRBS7 Pattern Checker

For test purposes, there is a PRBS7 pattern checker for each XAUI input lane. The PRBS7 pattern checker expects data generated using the polynomial 1+x6+x7. The checker is enabled through the MDIO register bit 4.C000h.11. If a pattern error is detected the error flag, MDIO register 4.C001h.3:0, is set for that lane. The error flag will remain set until cleared by an MDIO read. An 8 bit error counter will also count the total number of errors for each lane. The error counters are bits 7:0 of registers 4.C030h - 4.C033h for Lane0 - Lane3 respectively. Each register is a read-only, non-rollover counter that is cleared upon read.

If any of the XAUI input CDRs are not in lock, the PRBS7 pattern checkers will not operate properly for all 4 lanes - errors will be reported on all lanes. You may check the lock condition for each lane in MDIO register bits 4.C000h.7:4. To avoid this issue, please override the XAUI lane loss-of-lock indication by setting MDIO register bits 4.C020h.11:8 to 1 (for lane3 to lane0 respectively).

11.2.3 XAUI Jitter Test Pattern Generator

There are 3 patterns defined for XAUI interface jitter testing: low frequency (LF), high frequency (HF) and mixed frequency (MF) test patterns.

		MDIO register		
Pattern Name	Repeated Bit Pattern - each lane	Test Pattern Select 4.25.1:0	Test pattern enable 4.25.2	
high frequency	10	00	1	
low frequency	1111100000	01	1	
mixed frequency	11111010110000010100	10	1	

Table 41: XAUI Jitter Test Pattern Generator Enable

11.2.4 XAUI CRPAT Test Pattern Generator

The continuous random test pattern (CRPAT) consists of a continuous stream of identical packets separated by minimum IPG. The contents of the packets are as specified in IEEE 802.3 Section 48A.4. The test pattern provides a broad spectral content and minimal peaking. The CRPAT generator is enabled by writing a 1 to MDIO register 4.C000h.9.

11.2.5 XAUI CJPAT Test Pattern Generator

The continuous jitter test pattern (CJPAT) alternates repeating low transition density patterns with repeating high transition density patterns. This will expose the receiver's CDR to large instantaneous phase jumps. The detailed description of CJPAT is found in IEEE 802.3 Clause 48A.5. The CJPAT generator is enabled by writing a 1 to MDIO register 4.C000h.8.



11.2.6 8b/10b Error Checkers

For each lane, there is a dedicated 8 bit error counter for checking 8b/10b coding errors on the XAUI input. Each counter works independently. The error counters are located in bits 7:0 of registers 4.C030h - 4.C033h for Lane0 - Lane3 respectively. Each register is a read-only, non-rollover counter that is cleared upon read. This counter should be used when testing with CRPAT and CJPAT.

11.2.7 AMCC XAUI Test Pattern Generator

The XAUI output can be configured to transmit a user-defined 10 bit code word or, alternatively, a static output (no transitions). Transmission of these test patterns is enabled on a per-lane basis by setting MDIO register bits 4.C010h.3:0 to 1 for Lane3 to Lane0 respectively. The desired pattern is selected on a per-lane basis by setting MDIO register bits 4.C010h.7:4, where a 1 selects a user-defined pattern and a 0 selects the static output.

The 10-bit user defined test pattern is set in MDIO register bits 4.C011h.9:0. When enabled for a given lane, the programmed pattern will be continuously transmitted on the RxXAUI output.

11.3 PCS Test Features

11.3.1 Scrambler/Descrambler Bypass Modes

The scrambler can be bypassed by setting the MDIO register bit 3.C000h.2. The descrambler can be bypassed by setting the MDIO register bit 3.C000h.1.

11.3.2 PCS Jitter Test Pattern Generator

Specific IEEE-standard test patterns are enabled through the MDIO interface by setting the value of bit 3.42.3 (3.2Ah.3), as described in IEEE 802.3-2005 Clause 49.2.8.

By setting MDIO register 3.42.1 (3.2Ah.2) to 1, the output pattern will be a square wave of 8 high cycles followed by 8 low cycles.

If MDIO register 3.42.1 is set to 0, a programmable pseudo-random pattern is generated at the serial output. This pattern is generated by the scrambler (in figure 2 on page 21) using seeds stored in the MDIO registers 3.34 to 3.41. The scrambler is loaded with a 58-bit seeds at the start of every 128 blocks in the following order: seed A, seed A Inverted, seed B, seed B Inverted. The data input to the scrambler is set to either all zeros or local fault (LF) via MDIO register 3.42.0. A control sync header of 01 is used and the payload is the pseudo random data output from the scrambler.

11.3.3 PCS Jitter Test Pattern Checker

The PCS test pattern checker in the descrambler is enabled via MDIO bit 3.42.2 (3.2Ah.2). When the descrambler output matches the data pattern, or its inverse, a match is declared. Since the descrambler is free running and the scrambler is being loaded with a new seed every 128 blocks, a mismatch will be detected once every 128 blocks. This first mismatch does not increment the counter.

A 16-bit, non-rollover counter, test_pattern_error_count, counts the errors and is reflected in MDIO register 3.43 (3.2Bh). This is a non-rollover counter that is reset when read.

11.4 Serial Interface Test Features

11.4.1 PRBS31 Test Pattern Generator

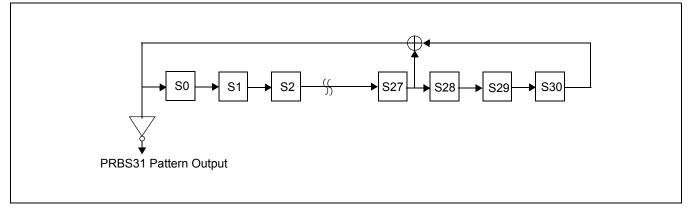
A pseudo-random pattern generator feature is available to test the 10Gb/s serial transmitter. When the PRBS31 pattern generator is enabled by setting MDIO bit 3.42.4 (3.2Ah.4), a 2^{31} -1 pseudorandom pattern is output at TXOUT. The polynomial -(1+ x^{28} + x^{31}) is used to generate the pattern. This polynomial produces the same output as the IEEE standard algorithm shown in Figure 39 (see IEEE 802.3-2005 Clause 49.2.8). The initial seed of this algorithm will not be all zeros.

Note that the PRBS31 output pattern is inverted from the standard pattern generated by most test equipment. To invert the pattern from the QT2022/32, set the TXOUT_SEL pin high. Alternatively, configure the test equipment to accept the inverted pattern.

In the QT2032 product, this generator is available in both LAN and WAN operation. It is controlled by a different bit depending on the mode. The control and counter registers are listed in Table 42 on page 101.

If both the jitter test pattern and the PRBS31 test pattern are enabled, the PRBS31 mode will be chosen (LAN mode).

Figure 39: PRBS31 Pattern Generator



11.4.2 PRBS31 Test Pattern Checker

A pseudo-random pattern error counter feature is available to test the 10Gb/s serial receiver. When the PRBS31 error detector is enabled a 2³¹-1 PRBS pattern is expected on the receive path input. The PRBS31 pattern checker is self-synchronizing and produces the same result as the IEEE standard algorithm shown in Figure 40 (see IEEE 802.3-2005 Clause 49.2.12). Pattern errors are counted by an 16-bit counter and can be observed at MDIO register 3.43 (3.2Bh), which is a non-rollover counter that is cleared on read. When an isolated bit error occurs, it will cause the PRBS31 pattern error output to go high 3 times, once when it is received and once when it is at each tap. Thus, each isolated error will be counted 3 times in the counter.

Note that the expected PRBS31 pattern is inverted from the standard pattern generated by most test equipment. To invert the input to the QT2022/32, set the RXIN_SEL pin high (or set MDIO register bit 1.D003h.4 to 1 to invert the RXIN_SEL pad polarity). Alternatively, configure the test equipment to transmit the inverted pattern. The built-in pattern checker is compatible with the built-in generator with no inversion applied to either pattern.

In the QT2032, this counter is available in both LAN and WAN operation. It is controlled by a different bit depending on the mode. The same 16-bit counter register is used in both modes. The control and counter registers are listed in Table 42 on page 101.





If the CDR is not in lock the PRBS31 error counter will read AAAAh. The PRBS31 pattern generator and checker can be used in conjunction with the PMA system loopback.

Figure 40: PRBS31 Pattern Checker

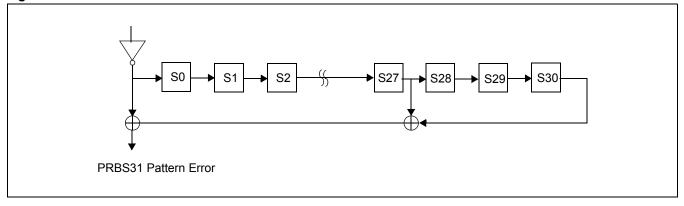


Table 42: PRBS31 Generator and Checker Control

ltem	LAN mode (QT2022 and QT2032)	WAN Mode (QT2032 only)	Note
PRBS31 Generator Control	Register bit 3.42.4 (3.2Ah.4)	Register bit 2.7.4	0 = disabled (default) 1 = enabled
PRBS31 Checker Control	Register bit 3.42.5 (3.2Ah.5)	Register bit 2.7.5	0 = disabled (default) 1 = enabled
16-bit Error Counter	3.43 (3.2B)	2.9	16-bit, non-rollover (RO) cleared on read

11.4.3 Timed BER Test

A BER test can be performed on the RXIN receive signal. The 2³¹-1 PRBS test pattern checker is used to count detected errors within a specified time period. The time period in seconds is set by the value in MDIO register 3.C001h. The errors are reported in the MDIO test pattern error counter register, 3.34. Once the PRBS test pattern checker has been enabled, the BER test is enabled by writing a 1 to MDIO register 3.C000h.12. The 'BER in progress' bit, MDIO 3.C000h.14, will be 1 while the BER test is in progress. The completion of the BER test is indicated by the 'BER DONE' bit, 3.C000h.15, going high. At this point the error count can be read from register 3.34. The error count should not be read until the completion of the BER test, as this will clear the error counter and give incorrect results.

Step #	Step
1	Write 1 to MDIO 3.42.5 in AN mode (2.7.5 in WAN mode - QT2032 only) This enables the PRBS 2 -1 receive test pattern checker
2	Write desired length of BER test in seconds to 3.C001h.15:0
3	write 1 to 3.C000h.12 (this register bit must have been 0 previously) This clears the error count and starts the BER test running
4	Check the BER in progress flag, 3.C000h.14 to see when it changes from1 to 0 to indicate the BER test is complete OR Check the BER test complete flag, 3.C000h.15 to see when it is 1
5	Read the error count register, (3.43 in LAN mode, 2.9 in WAN mode)
6	Write a 0 to MDIO 3.C00h.12 to disable the BER test
36	Repeat steps 3 to 6 for multiple BER tests

Table 43: BER Test Procedure

11.4.4 AMCC Fiber Test Pattern Generator

The fiber output can be configured to transmit a user-defined 16 bit code word or, alternatively, a static output (no transitions). The 16-bit user defined test pattern is set in MDIO register 1.C031. When enabled, the programmed pattern will be continuously transmitted on the TXOUT output.

Transmission of the test pattern is enabled by setting MDIO register bit 1.C030h.0 to 1. The desired pattern is selected by setting MDIO register bit 1.C030h.1, where a 1 selects the user-defined pattern and a 0 selects the static output.

11.5 WIS Test Features (QT2032 only)

The WIS implements three serial test patterns for testing the PMA and PMD layers. These include a square wave test pattern, an unframed PRBS31 pattern, and a framed mixed frequency test pattern. These patterns are implemented in accordance with IEEE 802.3 Clause 50.3.8. The PRBS31 pattern generator and checker are described in Section 11.4.



11.5.1 WIS Square Wave Test Pattern

When the WIS square wave test pattern is enabled, the WIS Transmit block will output a continuous square wave pattern to the PMA. The square wave pattern is 00FFh (8 consecutive 1s followed by 8 consecutive 0s). Transmission is enabled by first setting the 'transmit test pattern enable' bit 2.7.1 to a 1. Then the square wave pattern is chosen by setting the 'test pattern select' bit 2.7.3 to 1.

There is no pattern checker feature on the receive path for the square wave test pattern.

11.5.2 WIS Mixed Frequency Test Pattern

The mixed frequency test pattern consists of a framed WIS signal with a PRBS23 payload, plus a CID section (consecutive identical digits). The PRBS23 pattern is substituted for the payload data that would normally be sent in the WIS frame. The CID section is selected to stress the lock range of the receiver circuitry, and is placed in the Z0 octet locations as these are not scrambled. The complete Test Signal Structure of the signal is described in IEEE 802.3 Clause 50.3.8.3.

When transmission of the mixed frequency test pattern is enabled, the WIS Transmit block will continuously output the Test Signal Structure to the PMA. Transmission is enabled by first setting the 'transmit test pattern enable' bit 2.7.1 to a 1. Then the mixed frequency test pattern is chosen by setting the 'test pattern select' bit 2.7.3 to 0.

When the mixed frequency test pattern is received at the fiber input, errors are detected using the Line BIP Error Counter registers 2.57 and 2.58 (2.39h and 2.3Ah), the Path Block Error Counter Register 2.59 (2.3Bh) and the Section BIP Error Counter Register 2.60 (2.3Ch).

The 'receive test pattern enable' bit 2.7.2 does not need to be set to 1 to enable error checking.

11.6 Ethernet Packet Generator/Checker (QT2032 and QT2022)

The QT2022/32 has the ability to generate data packets for test purposes. There is one such generator in the TX path and one in the RX path. To complement the generators, a packet checker is placed in the TX path and another one in the RX path. See figure 38 on page 97.

11.6.1 General Characteristics

- The packets generated (for Data Fixed Type and Data Incremental Type) are like follows: //S//, //Preamble// , //D//, ..., //D//, //T//. These packets are not true ethernet packets since they do not include a CRC field, among other things. However, they are sufficient to test the logic implemented in the QT2022/32.
- Both the TX and RX packet generators share the same control registers with the exception of the enable bit
- (reg 3.C020h bits 0 and 1). Thus, they will both output the same type of packets when enabled.
- Both the TX and RX packet checkers share the same control registers. Thus, if both checkers are activated, they will both check for the same type of packets.
- Both the TX and RX packet checkers will be enabled automatically when either packet generator is enabled.
- If neither packet generator is enabled, the packet checkers can be turned on using the enable bits in reg 3.C030h bits 0 and 1. If either bit is set to '1', both TX and RX packet checkers will be enabled.
- Since the generators and the checkers have separate controls, it is possible to have the generators send data other than that expected by the checkers. Intentionally creating error conditions in the checker can be useful in debugging a chip.



11.6.2 Packet Generator Characteristics

- The generator can output complete packets with either fixed or incremental data. This is called the packet type feature and is controlled via register 3.C020h.5:4.
- When fixed data is chosen, the contents of registers 3.C021h and 3.C022h are transmitted inside the packet. These register value contents are repeated for the length of the packet. It can also output the contents of registers 3.C021h and 3.C022h without adding //S// or //T// columns. This can be useful to send certain reserved control codes, for example.
- When incremental data is chosen, the data byte values begin at 00 and bitwise increment to stuff the data field in a rollover fashion. The data is filled at the 8-bit level.
- The generator can output data continuously (Continuous Mode) or in bursts (Burst Mode). The generator can also be put in Idle Mode. In this case, only XGMII idles will be output by the generator.
- Once all the packets in a burst are sent, the generator will send only idles. To re-send another burst, the generator must be taken out of Burst Mode and into Idle Mode. When it is put back into Burst Mode, another burst of packets will be sent.
- Packet length is controlled by register 3.C025h and the IPG is controlled by register 3.C026h.
- Note: Asserting reset will not resend another burst. Doing so would clear all the generator control registers to their default values.

11.6.3 Packet Checker Characteristics

- The checker can expect complete packets with either fixed or incremental data. This is called the packet type feature. It is controlled via register 3.C030h.[5:4].
- When fixed data is chosen, the contents of registers 3.C031h and 3.C032h are expected inside the packet. It can also expect the contents of registers 3.C031h and 3.C032h without //S// or //T// columns. This can be quite useful when testing certain reserved control codes, for example.
- When incremental data is chosen, the expected data byte values begin at 00 and bitwise increment within the data field in a rollover fashion. The data is interpreted at the 8-bit level.
- Expected packet length and IPG is not programmed for the checkers.

11.6.4 Example Uses

Basic use, both generators on with Burst Mode and both checkers on

- 1. Connect the TX XAUI lanes to the RX XAUI lanes.
- 2. Connect the TX FIBER to the RX FIBER.
- 3. Write a random value to registers 3.C031h and 3.C032h. The 32 incoming XGMII data bits will be compared to those registers.
- 4. Write 4'h0 to register 3.C033h.[3:0], since we will be comparing on data octets (as opposed to reserved control codes).
- 5. Activate both packet checkers and program them to expect fixed data. Do this by writing 16'h0003 to register 3.C030h.
- 6. Read all error/status registers to clear. They are registers 3.C034h, 3.C035h, 3.C036h and 3.C037h.
- 7. Write the same values contained in registers 3.C031h and 3.C032h in registers 3.C021h and 3.C022h.
- 8. Set the burst size to a non-zero value by writing to the register 3.C024h. If the burst size is set to zero, no packets will be sent by the generator (only idles).
- 9. Set the packet size to a non-zero value by writing to the register 3.C025h.
- 10. Set the IPG size to a non-zero value by writing to the register 3.C026h. Although it is allowed to write zero to that register, the result would be back-to-back packets without any IPG.



- 11. Activate both generators. Set them to Burst Mode and Fixed Data Type. Do this by writing 16'h0103 to register 3.C020h.
- 12. Wait sufficiently long to receive all packets within one burst. Calculate the required delay based on packet length, IPG and packet count.
- 13. Read the RX and TX error counters (reg 3.C034h and 3.C036h). They will read all zeroes.
- 14. Read the RX and TX pkt counters (reg 3.C035h and reg 3.C037h). They should show the same value as reg 3.C024h.

To send a second burst:

- 1. Set the TX and RX generators to Idle Mode. Do this by writing 16'h0003 to reg 3.C020h.
- 2. Read all error/status registers to clear them. They are registers 3.C034h, 3.C035h, 3.C036h and 3.C037h.
- 3. Repeat steps 11 through 14.

11.6.5 Purposely creating errors

- 1. Connect the TX XAUI lanes to the RX XAUI lanes.
- 2. Connect the TX FIBER to the RX FIBER.
- 3. Write a random value to registers 3.C031h and 3.C032h. The 32 incoming XGMII data bits will be compared to those registers.
- 4. Write 4'h0 to register 3.C033h.3:0, since we will be comparing on data octets (as opposed to reserved control codes).
- 5. Activate both packet checkers and program them to expect fixed data. Do this by writing 16'h0003 to register 3.C030h.
- 6. Read all error/status registers to clear. They are registers 3.C034h, 3.C035h, 3.C036h and 3.C037h.
- 7. Write in registers 3.C021h and 3.C022h values that are different from the values in registers 3.C031h and 3.C032h.
- 8. Write 4'h0 to reg 3.C023h.3:0.
- 9. Set the burst size to a non-zero value by writing to the register 3.C024h. If the burst size is set to zero, no packets will be sent by the generator (only idles).
- 10. Set the packet size to a non-zero value by writing to the register 3.C025h.
- 11. Set the IPG size to a non-zero value by writing to the register 3.C026h. Although it is legal to write zero to that register, the result would be back-to-back packets without any IPG.
- 12. Activate both generators. Set them to Burst Mode and Fixed Data Type. Do this by writing 16'h0103 to register 3.C020h.
- 13. Wait sufficiently long to receive all packets within one burst. Calculate the required delay based on packet length, IPG and packet count.
- 14. Read the RX and TX error counters (reg 3.C034h and 3.C036h). They will read non-zero values.
- 15. Read the RX and TX pkt counters (reg 3.C035h and reg 3.C037h). They should show the same value as reg 3.C024h.

11.7 Disabling the Idle Decode Process

The XGXS block of the chip converts the incoming XAUI signal from a 10 bit-encoded signal to an 8-bit encoded signal. The chip also decodes all the K28.0, K28.3 and K28.5 idle codes to the same 8-bit code, /l/ = 0x07, as specified in IEEE 802.3-2005 Table 48-3. These idle codes will typically be transmitted to a far-end SerDes (such as another QT2022/32). The far-end SerDes will convert the 8-bit idle codes into 10-bit encoded K28.0, K28.3 and K28.5 codes, following the rules specified by the idle randomization process (as per IEEE 802.3-2005 Clause 48.2.4.2). The original idle code order will not be preserved.

The XGXS idle decode process can be disabled by setting MDIO register bit 4.C007h.8 = 1. In this test mode, the K28.0, K28.3 and K28.5 codes are decoded to their native 8-bit code as given in IEEE 802.3-2005 Table 49-1 (K28.0 -> 0x1C, K28.3 -> 0x7C, K28.5 -> 0xBC). There will be no idle codes, 0x07, generated in the signal.

When this modified signal is passed through the receive path of the QT2022/32, the idle codes will pass through the chip unmodified. The idle randomization process will not operate on them. The 8b/10b encoder will convert them to their original 10-bit code words, thereby preserving the original order of the signal.

This feature is useful when testing the XAUI interface using an external pattern generator & error detector that is not protocol-aware and cannot handle the idle randomization normally. Note that the receive 8b/10b encoder process will choose one of two running disparities, depending on the signal. If the disparity does not match that expected by the external error detector, errors will be reported. Therefore, it is important to check for both possible disparities. For more information on disparity, consult IEEE-802.3-2002 Clause 36.2.4.4; also review Clause 36.2.4.7.1 for 8b/10b valid code-groups. For information on disparity as it relates to CJPAT, consult IEEE 802.3-2005 Clause 48A.5.1.

When the idle decode process is disabled, the rate compensation capability of the chip will fail to function properly. It fails because the rate compensation block operates on standard 8-bit idle codes, 0x07, which are absent from the signal. Therefore, this feature should not be used during normal operation. To use this feature properly, supply a reference clock to the chip that is synchronous to the incoming signal. If an asynchronous reference clock is supplied and the chip must perform a rate compensation, error codes will be generated.

This feature does not work on the QT2032 when operating in WAN mode.

11.8 Test Access Port and Boundary Scan

The QT2022/32 has a test-access port (TAP) and a boundary scan (BSCAN) chain compliant with IEEE standards 1149.1 and 1149.6 (JTAG).

11.8.1 BSCAN chain

The following pins are on the BSCAN chain:

- AC pins: all XAUI I/O
- DC pins: all low-speed digital I/O

The following pins are not in the BSCAN chain:

- all supplies and grounds
- all analog pins for external component connections (RXFP/N/C, TXFP/N/C, RXICXP/N, ITH_LOS, XBIAS, RxXLEVEL, TXLEVEL, RXIPUMP, TXIPUMP, PHASE_OFFSET)
- all lab test I/O (TxXMONCVP/N, RXPLLOUTP/N, TXPLLOUTP/N)
- all 10G I/O (RXINP/N, TXOUTP/N)



11.8.2 TAP Port

Table 44 lists the supported BSCAN instructions while Table 45 lists the unsupported BSCAN instructions..

Table 44:	Supported BSCAN Instructions
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BSCAN Instruction	Value	Description
BYPASS	5'b11111	bypasses the bscan register
EXTEST	5'b00000	DC test of external connectivity to I/O
IDCODE	5'b00001	allows reading the device ID register
SAMPLE/PRELOAD	5'b00010	captures and updates data
RUNBIST	5'b00011	runs BIST on internal memories
DEBUGBIST	5'b00100	debug mode of memory BIST
SCAN	5'b01001	SCAN test on digital core
EXTEST_TRAIN	5'b00110	AC test of external connectivity to I/O
EXTEST_PULSE	5'b00101	AC test of external connectivity to I/O

Table 45: Unsupported BSCAN Instructions

BSCAN Instruction	Description
CLAMP	allows outputs to be forced to specific states during BYPASS
HIGHZ	allows outputs to be forced into high-z state
INTEST	allows testing of internal circuitry using BSCAN chain
USERCODE	allows a user-programmable ID code

11.8.3 Device ID register

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Table 46: Device ID Register

Field	Value
Manufacturer's ID code (11bits)	11'b0101_0110100
Part-number code (16 bits)	16'h2032 (16'b0010_0000_0011_0010)
Version code (4 bits)	4'hA (4'b1010)

Pins on BSCAN Chain	BSCAN Order	BSCAN Cell Captures/Drives	Pins on BSCAN Chain	BSCAN Order	BSCAN Cell Captures/Drives
TDCC	67	Input	TxXAUI0P	33	Input
TDCC_CLK	66	Output	RxXAUI3	32	Output
MDC	65	Input	RxXAUI3	31	AC/DC Select
MDIO	64	Enable	RxXAUI2	30	Output
MDIO	63	Output	RxXAUI2	29	AC/DC Select
MDIO	62	Input	RxXAUI1	28	Output
LED3	61	Enable	RxXAUI1	27	AC/DC Select
LED3	60	Output	RxXAUI0	26	Output
LED3	59	Input	RxXAUI0	25	AC/DC Select
LED2	58	Enable	VCXOONLY	24	Input
LED2	57	Output	VCXOSEL622	23	Input
LED2	56	Input	TXON	22	Enable
LED1	55	Enable	TXON	21	Output
LED1	54	Output	TXON	20	Input
LED1	53	Input	VCXOB	19	Input
Internal cell	52	Hardwired low	LANMODE	18	Input
TxXAUI_SEL	51	Input	LTIMEOK	17	Output
TXOUT_SEL	50	Input	TXENABLE	16	Output
TXFAULT	49	Input	RXIN_SEL	15	Input
LEGACY	48	Input	RESETN	14	Input
LASI_INTB	47	Input	EEPROM_SDA	13	Enable
LASI	46	Output	EEPROM_SDA	12	Output
PRTAD4	45	Input	EEPROM_SDA	11	Input
PRTAD3	44	Input	EEPROM_SCL	10	Enable
PRTAD2	43	Input	EEPROM_SCL	9	Output
PRTAD1	42	Input	EEPROM_SCL	8	Input
PRTAD0	41	Input	XFP	7	Input
TxXAUI3N	40	Input	LOSOUTB	6	Input
TxXAUI3P	39	Input	RXLOSB_I	5	Input
TxXAUI2N	38	Input	REFSEL622	4	Input
TxXAUI2P	37	Input	RDCC_CLK	3	Output
TxXAUI1N	36	Input	RDCC	2	Output
TxXAUI1P	35	Input	EEPROM_PROT	1	Input
TxXAUI0N	34	Input	RxXAUI_SEL	0	Input

 Table 47:
 BSCAN Chain Implementation

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12 Extended Link Monitoring Feature (QT2032 and QT2022)

12.1 Overview

The QT2022/32 includes an optional Extended Link Monitoring feature. This feature allows PHY level diagnostics of the link using the inter-packet gap space between traffic data. The PHY devices at both ends of the link must support this feature to take advantage of it. This feature has no effect on traffic, nor does it affect devices that do not support the feature. It includes the following capabilities:

- Remote PHY Error Monitoring
- Remote PHY Register Read/Write Capability.

Extended Link Monitoring is performed between two devices connected on a fiber optic link by means of a query message in each direction.

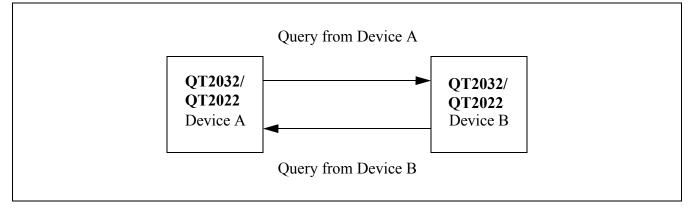


Figure 41: Schematic Representation of Extended Link Monitoring Transaction Between Two PHYs

By default, query generation and query response is disabled. A device will generate query messages on its Tx fiber output when its query generation algorithm is enabled by setting MDIO Register bit 3.CC00h.0 to '1'. The remote device will respond to query messages if its query response algorithm is enabled by setting MDIO register bit 3.CC00h.1 to '1'. If set properly, the devices will communicate and establish a successful link. Once a successful link is established, the extended link monitoring features may be used.

Extended Link Monitoring will work in PCS and PMA loopback mode for debug purposes.

- No /A/ codes are used as part of the Extended Link Monitoring procedure as these may cause deskew protocol violations on XAUI.
- No incomplete ||R|| or ||K|| ordered sets appear on the XAUI bus as these have a likelihood of being correctly identified as idle columns.

12.2 Query message format

In order to identify a remote device, the local device must initiate a series of "queries". These are specially formatted PCS-R 66B code blocks which can be detected by and responded to by the remote device. The query block (\\P\) consists of an all-control 66B block with the K28.5 8B/10B code used in payload $C_4C_5C_6C_7$ positions. Idle codes are used in the remaining $C_0C_1C_2C_3$ control code positions.

Table 48: AppliedMicro Query Block Format

Input Data	Sync bits				Blo	ock Paylo	ad			
$C_0C_1C_2C_3/C_4C_5C_6C_7$	10	8'h1e	7'h00	7'h00	7'h00	7'h00	7'h55	7'h55	7'h55	7'h55

Upon enabling of query generation on a device it will send a series of 16 \\P\\ blocks through its TX PCS. It will also check for query responses through its RX PCS. This process will continue until either the device is disabled via the MDIO or the 16 queries have been successfully sent. A count of transmitted \\P\\ blocks is held in a non-rollover MDIO counter at address 3.CC02h.7:0 that is cleared on read.

A \\P\\ can be generated by the TX PCS only after I_{num} (= 16) idle blocks have been transmitted. Therefore the data stream might look as follows -

/Start / Data / Data / / Data / Terminate / Idle / I_{num} \\P\\ / Idle / Start / Data / / Data / Terminate / Idle /I_{num} ... / Start / Data / Data / Terminate /

The RX fiber input must receive a total of 8 queries with an idle gap of < 32 blocks before identifying the remote PHY as AMCC. The count of \\P\\ blocks received is held in a non-rollover MDIO counter cleared on a read. The query frames are decoded and passed on to the XGXS unmodified. All PHY management traffic is removed and idles are substituted.

The Extended Link Monitoring Status 1 register indicates the status of the Extended Link Monitoring and contains a Query_Successful read only flag (3.CC01h).

The protocol supports the case where Extended Link Monitoring is enabled simultaneously on both devices.

12.3 Messaging

A remote link monitoring message consists of a AMCC Start block, data blocks and a AMCC Terminate block. The Start block and Terminate block contents define the feature being used. Currently, there are only two feature supported - Remote PHY Error Monitoring and Remote PHY Register Read/Write.

12.3.1 AppliedMicro Start Format

The Start consists of an all control 66B block with the K28.0 8B/10B code used in payload C₄ position. Idles must be used in the remaining $C_0C_1C_2C_3$ control code positions, along with feature specific codes in $C_5C_6C_7$.

Input Data	Sync bits				В	lock Pay	load			
C ₀ C ₁ C ₂ C ₃ / C ₄ C ₅ C ₆ C ₇	10	8'h1e	7'h00	7'h00	7'h00	7'h00	7'h69	FCode	FCode	FCode

Table 49: AppliedMicro Start Block Format





12.3.2 Terminate Format

The Terminate consists of an all control 66B block with the K28.5 8B/10B code used in payload C₄ position. Idles must be used in the remaining $C_0C_1C_2C_3$ control code positions, along with feature specific codes in $C_5C_6C_7$.

Table 50: AppliedMicro Terminate Block Format

Input Data	Sync bits				В	lock Pay	load			
$C_0C_1C_2C_3/C_4C_5C_6C_7$	10	8'h1e	7'h00	7'h00	7'h00	7'h00	7'h70	FCode	FCode	FCode

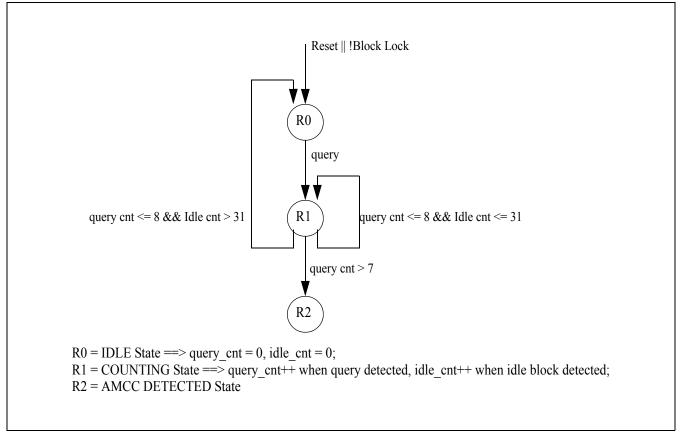
12.3.3 FCode Values

FCode Values will be one of the following: '3c' (reserved0), 'dc' (reserved4) or 'f7' (reserved5). Every feature is defined by its own unique combination of 3 FCode values.

All message data between a Start and Terminate should have the sync bits set to indicate a control block. All messages must have a size of <512 blocks.

12.4 Extended Link Monitoring State Diagram

Figure 42: Extended Link Monitoring State Diagram





12.5 Transmit State Diagram

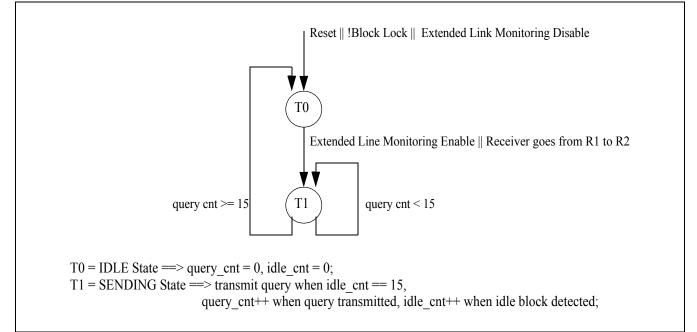


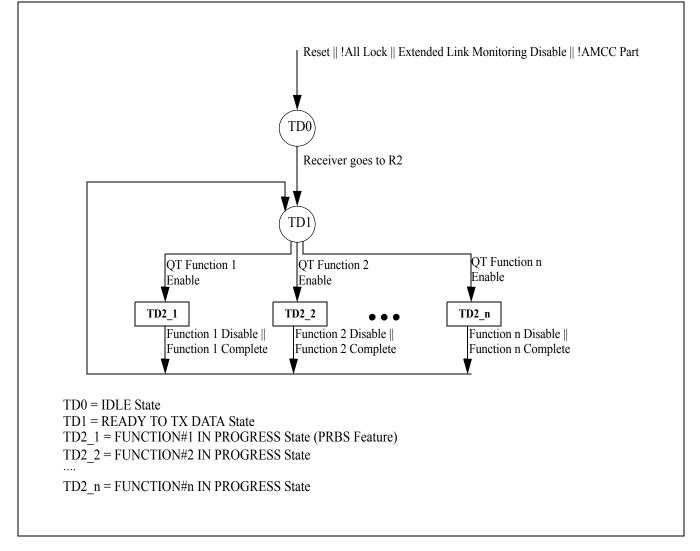
Figure 43: Extended Link Monitoring Transmit State Diagram

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12.6 Receive State Diagram





12.7 RMDIO (Remote MDIO Access) Extended Link Monitoring

The RMDIO Extended Link Monitoring feature allows the local device on a fiber link to remotely access the MDIO register contents of the device at the far end of the link. Both read and write transactions to the remote PHY register space are supported.

Once a RMDIO read request is initiated, Device A will send a RMDIO request message, Device B will then fetch the specified MDIO register content and insert it inside a RMDIO response message. Device A will then extract the data from the response message and place the result in Register 3.CC0Ch.

To perform a RMDIO read transaction, the user needs to:

- Enable the RMDIO feature for transmission in the local PHY by writing a 1 to Register bit 3.CC08.0.
- Enable the RMDIO feature for reception in the remote PHY by writing a 1 to Register bit 3.CC08.1. (This requires local access to the remote PHY.)
- Specify the device and register address he wants to remotely access. The device address is specified in MDIO register field 3.CC09h.5:0 and the register address is specified in MDIO register 3.CC0Ah.
- Perform a remote read transaction by writing a 1 to Register 3.CC08h.2. This triggers a RMDIO read request.
- Read the RMDIO Status register 3.CC0Bh to check the "Read Request Sent" flag to see if the command was sent (bit0) and the "Read Response Received" flag to see if the response was received (bit2). These flags are latching bits that are cleared on read.
- After the "Read Response Received" flag is set, the register content of the remote PHY will then be stored in register 3.CC0Ch of the local PHY.
- To perform further RMDIO reads, the "RMDIO Read Request" bit in Register 3.CC08h (bit2) must first be reset to '0'.

To perform a RMDIO write, the user needs to:

- Enable the RMDIO feature for transmission in the local PHY by writing a 1 to Register bit 3.CC08.0.
- Enable the RMDIO feature for reception in the remote PHY by writing a 1 to Register bit 3.CC08.1. (This requires local access to the remote PHY.)
- Specify the device and register address he wants to remotely access. The device address is specified in MDIO register field 3.CC09h.5:0 and the register address is specified in MDIO register 3.CC0Ah.
- Specify the 16-bit value to be written to the remote PHY. This data is stored in Register 3.CC0Eh.
- To perform a remote write transaction by writing a 1 to Register 3.CC08h.3. This triggers a RMDIO write request.
- Read the RMDIO Status register 3.CC0Bh to check the "Write Request Sent" flag to see if the command was sent (bit1) and the "Write Response Received" flag to see if the response was received (bit3). These flags are latching bits that are cleared on read.
- To perform further RMDIO writes, the "RMDIO Write Request" bit in Register 3.CC08h (bit3) must first be reset to '0'.

NOTE: The user is responsible to check the status bit to make sure that the current transaction is complete before attempting a new one. If this rule is not followed, the second transaction might be ignored. As well, there is no builtin mechanism to handle the loss of RMDIO request or response messages. It is up to the user to monitor the status bits and re-initiate a new transaction if the previous one failed (i.e. user specified time-out).

The RMDIO write transaction is password protected to prevent accidentally modifying register contents. The password is stored in Register 3.CC0Fh. The correct password must be written to this register to enable RMDIO writes. Please contact AMCC for further information.

The RMDIO Read/Write Feature has precedence over the PRBS feature. If a RMDIO read/write transaction is initiated while the PRBS feature is turned on, the PRBS test will be automatically interrupted and then turned on again once the read/write transaction is complete. The RMDIO read/write request and response messages will get introduced in the IPG stream at the next possibility (3 Idle blocks required).

The RMDIO Message format is composed of a QSTART, followed by a RMDIO Data Block and terminated with a QTERM.

Table 51: RMDIO START Block Format

Input D	ata	Sync bits				В	lock Pay	load			
C ₀ C ₁ C ₂ C ₄ C ₅ C ₆		10	8'h1e	7'h00	7'h00	7'h00	7'h00	7'h69	7'h78	7'h66	7'h33

Table 52: RMDIO TERM Block Format

Input Data	Sync bits				В	lock Pay	load			
C ₀ C ₁ C ₂ C ₃ / C ₄ C ₅ C ₆ C ₇	10	8'h1e	7'h00	7'h00	7'h00	7'h00	7'h70	7'h78	7'h66	7'h33

Table 53: RMDIO Data Block Format

Input Data	Sync bits			Block Payload		
D ₀ D ₁ D ₂ D ₃ / D ₄ D ₅ D ₆ D ₇	01	Ctrl/Stat[7:0]	Device[7:0]	Reg Addr[15:0]	Data [15:0]	Rsvd[15:0]

Ctrl/Stat field:

- bit [0] Read/Write Request (read = 1, write = 0)
- bit [6:1] Reserved
- bit [7] Response bit (request = 0, response = 1)

Device Address field:

- bit [5:0] Device Address (valid only for request all 0s for response)
- bit [7:6] Reserved

Register Address field:

• bit [15:0] - Register Address (valid only for request - all 0s for response)

Data Field:

• bit [15:0] - MDIO Data (valid only for response - all 0s for request)

12.8 PRBS Performance Monitoring

The Extended Link Monitoring feature includes the capability to monitor link quality. This is achieved by generating and checking special pseudo-random 66b blocks in the IPG. The pseudo-random block consists of a 64b word plus 2 sync bits. The 64b word is composed of either all 1s or all 0s which is then scrambled before transmission, using the scrambling algorithm presented in figure 3 on page 23. The sync bits are not scrambled.

The QT2022/32 will begin sending pseudo-random blocks within the IPG on the fiber output when MDIO register bit 3.CC03h.0 is set to 1. The chip will alternate sending all 1s and all 0s blocks. The number of transmitted pseudo-random blocks is counted in MDIO register 3.CC04h. This is a 16 bit rollover counter that is cleared on read.

Transmission of the pseudo-random blocks cannot be enabled unless the 'AMCC part detected' bit 3.CC01h.0 is set to 1. When the 'Extended Link Monitoring RX Enable' bit 3.CC00h.1 is set to 1 (0 by default), any pseudo-random blocks detected by the QT2022/32 on the serial receive input are replaced with idle codes. Ensure this bit is set to force idle replacement.

The chip will begin counting and checking the pseudo-random blocks for errors when MDIO register bit 3.CC03h.1 is set to 1. The number of received pseudo-random blocks is counted in MDIO register 3.CC05h. The chip also checks the descrambled 66b code for errors, which are counted in MDIO register 3.CC06h.

The received block counter and error counter are linked to allow an accurate error rate calculation. A read of the block counter will latch both registers, thereby stopping both registers from counting. The error counter can now be read and an accurate block error rate can be calculated. Reading the error counter clears both counters and restarts them.Both counters are 16 bits read only.

By setting MDIO register bit 3.CC03h.2 to 1, the chip will generate a single corrupted pseudo-random block (if transmission is enabled). This can be used to verify the errored block counter is operating properly.



13 QT2022/32 MII Register Map

The QT2022/32 implements the following register maps defined by the IEEE 802.3 Specification, Clause 45:

- 10G PMA/PMD (device 1)
- 10G WIS (device 2) QT2032 only
- 10G PCS (device 3)
- 10G PHY XGXS (device 4)

As well, there are a number of vendor specific registers which are used for additional functionality, testability and observability.

All reserved/undefined registers are read as 0. Writes to undefined registers are ignored.

Type Name	Type Definition
RO	read only register with a defined function writes are ignored
RO/LL	read only register, latched low bit is reset to high by a read unless the input low state is present
RO/LH	read only register, latched high bit is reset to low by a read unless the input high state is present
RO/NR	Read Only Register, Non-rollover counter. Cleared on read.
RW	read/write register with a defined function
RW, SC	self clearing read/write register bit clears itself after its defined function has been completed; use for resets
RW, Prot	R/W register which can be made R/O by setting EEPROM_PROT=0

13.1 PMA/PMD Internal Control Registers (Device 1)

Bit	PMA/PMD Control 1 Register 1.0
0	PMA Loop Back, RW 0 = Disable PMA Loopback, default 1 = Enable PMA Loopback
1	Reserved, RO
2	Speed Selection, RO 0 = operation at 10 Gb/s
3	Speed Selection, RO 0 = operation at 10 Gb/s
4	Speed Selection, RO 0 = operation at 10 Gb/s
5	Speed Selection, RO 0 = operation at 10 Gb/s
6	Speed Selection, RO 1 = operation at 10 Gb/s and above
7:10	Reserved, RO
11	Low power mode, RW 0 = Normal operation, default 1 = low power mode. PMA power down enabled will power down the whole device with the exception of MDIO access. A reset must be applied to exit power down mode.
12	Reserved, RO
13	Speed Selection, RO 1 = operation at 10 Gb/s and above
14	Reserved, RO
15	PMA/PMD Reset, R/W, SC 0 = Normal operation, default 1 = Reset PMA circuits



Bit	PMA/PMD Status 1 Register 1.1
0	Reserved, RO
1	Power down capability, RO 1 = ability to power down
2	Receive Link Status, RO/LL 0 = PMA receive link down 1 = PMA locked to the receive signal PMA locked to the receive signal = (<i>frxlock</i> = receive path PLL is in lock) AND (RXLOSB_I = no signal loss)
6:3	Reserved, RO
7	Local PMA/PMD Fault, RO 0 = no PMA/PMD fault detected 1 = PMA/PMD fault detected PMA Local Fault = PMA Receive Local Fault (MDIO reg 1.8.10) + PMA Transmit Local Fault (MDIO reg 1.8.11)
15:8	Reserved, RO

Bit	PMA/PMD Identifier 1.2	PMA/PMD Identifier 1.3
15:0	PMA Identifier ¹ , RO 0043h = 0000_0000_0100_0011	PMA Identifier, RO A400h = 1010_0100_0000_0000

1. The PMA unique identifier is the AMCC identifier.

Bit	PMA/PMD Speed Ability Register 1.4
0	PMA/PMD is capable of operating at 10 Gb/s, RO 1
15:1	Reserved, RO

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Bit	PMA/PMD Devices in Package Register 1.5
0	Clause 22 registers not present in package, RO 0
1	PMA/PMD present in package, RO 1
2	1, WIS present in package (QT2032), RO 0, WIS not present in package (QT2022), RO
3	PCS present in package, RO 1
4	PHY_XS present in package, RO 1
5	DTE_XS not present in package, RO 0
15:6	Reserved, RO

Bit	PMA/PMD Devices in Package Register 1.6		
14:0	Reserved, RO		
15	vendor specific device not present in package, RO 0		

Bit	PMA/PMD Control 2 Register 1.7				
2:0		1 0 1 0		PMA/PMD Type 10GBASE-SR (default) 10GBASE-LR 10GBASE-ER 10GBASE-SW ¹ 10GBASE-LW ¹ 10GBASE-LW ¹ Undefined Undefined	
15:3	Reserv	ed, RO	-		

1. Valid for QT2032 only.

Bit	PMA/PMD Status 2 Register 1.8
0	PMA loopback ability, RO 1
1	10GBASE-EW ability ¹ , RO EEPROM register 17 bit 7 = MDIO register 8018h.7
2	10GBASE-LW ability ¹ , RO EEPROM register 17 bit 6 = MDIO register 8018h.6
3	10GBASE-SW ability ¹ , RO EEPROM register 17 bit 5 = MDIO register 8018h.5
4	not 10GBASE-LX4, RO 0
5	10GBASE-ER ability, RO EEPROM register 17 bit 2 = MDIO register 8018h.2
6	10GBASE-LR ability, RO EEPROM register 17 bit 1= MDIO register 8018h.1
7	10GBASE-SR ability, RO EEPROM register 17 bit 0 = MDIO register 8018h.0
8	PMD Transmit disable ability, RO 1
9	Reserved, RO
10	PMA Receive local fault, RO/LH 1 = PMA Receive local fault detected ² == RXLOSB_I + frxlock (Legacy=1) == frxlock (Legacy=0) Linked to 1.9003h.4
11	PMA Transmit local fault, RO/LH 1= PMA Transmit local fault detected ² == TXFAULT + txlock (Legacy=1) == Tx FIFO overflow or underflow (Legacy=0) Linked to 1.9004h.4
12	Receive local fault detect ability, RO 1
13	Transmit local fault detect ability, RO 1
14	Device present, RO 0
15	Device present, RO 1

1. Value of 1 valid for QT2032 only.

2. The field is linked to an MDIO latched high diagnostic alarm register bit. When either register is read both bits will be cleared. The alarm definition depends on Legacy pin input state, as per Table 19 on page 58.

Bit	PMD Transmit Disable 1.9	PMD Receive Signal OK (1.10) 1.Ah
0	PMD Transmit Disable ¹ , RW 1 = Transmit disable 0 = Transmit enable (default)	1=Receive signal detected (RXLOSB_I =1)
1	no PMD lane 0, RO 0	no PMD lane 0, RO 0
2	no PMD lane 1, RO 0	no PMD lane 1, RO 0
3	no PMD lane 2, RO 0	no PMD lane 2, RO 0
4	no PMD lane 3, RO 0	no PMD lane 3, RO 0
15:5	Reserved, RO	Reserved, RO

1. Setting this bit to a 1 will set the TXENABLE pin output low. See Table 30 on page 69 for details.

Bit	Package Identifier OUI (1.14) 1.Eh	Package Identifier OUI (1.15) 1.Fh	
7:0	EEPROM reg 44 bit 7:0, MDIO 1.8033h.7:0	EEPROM reg 46 bit 7:0, MDIO 1.8035h.7:0	
15:8	EEPROM reg 43 bit 7:0, MDIO 1.8032h.7:0	EEPROM reg 45 bit 7:0, MDIO 1.8034h.7:0	

The Package Identifier OUI is read from EEPROM registers 43-46, which correspond to MDIO registers 1.8032h-1.8035h.



Bit	PMA/PMD Vendor Specific EEPROM NVR Control Register 1.32 768 1.8000h	
0	EEPROM NVR Read/Write Byte Count, RW bit1 bit0 Command	
1	0 0 reserved 0 1 reserved 1 0 read or write 1 byte 1 1 read or write 256 bytes (default)	
2	Command Status, RO/LH bit3 bit2 Command	
3	0 0 no command 0 1 command completed 1 0 command in progress 1 1 previous command failed	
4	Reserved, RO	
5	Read/Write Command, RW 0 = read mode (default) 1 = write mode	
6	Reserved, RO	
7	Reserved, RO	
15:8	EEPROM NVR address for single byte write/read	

Bit	PMA Vendor Specific - EEPROM NVR Registers ¹ Register Number = (2 ¹⁵ +7+EEPROM reg#) Register Number = (8007h + EEPROM reg#) Register Number = (32775 + EEPROM reg#)				
	MDIO Reg. 1.32775 1.8007h EEPROM Reg. 0		MDIO Reg. 1.33030 1.8106h EEPROM Reg. 255		
7:0	EEPROM register 0 bit 7:0		EEPROM register 255 bit 7:0		
15:8	Reserved, RO	Reserved, RO	Reserved, RO		

1. See section Table 34, "XENPAK EEPROM Register Map," on page 80 for more information on EEPROM register definitions



Bit	RX_ALARM Control reg 36864 reg 1.9000h		reg 3	M Control 36865 9001h
	LEGACY=1	LEGACY=0	LEGACY=1	LEGACY=0
0	PHY_XS receive loo 1 = enable	cal fault enable, RW ed, default	PHY_XS transmit local fault enable, RW 1 = enabled, default	
1		enable ed, default	<i>tx_flag</i> enable 0 = disabled, default	
2		e violation enable ed, default	PCS buffer over/underflow error enable 0 = disabled, default See Note 1	
3		cal fault enable ed, default	PCS transmit local fault enable 1 = enabled, default	
4		e local fault enable ed, default	PMA/PMD transmit local fault enable 1 = enabled, default	
5	Reserved, RO Receive Optical Power fault enable 1 = enabled, default		Transmitter loss of lock enable 0 = disabled, default	
6	0 = disable	nderflow error enable ed, default Note 1	Transmitter Fault enable 1 = enabled, default	Transmitter Fault enable 0 = disabled, default
7	WIS Alarm Interrupt Enable (RW) 0 = disabled, default See Note 2		Reserved, RO	Laser Output Power Fault enable 1 = enabled, default
8	0 = disable	Interrupt Enable (RW) ed, default Note 2	Reserved, RO	Laser Temperature Fault enable 1 = enabled, default
9	WAN receive local fault 1=enabled, default 0 = disabled See Note 2		Reserved, RO	Laser Bias Current Fault enable 1 = enabled, default
10	Reserved, RO Reserved, RO		_	lation error enable ed, default
15:11	Reserved, RO Reserved, RO		Reserved, RO	Reserved, RO

Note 1: When LANMODE=1, this bit enables alarms on PHY_XS buffer over/under-flow. When LANMODE=0, this bit enables alarms on WIS buffer over/under-flow. Note 2: This bit has no effect and is zero-valued (read-only) when LANMODE=1.

Bit	LASI control reg 36866 reg 1.9002h
0	LS_ALARM enable, RW 0=disabled, default
1	TX_ALARM enable, RW 0=disabled, default
2	RX_ALARM enable, RW 0=disabled, default
3	LASI INTB enable, RW 0=disabled, default
6:4	Reserved, RO
7	LASI test data enable, RW
15:8	Reserved, RO

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Bit	RX_ALARM Sta reg 1.	tus reg 1.36867 9003h	TX_ALARM Status reg 1.36868 reg 1.9004h	
	LEGACY=1	LEGACY=0	LEGACY=1	LEGACY=0
0	PHY_XS receive local fault (RO linked to 4.8.10	, LH) ¹	PHY_XS transmit local fault (RO, LH) ¹ linked to 4.8.11	
1	<i>rx_flag</i> (RO, LH)		<i>tx_flag</i> (RO, LH)	
2	PCS receive code violation (RO	, LH)	PCS buffer over/underflow error (RO, LH) ¹ linked to 4.C002h.9:8	
3	PCS receive local fault (RO, LH linked to 3.8.10)1	PCS transmit local fault (RO, LH) ¹ linked to 3.8.11	
4	PMA/PMD receive local fault (R linked to 1.8.10	O, LH) ¹	PMA/PMD transmit local fault (RO, LH) ¹ linked to 1.8.11	
5	Reserved, RO	Receive Optical Power Fault (RO , LH) linked to 1.A071h.7:6	Transmitter loss of lock (RO, LH) ¹	
6	PHY_XS receive buffer over/une linked to 4.C002h.7:6	derflow value error (RO, LH) ¹	Transmit Fault (RO, LH) ¹ TXFAULT state	
7	WIS Alarm Interrupt Flag (RO) ²	2 3	Reserved, RO	Laser Output Power Fault (RO) linked to 1.A070h.<1:0>
8	WIS Extended Alarm Interrupt F	ïlag (RO) ^{3 4}	Reserved, RO	Laser Temperature Fault (RO) linked to 1.A070h.7:6
9	WIS Local fault (RO,LH) ^{1 3} linked to 2.1.7		Reserved, RO	Laser Bias Current Fault (RO) linked to 1.A070h.3:2
10	Reserved, RO	Reserved, RO	PHY_XS code violation error (R	O, LH)
15:11	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO

1. Register is linked to the MDIO latched high register noted. A read of either register will cause both bits to clear.

2. WIS Alarm Interrupt Flag is high if any bit of MDIO Register 2.33 (2.21h) is set and its associated enable bit in MDIO Register 2.C500h is set as well.

3. Register bit type is Reserved, RO for the QT2022 and the QT2032 when LANMODE = 1.

4. WIS Extended Alarm Interrupt Flag is high if any bit of MDIO Register 2.C502h is set and its associated enable bit in MDIO Register 2.C501h is set as well.



Bit	LASI Status reg 1.36869 reg 1.9005h
0	LS_ALARM, RO/LH 1 = status change 0 = no status change)
1	TX_ALARM, RO 1 = TX_ALARM condition 0 = no alarm
2	RX_ALARM, RO 1 = RX_ALARM condition 0 = no alarm
3	Interrupt from LASI_INTB pin, RO 1 = Interrupt condition (LASI_INTB=0) 0 = no alarm (LASI_INTB=1)
6:4	Reserved, RO
7	LASI test data, RW 0 = default
15:8	Reserved, RO

Bit	tx_flag Control reg 1.9006h	rx_flag Control reg 1.9007h
0	Laser Output Power Low Alarm Enable, RW default=0	Reserved, RW
1	Laser Output Power High Alarm Enable, RW default=0	Reserved, RW
2	Laser Bias Current Low Alarm Enable, RW default=0	Reserved, RW
3	Laser Bias Current High Alarm Enable, RW default=0	Reserved, RW
4	Reserved, RW	Reserved, RW
5	Reserved, RW	Reserved, RW
6	Temp Low Alarm Enable, RW default=0	Rx Optical Power Low Alarm Enable, RW default=0
7	Temp High Alarm Enable, RW default=0	Rx Optical Power High Alarm Enable, RW default=0
15:8	Reserved, RO	Reserved, RO

	DOM Registers			
Bit	1.A000-1.A06Fh	1.A070h <i>tx_flag</i> status	1.A071h <i>rx_flag</i> status	1.A072-1.A0FFh
0	LSB, bit 0	Laser Output Power Low Alarm, RO	LSB, bit 0	LSB, bit 0
1	:	Laser Output Power High Alarm, RO	:	:
2	:	Laser Bias Current Low Alarm, RO	:	:
3	:	Laser Bias Current High Alarm, RO	:	:
4	:	bit 4	:	:
5	:	bit 5	bit 5	:
6	:	Temp Low Alarm, RO	Rx Optical Power Low Alarm, RO	:
7	MSB, bit 7	Temp High Alarm, RO	Rx Optical Power High Alarm, RO	MSB, bit 7
15:8	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO

Bit	DOM Command and Status 1.A100h
0	DOM Update Control, RW ¹ bit1 bit0 Command 0 0 write->single DOM update (default) 0 1 write->slow periodic update 1 0 write->inter. periodic update
	1 1 write->fast periodic update
2	DOM Read Command Status, RO/LH bit3 bit2 Command
3	0 0 idle, no command (default) 0 1 command completed 1 0 command in progress 1 1 previous command failed
4	Reserved, RO
5	Reserved, RO

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Bit	DOM Command and Status 1.A100h	
6	Reserved, RO	
7	Reserved, RO	
8	DOM Command Byte Count Control, RW 0 = 256 bytes (default) 1 = 1 byte	
9	Reserved, RO	
10	Reserved, RO	
11	Reserved, RO	
12	DOM Write Command Status (RO, LH)	
13	bit3 bit2 Command 0 0 idle, no command (default) 0 1 command completed 1 0 command in progress 1 1 previous command failed	
14	Reserved, RO	
15	Reserved, RO	

1. Setting this filed will trigger reading from the peripheral I2C device.

Bit	PMA Vendor Specific 1.C001h
0	<i>txlock</i> , RO 1=Fiber transmit PLL in lock
1	sync_err, RO/LH 1=recovered clock rate error
2	TXPLLOUT Output Frequency Select This pin reverses the sense of the XFP input for determining TXPLLOUT frequency. See Table 8 on page 35. 0 = normal (default) 1 = reversed.
3	TXPLLOUT Output Enable In conjunction with 1.C001h.7, enables or disables the TXPLLOUT output driver. See Table 7 on page 35.
4	PMA network loopback mode, RW 0=disable network loopback (default) 1=enable network loopback
5	PMA Network Loopback Data Override, RW 1= Transmit Data (default) 0= Transmit Idles



Bit	PMA Vendor Specific 1.C001h	
6	RXPLLOUT Enable, RW 0=RXPLLOUT disabled except in line timing mode (default) 1=RXPLLOUT enabled	
7	LAN Reference Input Select 0 = use EREFCLK input (default) 1 = use TXPLLOUT input (disables TXPLLOUT output driver) In conjunction with MDIO 1.C001h.3, this bit enables or disables the TXPLLOUT output driver. See Table 7 on page 35.	
8	RXPLLOUT Output Frequency Select, RW 0 = 161MHz rxclk, Default 1 = test mode only. Do not use.	
9	Force Line Timing Mode, RW 0 = Normal Operation (default) 1 = Force Line Timing Mode This bit is used in conjunction with 1.C001h.14 to specify the current line timing state. See "Line Timing" on page 30. for more information on line timing modes.	
10	RXLOSB_I override, RW 0=no override, default 1=RXLOSB_I override RXLOSB_I override does not impact MDIO register 1.10.0 functionality	
11	Reserved, RO	
12	PMA PLL VCO Center Frequency Override Enable (RW) 0 = No Override (default) 1 = Override	
13	PMA PLL VCO Center Frequency Override Value (RW) 0 = Select LOW Frequency (default) 1 = Select HIGH Frequency Note: Selection is active only when bit 1.C001h.12 is high.	
14	Automatic Line Timing Mode Enable, RW 0 = Automatic Line Timing Mode disabled (default) 1 = Automatic Line Timing Mode enabled This bit is used in conjunction with 1.C001h.9 to specify the current line timing state. For more information on line timing modes, refer to section Section 6.2.2 on page 30.	
15	PMA System Loopback Data Override, RW 1= Transmit Data 0= Transmit All 0s (default)	



Bit	PMA/PMD Vendor Specific Register 1.C002h	PMA/PMD Vendor Specific EEPROM NVR Control Register 1.C003h	PMA/PMD Vendor Specific EEPROM NVR Checksum / I2C/DOM Write Control 1.C004h	Register Upload Command and Status 1.C005h
0	I2C/DOM single byte read/write address, RW	EEPROM NVR 256 byte write	I2C/DOM Write Command, RW bit1 bit0 Command	Register Upload Commands, RW bit1 bit0 Command
1		cycle burst size, RW size bit1 bit0 1 0 0 8 0 1 default 16 1 0 1 1 1	0 0 reserved 0 1 reserved 1 0 write 1 byte 1 1 write 256 bytes	0 0 Reserved (default) 0 1 Reserved 1 0 Reserved 1 1 read-> Upload the MDIO registers from external EEPROM.
2		Reserved, RO	I2C/DOM 256 byte write cycle burst size, RW	Register Upload Command Status for the first EEPROM, RO/LH
3		Reserved, RO	size bit1 bit0 1 0 0 8 0 1 default 16 1 0 1 1 1	bit3 bit2 Command 0 0 idle, no command (default) 0 1 command completed 1 0 command in progress 1 1 previous command failed
4		EEPROM NVR 256 byte read	Reserved, RO	Register Upload Command Status for the second EEPROM, RO/LH
5		cycle burst size, RW size bit1 bit0 1 0 0 8 0 1 16 1 0 256 1 1 default	Reserved, RO	bit5 bit4 Command 0 0 idle, no command (default) 0 1 command completed 1 0 command in progress 1 1 previous command failed
6		Reserved, RO	Reserved, RO	Reserved, RO
7		EEPROM NVR Checksum OK, RO 1=OK	Reserved, RO	Reserved, RO
8	I2C Bus Timeout Coun-	Reserved, RO	EEPROM NVR Calculated	Reserved, RO
9	ter, RW Default = 8'd0 (disabled)	Reserved, RO	Checksum, RO	Reserved, RO
10	Note: Timeout Value defined in Seconds	Reserved, RO		Reserved, RO
11		EEPROM NVR Active, RO 1=EEPROM access in progress (MDIO writes to EEPROM regis- ters ignored)		Reserved, RO
12		EEPROM NVR Error, RO/LH 1=EEPROM error		Reserved, RO
13		EEPROM NVR Detected, RO 1=EEPROM Detected		Reserved, RO
14		EEPROM master bus rate control,		Reserved, RO
15		RW bit15 bit14 0 0 = $37kHz$, default 1 0 = $74kHz$ 1 x = reserved 1 x = $600kHz$		Reserved, RO

Bit	PMA Vendor Specific 1.C023h	
4:0	I2C Address Extension in 2 Byte Addressing Mode (RW)	
15:5	Reserved, RO	

Bit	PMA Vendor Specific 1.C024h	
0	EEPROM_SCL tristate, RW ¹ 0 = not tristate, default 1 = tristate	
1	Bypass EEPROM Powerup Wait (RW) 0 = Normal EEPROM Operation (default) 1 = Bypass 250ms Powerup Wait Time	
2	EEPROM ATE Mode Enable (RW) 0 = Normal EEPROM Operation (default) 1 = ATE Mode (test mode only, do not use)	
15:3	Reserved, RO	

1. It is not necessary to set this bit to 1 in order for external I2C access to function properly (see Section 10.8.2, "Reading and Writing Using the I2C Interface," on page 94

Bit	PMA Vendor Specific 1.C025h	
0	TX Fiber 1.2V Power Supply Monitor ¹ , RO 1 = Power Supply OK	
1	RX Fiber 1.2V Power Supply Monitor ¹ , RO 1 = Power Supply OK	
2	XAUI CDR 1.2V Power Supply Monitor ¹ , RO 1 = Power Supply OK	
15:3	Reserved (RO)	

1. Informative only. Performance of the supply monitors are not guaranteed.



Bit	PMA Vendor Specific AMCC Test Patterns Control 1.C030h	PMA Vendor Specific AMCC Test Patterns 1.C031h
0	Enable TX Fibre for AMCC Test Pattern 0 = Disable, Default 1 = Enable	AMCC Test Pattern Programmable Value, RW default = 0x0000
1	Select AMCC Test Pattern on TX Fibre 0 = Static, Default 1 = User Defined Value	
2	Override TX Fibre Lock 0 = Disabled, Default 1 = Set Lock to 1	
3	Override RX Fibre Lock 0 = Disabled, Default 1 = Set Lock to 1	
4	Force sync_err 0 = Disabled, Default 1 = Force Sync Error	
5	Select sync_err Value 0 = Sync Error Low 1 = Sync Error High	
6	Override xfp_eqn 0 = Disabled, Default 1 = Set xfp_eqn to 1	
7	Override effect of sync_err on LTIMEOK logic, RW 0 = Disabled, default 1 = override sync_err (see Table 8 on page 31 for details).	
8	Force TX Fibre VCO 0 = Disabled, Default 1 = Force VCO	
9	Select TX Fibre VCO Forced Frequency 0 = MIN Freq, Default 1 = MAX Freq	
10	Force RX Fibre VCO 0 = Disable, Default 1 = Force VCO	
11	Select RX Fibre VCO Forced Frequency 0 = MIN Freq, Default 1 = MAX Freq	
12	Force TX Fibre Powerdown 0 = Disable, Default 1 = Force Powerdown	
13	Force RX Fibre Powerdown 0 = Disable, Default 1 = Force Powerdown	
14	Line Timing AIS-L Override ¹ (RW) 0 = Override Disabled, default 1 = Override Enabled	
15	Line Timing LOF Override ¹ (RW) 0 = Override Disabled, default 1 = Override Enabled	



1. Register value ignored for QT2022, or QT2032 in LAN mode.

Bit	Memory BIST Mode Register 0 1.C100h	Memory BIST Control Register 1 1.C101h	Memory BIST Control Register 1.C102h
0	Done	Upper Mode Register Bit 16 (RW)	Run Memory BIST 0 (RW)
1	Control Select	Reserved, RO	Run Memory BIST 1 (RW)
2:5	Algorithm Select	Reserved, RO	Run Memory BIST 2 (RW)
		Reserved, RO	Run Memory BIST 3 (RW)
		Reserved, RO	Run Memory BIST 4 (RW)
		Reserved, RO	Corrupt Memory BIST 0 (RW)
6	Pause	Reserved, RO	Corrupt Memory BIST 1 (RW)
7	Error	Reserved, RO	Corrupt Memory BIST 2 (RW)
8	Debug Mode	Reserved, RO	Corrupt Memory BIST 3 (RW)
12:9	Pattern	Reserved, RO	Corrupt Memory BIST 4 (RW)
		Reserved, RO	BIST Enable 0 (RW)
		Reserved, RO	BIST Enable 1 (RW)
		Reserved, RO	BIST Enable 2 (RW)
14:13	Port	Reserved, RO	BIST Enable 3 (RW)
		Reserved, RO	BIST Enable 4 (RW)
15	Upper Mode Register	Reserved, RO	Reserved, RO

Bit	Memory BIST Debug Register 0 1.C103h	Memory BIST Debug Register 1 1.C104h	Memory BIST Debug Register 2 1.C105h	Memory BIST Debug Register 3 1.C106h	Memory BIST Debug Register 4 1.C107h
7:0	Data [15:0], RO	Data [31:16], RO	Data [47:32], RO	Data [63:48], RO	Data [71:64], RO
15:8					Reserved, RO

Bit	Memory Select Register 1.C108h
2:0	BIST Select (RW) 0 = BIST 0, Memory 0 (default) 1 = BIST 1, Memory 0 2 = BIST 2, Memory 0 3 = BIST 2, Memory 1 4 = BIST 3, Memory 0 5 = BIST 3, Memory 1 6 = BIST 4, Memory 0
15:3	Reserved, RO

Bit	XFP Status Register 1.C200h	XFP Control Register 1.C201h
0	MOD_ABS Status, RO	MOD_DESEL Control, RW 0 = module selected, default 1 = module deselected
1	MOD_NR Status, RO	P_DOWN_RST Control, RW 0 = no power down, default 1 = power down
2	INT_B Status, RO	Reserved, RO
3	RX_LOS Status, RO	Reserved, RO
14:4	Reserved, RO	Reserved, RO
15	TX_DIS Status, RO Note: TX_DIS is an output pin of QT2022/32 driven by Reg- ister 1.9.0 (same as TXENABLE)	Reserved, RO



Bit	PMA Vendor Specific AMCC Product Code 1.D000h		AMCC	PMA Vendor Specific AMCC Revision Code 1.D001h	
	QT2032	QT2022	QT2032	QT2022	
3:0	Product code Fourth Character, RO 0x 2	Product code Fourth Character, RO 0x 2	Reserved, RO 0x 0	Reserved, RO 0x 0	
7:4	Product code Third Character, RO 0x 3	Product code Third Character, RO 0x 2	Reserved, RO 0x 0	Reserved, RO 0x 0	
11:8	Product code Second Character, RO 0x 0	Product code Second Character, RO 0x 0	Metal Code, RO 0x 1	Metal Code, RO 0x 1	
15:12	Product code First Character, RO 0x 2	Product code First Character, RO 0x 2	Version Code, RO 0x A	Version Code, RO 0x C	

Bit	PMA Vendor Specific AMCC Input Pads Status 1.D002h	PMA Vendor Specific AMCC Input Pads Inversion Control 1.D003h
0	RxXAUI_SEL, RO	RxXAUI_SEL Invert, RW 0 = No Change (default) 1 = Inverted after PAD
1	TxXAUI_SEL, RO	TxXAUI_SEL Invert, RW 0 = No Change (default) 1 = Inverted after PAD
2	TXON, RO	TXON Invert, RW 0 = No Change (default) 1 = Inverted after PAD
3	TXOUT_SEL, RO	TXOUT_SEL Invert, RW 0 = No Change (default) 1 = Inverted after PAD
4	RXIN_SEL, RO	RXIN_SEL Invert, RW 0 = No Change (default) 1 = Inverted after PAD
5	TXFAULT, RO	TXFAULT Invert, RW 0 = No Change (default) 1 = Inverted after PAD
6	RXLOSB_I, RO	RXLOSB_I Invert, RW 0 = No Change (default) 1 = Inverted after PAD
7	LASI_INTB, RO	LASI_INTB Invert, RW 0 = No Change (default) 1 = Inverted after PAD
8	VCXOONLY ¹ , RO	VCXOONLY Invert ¹ , RW 0 = No Change (default) 1 = Inverted after PAD
9	VCXOB ¹ , RO	VCXOB Invert ¹ , RW 0 = No Change (default) 1 = Inverted after PAD
10	VCXOSEL622 ¹ , RO	VCXOSEL622 Invert ¹ , RW 0 = No Change (default) 1 = Inverted after PAD
11	REFSEL622 ¹ , RO	REFSEL622 Invert ¹ , RW 0 = No Change (default) 1 = Inverted after PAD
12	PHOFF_EN, RO	PHOFF_EN Invert, RW 0 = No Change (default) 1 = Inverted after PAD
13	EEPROM_PROT, RO	Reserved, RO
14	XFP, RO	Reserved, RO
15	LEGACY, RO	Reserved, RO

1. Pin is not defined for QT2022.

Bit	PMA Vendor Specific AMCC Output Pads Status 1.D004h	PMA Vendor Specific AMCC Output Pads Inversion Control 1.D005h
0	LASI, RO	LASI Invert, RW 0 = No Change (default) 1 = Inverted before PAD
1	TXENABLE, RO	TXENABLE Invert, RW 0 = No Change (default) 1 = Inverted before PAD
2	LOSOUTB, RO	LOSOUTB Invert, RW 0 = No Change (default) 1 = Inverted before PAD
3	LTIMEOK ¹ , RO	LTIMEOK Invert ¹ , RW 0 = No Change (default) 1 = Inverted before PAD
15:4	Reserved, RO	Reserved, RO

1. Pin is not defined for QT2022.

Bit	PMA Vendor Specific GPIO1/LED1 Control and Status 1.D006h
0	LED1/GPIO1 Configuration Control, RW
1	<u>2 1 0</u> 0 0 0 = Reserved
2	0 0 1 = Link Status Only 0 1 0 = Link Activity Only 0 1 1 = Link Status and Activity (default) 1 0 0 = LED OFF 1 0 1 = LED ON 1 1 1 = Input Mode
3	LED1 Path Select, RW 0= Transmit Path (default) 1= Receive Path
4	LED1 Stretch Time Select, RW 0= 50ms (default) 1= 100ms
5	LED1/GPI01 Pin State, RO
15:6	Reserved, RO

Bit	PMA Vendor Specific GPIO2/LED2 Control and Status 1.D007h
0	LED2/GPIO2 Configuration Control, RW
1	<u>2 1 0</u> 0 0 0 = Reserved
2	0 0 1 = Link Status Only 0 1 0 = Link Activity Only 0 1 1 = Link Status and Activity (default) 1 0 0 = LED OFF 1 0 1 = LED ON 1 1 1 = Input Mode
3	LED2 Path Select, RW 0= Transmit Path 1= Receive Path (default)
4	LED2 Stretch Time Select, RW 0= 50ms (default) 1= 100ms
5	LED2/GPIO2 Pin State, RO
15:6	Reserved, RO

Bit	PMA Vendor Specific GPIO3/LED3 Control and Status 1.D008h
0 1 2	LED3/GPIO3 Configuration Control, RW 210 000 = Reserved 001 = Link Status Only (default) 010 = Link Activity Only 011 = Link Status and Activity 100 = LED OFF 101 = LED ON 111 = Input Mode
3	LED3 Path Select, RW 0= Transmit Path 1= Receive Path (default)
4	LED3 Stretch Time Select, RW 0= 50ms (default) 1= 100ms
5	LED3/GPIO3 Pin State, RO
15:6	Reserved, RO



13.2 WIS Registers (Device 2) (QT2032 only)

The Device 2 registers are defined for the QT2032 only. For the QT2022, writes to these registers are ignored. Reads from these registers will return all 0's.

Bit	WIS Control 1 Reg 2.0
0	Reserved, RO
6:1	Speed selection (RO): always 5'b10000
12:7	Reserved, RO
13	Speed selection (RO) always 1
14	loopback (RW) 1=enable loopback mode 0=disable loopback mode
15	Reset (RW/SC) 1=WIS reset 0=normal operation

Bit	WIS Status 1 Reg 2.1
0	Reserved, RO
1	Power down capability, RO 1 = ability to power down
2	Link Status (RO/LL) 1=WIS link up 0=WIS link down Link Status == WIS Sync AND PLM-P AND LOP-P AND AIS-P AND AIS-L
6:3	Reserved, RO
7	WIS Local Fault ¹ (RO/LH)
15:8	Reserved, RO

1. WIS Local Fault = NOT (WIS Sync). WIS Sync is defined in IEEE 802.3-2005 Clause 50.4.

Bit	WIS Identifier 2.2	WIS Identifier 2.3
15:0	WIS Identifier ¹ , RO 0043h = 0000_0000_0100_0011	WIS Identifier, RO A400h = 1010_0100_0000_0000

1. The WIS unique identifier is the AMCC identifier.

Bit	WIS Speed Ability Register 2.4
0	WIS is capable of operating at 10 Gb/s, RO always 1
15:1	Reserved, RO

Bit	Device in package Register 2.5
0	Clause 22 register present (RO) always 0
1	PMD/PMA present (RO) always 1
2	WIS present (RO) always 1
3	PCS present (RO) always 1
4	PHY XS present (RO) always 1
5	DTE XS present (RO) always 0
15:6	Reserved (RO)

Bit	Device in package Register 2.6
14:0	Reserved (RO)
15	Vendor Specific Device present (RO): always 0



Bit	WIS Control 2 Register 2.7
0	Port type selection ¹ (RW) 1 = Select 10GBASE-W PCS type, default 0 = Select 10GBASE-R PCS type
1	Transmit test pattern enable (RW)
2	Receive test pattern enable (RW)
3	Test pattern select (RW) 1=Square wave test pattern 0=Mixed frequency test pattern
4	Transmit PRBS31 generator enable (RW) 0 = not enabled, default 1 = enable Tx PRBS31
5	Receive PRBS31 checker enable (RW) 0 = not enabled, default 1 = enable Rx PRBS31 checker
15:6	Reserved (RO)

This register bit can be used to enable/disable the WIS in the QT2032. Refer to Section 7, "WAN Interface Sublayer (WIS) Description (QT2032 Only)," on page 36 for details. This bit is "sticky"; it maintains its value after a soft reset (a reset from an MDIO command). The default value is restored after a hard reset (applied to RESETN input pin).

Bit	WIS Status 2 Register 2.8
0	10GBASE-R ability (RO) always 1
1	PRBS31 ability (RO) always 1
13:2	Reserved (RO)
14	Device present (RO): always 0
15	Device present (RO): always 1

Bit	WIS Test Pattern Error Counter Register 2.9
15:0	Test pattern error count (RO,NR) count reset on read LSB is bit 0 MSB is bit 15

Bit	10G WIS Status 3 Register (2.33) 2.0021h ¹
0	LOP-P (RO/LH): Loss of Pointer
1	AIS-P (RO/LH): Alarm Indication signal
2	PLM-P (RO/LH): Loss of Label Mismatch
3	LCD-P (RO/LH): Path loss of cell delineation
4	AIS-L(RO/LH): Line Alarm Indication Signal
5	RDI-L (RO/LH): Line Remote Defect Indication
6	LOS (RO/LH): Loss of Signal (based on no transitions as described in ANSI T1.416-1999)
7	LOF (RO/LH): Loss of Frame
8	Reserved (RO)
9	Far End AIS-P/LOP-P (RO/LH)
10	Far End PLM-P/LCD-P(RO/LH):
11	SEF (RO/LH): Severely Errored Frame
15:12	Reserved (RO)

1. The alarms in this register can be programmed to trip the LASI interrupt output signal. The mask register 2.C500h is used to control which alarms are enabled.

Bit	Register (2.37) 2.25h
15:0	Far End Path Block (BIP-8) Error Count (RO)

Reg	WIS J1 Tx Registers (2.39-2.46) 2.27h - 2.2Eh
2.39	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 1
2.39	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 2
2.40	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 3
2.40	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 4
2.41	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 5
2.41	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 6
2.42	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 7
2.42	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 8
2.43	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 9
2.43	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 10
2.44	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 11
2.44	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 12
2.45	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 13
2.45	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 14
2.46	J1 Tx (RW):
7:0	Transmitted Path Trace Octet J1 Tx 15
2.46	J1 Tx (RW):
15:8	Transmitted Path Trace Octet J1 Tx 16

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Reg	WIS J1 Rx Registers (2.47-2.54) 2.2Fh - 2.36h
2.47	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 1
2.47	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 2
2.48	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 3
2.48	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 4
2.48	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 5
2.49	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 6
2.50	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 7
2.50	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 8
2.51	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 9
2.51	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 10
2.51	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 11
2.52	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 12
2.53	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 13
2.53	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 14
2.54	J1 Rx (RO):
7:0	Received Path Trace Octet J1 Rx 15
2.54	J1 Rx (RO):
15:8	Received Path Trace Octet J1 Rx 16

Reg	WIS Far End Line BIP-8 Errors (2.55-2.56) 2.0037h - 2.0038h
2.55	WIS Far End Line BIP-8 Error 0 (RO)
15:0	(Most significant word of the WIS Far End Line BIP-8 Error count)
2.56	WIS Far End Line BIP-8 Error 1 (RO)
15:0	(Least significant word of the WIS Far End Line BIP-8 Error count)

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Reg	WIS Line BIP-8 Errors Registers (2.57-2.58) 2.39h-2.3Ah
2.57	WIS Line BIP-8 Error 0 (RO) (Most significant word of the WIS Line BIP-8 Error count)
2.58	WIS Line BIP-8 Error 1 (RO) (Least significant word of the WIS Line BIP-8 Error count)

Bit	WIS Path BIP-8 Error count Register (2.59) 2.3Bh
15:0	WIS Path BIP-8 Error count (RO)

Bit	WIS Section BIP-8 Error count Register (2.60) 2.3Ch
15:0	WIS Section BIP-8 Error count (RO)

Reg	WIS J0 Tx Registers (2.64-2.71) 2.40h - 2.47h
2.64	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 1
2.64	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 2
2.65	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 3
2.65	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 4
2.66	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 5
2.66	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 6
2.67	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 7
2.67	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 8
2.68	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 9
2.68	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 10
2.69	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 11
2.69	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 12
2.70	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 13
2.70	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 14
2.71	J0 Tx (RW):
7:0	Transmitted Section Trace Octet J0 Tx 15
2.71	J0 Tx (RW):
15:8	Transmitted Section Trace Octet J0 Tx 16

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Reg	WIS J0 Rx Registers (2.72-2.79) 2.0048h - 2.004Fh
2.72	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 1
2.72	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 2
2.73	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 3
2.73	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 4
2.74	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 5
2.74	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 6
2.75	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 7
2.75	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 8
2.76	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 9
2.76	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 10
2.77	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 11
2.77	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 12
2.78	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 13
2.78	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 14
2.79	J0 Rx (RO):
7:0	Received Section Trace Octet J0 Rx 15
2.79	J0 Rx (RO):
15:8	Received Section Trace Octet J0 Rx 16

Bit	WIS Frame Pointer - Vendor Specific Register 2.C000h
0	Received Invalid Pointer (RO/LH) Triggered when positive stuff events are not separated by 3 or more frames.
1	Received Invalid Pointer (RO/LH) Triggered under any of the following four conditions: (NDF & invalid pointer value) OR (no NDF & invalid pointer value for 3 consecutive frames) OR (invalid NDF) OR (a majority of I-bits and D-bits are inverted simultaneously & no NDF & valid pointer value)
2	Pointer change from negative stuff (RO/LH): 1=Pointer changed using a negative stuff event. 0=No pointer changed using a negative stuff event
3	Pointer change from positive stuff (RO/LH): 1=Pointer changed using a positive stuff event. 0=No Pointer changed using a positive stuff event
4	Pointer change without NDF flag (RO/LH): 1=Pointer Changed without NDF flag for 3 consecutive frames. 0=No Pointer changed without NDF flag.
5	Peinter change with-NDF flag detected (RO/LH): 1= Pointer changed using- NDF flag detected. 0 =Ne Peinter changed using- No NDF flag detected.
15:6	Current Pointer (RO): Pointer Value at which the logic looks for the start of a new SPE.

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Bit	WIS Vendor Specific Control - Vendor Specific Register 2.C001h
0	WIS scrambler bypass (RW) 0 = Bypass not asserted (default) 1 = Bypass asserted
1	WIS descrambler bypass (RW) 0 = Bypass not asserted (default) 1 = Bypass asserted
2	WIS TX Reset_N (RW) 0 = Reset asserted 1 = Reset not asserted (default)
3	WIS RX Reset_N (RW) 0 = Reset asserted 1 = Reset not asserted (default)
4	WIS Loopback Select Data Override (RW) 0 = loopback data override not asserted. TXOUT will output 00FF pattern. (default) 1 = loopback data override asserted. TXOUT will output transmit data.
5	WIS Fiber PRBS Inversion (RW) 0 = No change. 1 = Inverted (default)
7:6	WIS TX SS Bits Value (RW) 2'b00 = Default Value
15:8	Reserved (RO)

Bit	WIS Extended Features Control - Vendor Specific Register 2.C002h
0	WIS Transmit Extended J1 Trace Message Enable (RW)
1	WIS Receive Extended J1 Trace Message Enable (RW)
2	WIS Transmit Serial Overhead Interface Enable (RW)
3	WIS Receive Serial Overhead Interface Enable (RW)
4	WIS Transmit Programmable K1 Value Enable (RW)
5	WIS Transmit Programmable K2 Value Enable (RW)
6	WIS Transmit Programmable S1 Value Enable (RW)
7	WIS SD Monitoring Enable (RW)
8	WIS SF Monitoring Enable (RW)
9	WIS TX SS Bits Insert Enable (RW) Reserved (RO)
15:10	Reserved (RO)

Bit	WIS Serial Interface Control - Vendor Specific Register 2.C010h
2:0	WIS Serial Interface Mode of Operation on Transmit Path (RW) 001 = Use serial data for all STS-1 Transport Overhead 100 = Use serial data for D1-D3 Overhead Bytes 101 = Use serial data for D4-D12 Overhead Bytes 110 = Use serial data for D1-D12 Overhead Bytes other values = Serial data ignored (default)
3	Reserved (RO)
6:4	WIS Serial Interface Mode of Operation on Receive Path (RW) 001 = Use serial data for all STS-1 Transport Overhead 100 = Use serial data for D1-D3 Overhead Bytes 101 = Use serial data for D4-D12 Overhead Bytes 110 = Use serial data for D1-D12 Overhead Bytes other values = Serial data ignored (default)
15:7	Reserved (RO)

Bit	Pointer Justification Counter - Vendor Specific Register 2.C020h
7:0	Positive Stuff Event Counter (RO, Cleared on Read - No Rollover) Counter incremented by 1 on Positive Stuff Event
15:8	Negative Stuff Event Counter (RO, Cleared on Read - No Rollover) Counter incremented by 1 on Negative Stuff Event

Reg	WIS J1 Rx Extended Registers 2.C100h - 2.C117h
2.C100h	J1 Rx Byte #18 (MSB), J1 Rx Byte #17 (LSB) - (RO)
2.C101h	J1 Rx Byte #20 (MSB), J1 Rx Byte #19 (LSB) - (RO)
2.C102h	J1 Rx Byte #22 (MSB), J1 Rx Byte #21 (LSB) - (RO)
2.C103h	J1 Rx Byte #24 (MSB), J1 Rx Byte #23 (LSB) - (RO)
2.C104h	J1 Rx Byte #26 (MSB), J1 Rx Byte #25 (LSB) - (RO)
2.C105h	J1 Rx Byte #28 (MSB), J1 Rx Byte #27 (LSB) - (RO)
2.C106h	J1 Rx Byte #30 (MSB), J1 Rx Byte #29 (LSB) - (RO)
2.C107h	J1 Rx Byte #32 (MSB), J1 Rx Byte #31 (LSB) - (RO)
2.C108h	J1 Rx Byte #34 (MSB), J1 Rx Byte #33 (LSB) - (RO)
2.C109h	J1 Rx Byte #36 (MSB), J1 Rx Byte #35 (LSB) - (RO)
2.C10Ah	J1 Rx Byte #38 (MSB), J1 Rx Byte #37 (LSB) - (RO)



Reg	WIS J1 Rx Extended Registers 2.C100h - 2.C117h (Continued)
2.C10Bh	J1 Rx Byte #40 (MSB), J1 Rx Byte #39 (LSB) - (RO)
2.C10Ch	J1 Rx Byte #42 (MSB), J1 Rx Byte #41 (LSB) - (RO)
2.C10Dh	J1 Rx Byte #44 (MSB), J1 Rx Byte #43 (LSB) - (RO)
2.C10Eh	J1 Rx Byte #46 (MSB), J1 Rx Byte #45 (LSB) - (RO)
2.C10Fh	J1 Rx Byte #48 (MSB), J1 Rx Byte #47 (LSB) - (RO)
2.C110h	J1 Rx Byte #50 (MSB), J1 Rx Byte #49 (LSB) - (RO)
2.C111h	J1 Rx Byte #52 (MSB), J1 Rx Byte #51 (LSB) - (RO)
2.C112h	J1 Rx Byte #54 (MSB), J1 Rx Byte #53 (LSB) - (RO)
2.C113h	J1 Rx Byte #56 (MSB), J1 Rx Byte #55 (LSB) - (RO)
2.C114h	J1 Rx Byte #58 (MSB), J1 Rx Byte #57 (LSB) - (RO)
2.C115h	J1 Rx Byte #60 (MSB), J1 Rx Byte #59 (LSB) - (RO)
2.C116h	J1 Rx Byte #62 (MSB), J1 Rx Byte #61 (LSB) - (RO)
2.C117h	J1 Rx Byte #64 (MSB), J1 Rx Byte #63 (LSB) - (RO)

Reg	WIS J1 Tx Extended Registers 2.C200h - 2.C217h
2.C200h	J1 Tx Byte #18 (MSB), J1 Tx Byte #17 (LSB) - (RW)
2.C201h	J1 Tx Byte #20 (MSB), J1 Tx Byte #19 (LSB) - (RW)
2.C202h	J1 Tx Byte #22 (MSB), J1 Tx Byte #21 (LSB) - (RW)
2.C203h	J1 Tx Byte #24 (MSB), J1 Tx Byte #23 (LSB) - (RW)
2.C204h	J1 Tx Byte #26 (MSB), J1 Tx Byte #25 (LSB) - (RW)
2.C205h	J1 Tx Byte #28 (MSB), J1 Tx Byte #27 (LSB) - (RW)
2.C206h	J1 Tx Byte #30 (MSB), J1 Tx Byte #29 (LSB) - (RW)
2.C207h	J1 Tx Byte #32 (MSB), J1 Tx Byte #31 (LSB) - (RW)
2.C208h	J1 Tx Byte #34 (MSB), J1 Tx Byte #33 (LSB) - (RW)
2.C209h	J1 Tx Byte #36 (MSB), J1 Tx Byte #35 (LSB) - (RW)
2.C20Ah	J1 Tx Byte #38 (MSB), J1 Tx Byte #37 (LSB) - (RW)
2.C20Bh	J1 Tx Byte #40 (MSB), J1 Tx Byte #39 (LSB) - (RW)
2.C20Ch	J1 Tx Byte #42 (MSB), J1 Tx Byte #41 (LSB) - (RW)
2.C20Dh	J1 Tx Byte #44 (MSB), J1 Tx Byte #43 (LSB) - (RW)

Reg	WIS J1 Tx Extended Registers 2.C200h - 2.C217h (Continued)
2.C20Eh	J1 Tx Byte #46 (MSB), J1 Tx Byte #45 (LSB) - (RW)
2.C20Fh	J1 Tx Byte #48 (MSB), J1 Tx Byte #47 (LSB) - (RW)
2.C210h	J1 Tx Byte #50 (MSB), J1 Tx Byte #49 (LSB) - (RW)
2.C211h	J1 Tx Byte #52 (MSB), J1 Tx Byte #51 (LSB) - (RW)
2.C212h	J1 Tx Byte #54 (MSB), J1 Tx Byte #53 (LSB) - (RW)
2.C213h	J1 Tx Byte #56 (MSB), J1 Tx Byte #55 (LSB) - (RW)
2.C214h	J1 Tx Byte #58 (MSB), J1 Tx Byte #57 (LSB) - (RW)
2.C215h	J1 Tx Byte #60 (MSB), J1 Tx Byte #59 (LSB) - (RW)
2.C216h	J1 Tx Byte #62 (MSB), J1 Tx Byte #61 (LSB) - (RW)
2.C217h	J1 Tx Byte #64 (MSB), J1 Tx Byte #63 (LSB) - (RW)

Bit	WIS K1 Tx Byte - Vendor Specific Register 2.C300h
7:0	K1 Byte Value to Transmit (RW) default = 8'h00
15:8	Reserved (RO)

Bit	WIS K1 Rx Byte - Vendor Specific Register 2.C301h
7:0	Validated K1 Byte Value (RO)
15:8	Received K1 Byte Value (RO)

Bit	WIS K2 Tx Byte - Vendor Specific Register 2.C302h
2:0	Reserved (RO)
7:3	K2 Byte Value to Transmit (RW) default = 5b'00000
15:8	Reserved (RO)

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Bit	WIS K2 Rx Byte - Vendor Specific Register 2.C303h
7:0	Validated K2 Byte Value (RO)
15:8	Received K2 Byte Value (RO)

Bit	WIS S1 Tx Byte - Vendor Specific Register 2.C304h
7:0	S1 Byte Value to Transmit (RW) default = 8'h00
15:8	Reserved (RO)

Bit	WIS S1 Rx Byte - Vendor Specific Register 2.C305h
7:0	Validated S1 Byte Value (RO)
15:8	Received S1 Byte Value (RO)

Bit	WIS SD Timing Window - Vendor Specific Register 2.C400h
15:0	Programmable timing window (RW) n x 125μs (from 125μs to 8.192s) (0 is an illegal value) default = 16'd40

Bit	WIS SD Detection Threshold - Vendor Specific Register 2.C401h
15:0	Programmable Detection Threshold (RW) default = 16'd49

Bit	WIS SD Clearing Threshold - Vendor Specific Register 2.C402h
15:0	Programmable Clearing Threshold (RW) default = 16'd49



Bit	WIS SD Coding Violations Count - Vendor Specific Register 2.C403h
15:0	Coding Violation Count over the last timing window (RO)

Bit	WIS SF Timing Window - Vendor Specific Register 2.C410h
15:0	Programmable timing window (RW) n x 125μs (from 125μs to 8.192s) (0 is an illegal value) default = 16'd40

Bit	WIS SF Detection Threshold - Vendor Specific Register 2.C411h
15:0	Programmable Detection Threshold (RW) default = 16'd49

Bit	WIS SF Clearing Threshold - Vendor Specific Register 2.C412h
15:0	Programmable Clearing Threshold (RW) default = 16'd49

Bit	WIS SF Coding Violations Count - Vendor Specific Register 2.C413h
15:0	Coding Violation Count over the last timing window (RO)



Bit	WIS Alarms Interrupt Control ¹ - Vendor Specific Register 2.C500h
0	LOP-P Enable (RW) 0 = Disabled (default) 1 = Enabled
1	AIS-P Enable (RW) 0 = Disabled (default) 1 = Enabled
2	PLM-P Enable (RW) 0 = Disabled (default) 1 = Enabled
3	LCD-P Enable (RW) 0 = Disabled (default) 1 = Enabled
4	AIS-L Enable (RW) 0 = Disabled (default) 1 = Enabled
5	RDI-L Enable (RW) 0 = Disabled (default) 1 = Enabled
6	LOS Enable (RW) 0 = Disabled (default) 1 = Enabled
7	LOF Enable (RW) 0 = Disabled (default) 1 = Enabled
8	Reserved (RO) Far End LOP-P Enable (RW) 0 = Disabled (default) 1 = Enabled
9	Far End AIS-P/LOP-P Enable (RW) 0 = Disabled (default) 1 = Enabled
10	Far End PLM-P/LCD-P Enable (RW) 0 = Disabled (default) 1 = Enabled
11	SEF Enable (RW) 0 = Disabled (default) 1 = Enabled
15:12	Reserved (RO)

1. This is the Alarm Interrupt Control Register for Register 2.33d (2.21h). It can be used to program which alarms will trip the LASI interrupt output signal.

Bit	WIS Extended Alarms Interrupt Control ¹ - Vendor Specific Register 2.C501h
0	K1 Validated Byte Enable (RW) 0 = Disabled (default) 1 = Enabled
1	K2 Validated Byte Enable (RW) 0 = Disabled (default) 1 = Enabled
2	Received Inconsistent K1 Bytes Enable (RW) 0 = Disabled (default) 1 = Enabled
3	Received Inconsistent K2 Bytes Enable (RW) 0 = Disabled (default) 1 = Enabled
4	S1 Validated Byte Enable (RW) 0 = Disabled (default) 1 = Enabled
5	Reserved (RW)
6	Received <u>New</u> J0 Trace <u>Message</u> Mismatch Enable (RW) 0 = Disabled (default) 1 = Enabled
7	Received <u>New</u> J1 Trace <u>Message</u> Mismatch Enable (RW) 0 = Disabled (default) 1 = Enabled
8	SD Alarm Enable (RW) 0 = Disabled (default) 1 = Enabled
9	SD Timing Window Expired Enable (RW) 0 = Disabled (default) 1 = Enabled
10	SF Alarm Enable (RW) 0 = Disabled (default) 1 = Enabled
11	SF Timing Window Expired Enable (RW) 0 = Disabled (default) 1 = Enabled
15:12	Reserved (RO)

1. This is the alarm interrupt control for Register 2.C502h. It can be used to program which alarms will trip the LASI interrupt output signal.



Bit	WIS Extended Alarms Status - Vendor Specific Register 2.C502h ¹
0	K1 Validated Byte Flag (RO/LH)
1	K2 Validated Byte Flag (RO/LH)
2	Received Inconsistent K1 Bytes Flag (RO/LH)
3	Received Inconsistent K2 Bytes Flag (RO/LH)
4	S1 Validated Byte Flag (RO/LH)
5	Reserved (RO)
6	Received New J0 Trace Message Mismatch Flag (RO/LH)
7	Received New J1 Trace Message Mismatch Flag (RO/LH)
8	SD Alarm Flag (RO/LH)
9	SD Timing Window Expired Flag (RO/LH)
10	SF Alarm Flag (RO/LH)
11	SF Timing Window Expired Flag (RO/LH)
15:12	Reserved (RO)

1. The alarms in this register can be programmed to trip the LASI interrupt output signal. The mask register 2.C501h is used to control which alarms are enabled.

Bit	WIS OH Insert Enable - Vendor Specific Register 2.C600h
0	Byte Insertion Enable ¹ (RW) 0 = Insertion Disabled (default) 1 = Insertion Triggered
15:1	Reserved (RO)

1. The "Insertion Enable" bit is used to trigger OH byte insertion when a fixed number of frame insertion events is selected. The number of insertion events is specified in Register 2.C601h-C603h, bits 15:14. If continuous insertion is specified, the "Insertion Enable" bit has no effect.

Bit	WIS OH Insert Byte 1 Control - Vendor Specific Register 2.C601h
1:0	STS-1 Column Number (RW) Valid Values: from 0 to 3.
5:2	STS-1 Row Number (RW) Valid Values: from 0 to 8.
13:6	STS-1 Byte Number (RW) Valid Values: from 0 to 191
15:14	Count Control (RW) 00 = overwrite the selected byte for 1 frame 01 = overwrite the selected byte for 5 frame 10 = overwrite the selected byte for 7 frame 11 = overwrite the selected byte continuously

Bit	WIS OH Insert Byte 2 Control - Vendor Specific Register 2.C602h
1:0	STS-1 Column Number (RW) Valid Values: from 0 to 3.
5:2	STS-1 Row Number (RW) Valid Values: from 0 to 8.
13:6	STS-1 Byte Number (RW) Valid Values: from 0 to 191
15:14	Count Control (RW) 00 = overwrite the selected byte for 1 frame 01 = overwrite the selected byte for 5 frames 10 = overwrite the selected byte for 7 frames 11 = overwrite the selected byte continuously

Bit	WIS OH Insert Byte 3 Control - Vendor Specific Register 2.C603h
1:0	STS-1 Column Number (RW) Valid Values: from 0 to 3.
5:2	STS-1 Row Number (RW) Valid Values: from 0 to 8.
13:6	STS-1 Byte Number (RW) Valid Values: from 0 to 191
15:14	Count Control (RW) 00 = overwrite the selected byte for 1 frame 01 = overwrite the selected byte for 5 frames 10 = overwrite the selected byte for 7 frames 11 = overwrite the selected byte continuously



Bit	WIS OH Insert Byte 1 Value - Vendor Specific Register 2.C604h
7:0	Overwrite Byte Value (RW)
15:8	Reserved (RO)

Bit	WIS OH Insert Byte 2 Value - Vendor Specific Register 2.C605h
7:0	Overwrite Byte Value (RW)
15:8	Reserved (RO)

Bit	WIS OH Insert Byte 3 Value - Vendor Specific Register 2.C606h
7:0	Overwrite Byte Value (RW)
15:8	Reserved (RO)

Bit	WIS OH Extract Enable - Vendor Specific Register 2.C610h
0	Byte 1 Extraction Enable (RW) 0 = Extraction Disabled (default) 1 = Extraction Enabled
1	Byte 2 Extraction Enable (RW) 0 = Extraction Disabled (default) 1 = Extraction Enabled
2	Byte 3 Extraction Enable (RW) 0 = Extraction Disabled (default) 1 = Extraction Enabled
15:3	Reserved (RO)

Bit	WIS OH Extract Byte 1 Control - Vendor Specific Register 2.C611h
1:0	STS-1 Column Number (RW) Valid Values: from 0 to 3. (3 = Path Overhead Bytes)
5:2	STS-1 Row Column Number (RW) Valid Values: from 0 to 8.
13:6	STS-n Byte Number (RW) Valid Values: from 0 to 191. (Field ignored when Column Number == 3)
15:14	Reserved (RO)

Bit	WIS OH Extract Byte 2 Control - Vendor Specific Register 2.C612h
1:0	STS-1 Column Number (RW) Valid Values: from 0 to 3. (3 = Path Overhead Bytes)
5:2	STS-1 Row Column Number (RW) Valid Values: from 0 to 8.
13:6	STS-n Byte Number (RW) Valid Values: from 0 to 191. (Field ignored when Column Number == 3)
15:14	Reserved (RO)

Bit	WIS OH Extract Byte 3 Control - Vendor Specific Register 2.C613h
1:0	STS-1 Column Number (RW) Valid Values: from 0 to 3. (3 = Path Overhead Bytes)
5:2	STS-1 Row Column Number (RW) Valid Values: from 0 to 8.
13:6	STS-n Byte Number (RW) Valid Values: from 0 to 191. (Field ignored when Column Number == 3)
15:14	Reserved (RO)

Bit	WIS OH Extracted Byte 1 Value - Vendor Specific Register 2.C614h
7:0	Extracted Byte Value (RO)
15:8	Reserved (RO)



Bit	WIS OH Extracted Byte 2 Value - Vendor Specific Register 2.C615h
7:0	Extracted Byte Value (RO)
15:8	Reserved (RO)

Bit	WIS OH Extracted Byte 3 Value - Vendor Specific Register 2.C616h	
7:0	Extracted Byte Value (RO)	
15:8	Reserved (RO)	



13.3 PCS Registers (Device 3)

Bit	PCS Control 1 Register 3.0	PCS Status 1 Register Register 3.1	PCS Identifier Register 3.2	PCS Identifier Register 3.3
0	Reserved, RO	Reserved, RO	PCS Identifier, RO 1 ¹	PCS Identifier, RO 0
1	Reserved, RO	Power down capability, RO 1 = ability to power down	PCS Identifier, RO 1	PCS Identifier, RO 0
2	Speed Selection, RO 0 = operation at 10 Gb/s	PCS receive link status RO/LL, 1=receive link up ²	PCS Identifier, RO 0	PCS Identifier, RO 0
3	Speed Selection, RO 0 = operation at 10 Gb/s	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
4	Speed Selection, RO 0 = operation at 10 Gb/s	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
5	Speed Selection, RO 0 = operation at 10 Gb/s	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
6	Speed Selection, RO 1 = operation at 10 Gb/s and above	Reserved, RO	PCS Identifier, RO 1	PCS Identifier, RO 0
7	Reserved, RO	Local fault condition detected 1=local fault condition, RO ³	PCS Identifier, RO 0	PCS Identifier, RO 0
8	Reserved, RO	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
9	Reserved, RO	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
10	Reserved, RO	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 1
11	Power Down, RW 0 = don't power down 1 = power down ⁴	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
12	Reserved, RO	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
13	Speed Selection, RO 1 = operation at 10 Gb/s and above	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 1
14	PCS Loopback, RW, 1 =enable PCS loopback mode 0 = disable PCS loopback	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 0
15	PCS_64/66 Reset, RW/SC 1=reset, 0=normal operation	Reserved, RO	PCS Identifier, RO 0	PCS Identifier, RO 1

1. The PCS unique identifier is the AMCC identifier.

2. PCS Receive Link Status= latching low version of MDIO register 3.32.12 (block_lock + (high_ber)

3. PCS Local fault = PCS transmit local fault (MDIO reg 3.8.11) + PCS receive local fault (MDIO reg 3.8.10)

4. PCS power down enabled will power down the whole device with the exception of MDIO access



Bit	PCS Speed Ability Register 3.4	PCS Devices in Package Register 3.5	PCS Devices in Package Register 3.6
0	1, PCS is capable of operating at 10 Gb/s, RO	0, Clause 22 registers not present in package, RO	Reserved, RO
1	Reserved, RO	1, PMA/PMD present in package, RO	Reserved, RO
2	Reserved, RO	1, WIS present in package (QT2032), RO 0, WIS not present in package (QT2022), RO	Reserved, RO
3	Reserved, RO	1, PCS present in package, RO	Reserved, RO
4	Reserved, RO	1, PHY_XS present in package, RO	Reserved, RO
5	Reserved, RO	0, DTE_XS not present in package, RO	Reserved, RO
6	Reserved, RO	Reserved, RO	Reserved, RO
7	Reserved, RO	Reserved, RO	Reserved, RO
8	Reserved, RO	Reserved, RO	Reserved, RO
9	Reserved, RO	Reserved, RO	Reserved, RO
10	Reserved, RO	Reserved, RO	Reserved, RO
11	Reserved, RO	Reserved, RO	Reserved, RO
12	Reserved, RO	Reserved, RO	Reserved, RO
13	Reserved, RO	Reserved, RO	Reserved, RO
14	Reserved, RO	Reserved, RO	Reserved, RO
15	Reserved, RO	Reserved, RO	vendor specific device not present in package, RO 0

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Bit	PCS Control 2 Register 3.7	10G PCS Status 2 Register 3.8	10GBASE-R PCS Status 1 Register 3.32 (3.20h)	10GBASE-R PCS Status 2 Register 3.33 (3.21h)
0	bit1 bit0 0 0 Select 10GBASE-R PCS 1 0 Select 10GBASE-W PCS ¹ R/W, writes ignored	1, RO, 10GBASE-R PCS capable	10GBASE-R PCS block_lock, RO; 1=PCS locked to received blocks (<i>block_lock</i>)	Errored blocks counter, RO/NR clear counter on read
1		0, RO, 10GBASE-X PCS not supported	10GBASE-R PCS high BER, RO 1=PCS reporting high BER (<i>high_ber</i>)	
2	Reserved, RO	1, RO, 10GBASE-W PCS capable	PRBS31 test mode supported, RO 1=PRBS31 mode supported)	
3	Reserved, RO	Reserved, RO	Reserved, RO	
4	Reserved, RO	Reserved, RO	Reserved, RO	
5	Reserved, RO	Reserved, RO	Reserved, RO	
6	Reserved, RO	Reserved, RO	Reserved, RO	
7	Reserved, RO	Reserved, RO	Reserved, RO	
8	Reserved, RO	Reserved, RO	Reserved, RO	hi_ber Counter, RO/NR
9	Reserved, RO	Reserved, RO	Reserved, RO	clear counter on read
10	Reserved, RO	Receive Local Fault detected, RO/LH 1=PCS Receive Local Fault ^{2 3} linked to 1.9003h.3	Reserved, RO	
11	Reserved, RO	Transmit Local Fault detected, RO/LH 1=PCS Transmit Local Fault ^{3 4} linked to 1.9004h.3	Reserved, RO	
12	Reserved, RO	Reserved, RO	10GBASE-R PCS receive link status, RO 1=receive link up ⁵	
13	Reserved, RO	Reserved, RO	Reserved, RO	
14	Reserved, RO	0, RO Device responding at this address	Reserved, RO	Latched hi_ber, RO/LH 1=10GBASE-R PCS has reported high BER
15	Reserved, RO	1, RO Device responding at this address	Reserved, RO	Latched block lock, RO/LL 1=10GBASE-R PCS has block lock

1. 10GBASE-W not supported in QT2022.

2. PCS receive local fault = (*block_lock*), block lock = register 3.32.0

3. This bit is linked to an MDIO latched high diagnostic alarm register bit. When either register is read both bits will be cleared.

4. PCS transmit local fault = Transmit FIFO Overflow OR Underflow (4.C002h.9:8).

5. PCS receive link up = $block_lock$ AND hi_ber



	10G Base-R PCS Jitter Test Pattern Seed A			10G Ba	se-R PCS Jitte	er Test Pattern	Seed B	
Bit	Registers 3.34 A0	Registers 3.35 A1	Registers 3.36 A2	Registers 3.37 A3	Registers 3.38 B0	Registers 3.39 B1	Registers 3.40 B2	Registers 3.41 B3
0	bit 0, RW	bit 16, RW	bit 32, RW	bit 48, RW	bit 0, RW	bit 16, RW	bit 32, RW	bit 48, RW
1	:	:	:	:	:	:	:	:
2	:	:	:	:	:	:	:	:
3	:	:	:	:	:	:	:	:
4	:	:	:	:	:	:	:	:
5	:	:	:	:	:	:	:	:
6	:	:	:	:	:	:	:	:
7	:	:	:	:	:	:	:	:
8	:	:	:	:	:	:	:	:
9	:	:	:	bit 57, RW	:	:	:	bit 57, RW
10	:	:	:	Res., RW	:	:	:	Res., RW
11	:	:	:	Res., RW	:	:	:	Res., RW
12	:	:	:	Res., RW	:	:	:	Res., RW
13	:	:	:	Res., RW	:	:	:	Res., RW
14	:	:	:	Res., RW	:	:	:	Res., RW
15	bit 15, RW	bit 31, RW	bit 47, RW	Res., RW	bit 15, RW	bit 31, RW	bit 47, RW	Res., RW

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Bit	10GBASE-R PCS Jitter Test Pattern Control Register 3.42 (3.2Ah)	10GBASE-R PCS Test Pattern Error Counter Register 3.43 (3.2Bh)	PCS Vendor Specific 3.C000h	10GBASE-R PCS BER Timer Value Register 3.C001h	PCS Vendor Specific 3.C006h
0	pattern select, RW 1=zeros data pattern 0=LF data pattern	Test pattern error count, RO/NR count reset on read	64/66 encoder error detected, RO/LH 1 = error	BER Timer Counter Start Value	receive frame off- set, RO
1	test pattern select, RW 1 = square wave test pattern 0= pseudo random test pat- tern	LSB is bit 0 MSB is bit 15	RX descrambler bypass, RW 1 = bypass 0 = not bypassed (default)	default value = 100 d = 64 hex	
2	Receive test pattern enable, RW 1=enable receive test		TX scrambler bypass, RW 1=bypass 0 = not bypassed (default)		
3	Transmit test pattern enable, RW 1=enable transmit test		reset receive pcs, RW 0=reset 1=not reset, default Note: not self clearing		
4	Transmit PRBS31 generator enable, RW 0 = not enabled, default 1 = enable Tx PRBS31		reset transmit pcs, RW 0=reset 1=not reset, default Note: not self clearing		
5	Receive PRBS31 checker enable, RW 0 = not enabled, default 1 = enable Rx PRBS31 checker		PCS loopback data out ena- ble, RW 1=transmit data at TXOUT when in PCS loopback mode 0=transmit all a square wave when in PCS loopback mode		
6	Reserved, RO		Reserved, RO		
7	Reserved, RO		Reserved, RO		Reserved, RO
8	Reserved, RO	-	Reserved, RO		Reserved, RO
9	Reserved, RO	-	Reserved, RO		Reserved, RO
10	Reserved, RO		Reserved, RO		Reserved, RO
11	Reserved, RO		Reserved, RO		Reserved, RO
12	Reserved, RO		BER TEST enable, RW 0 = disabled, default 1 = enabled		Reserved, RO
13	Reserved, RO		Reserved, RO		Reserved, RO
14	Reserved, RO		BER Test in progress, RO 1 = BER Test in progress		Reserved, RO
15	Reserved, RO		BER Test Complete, RO/LH 1 = BER Test Completed		Reserved, RO



Bit	10GBASE-W Defect Mask Control Register 3.C010h
0	PCS: LOP-P Mask Enable ¹ , RW 1= defect does not propagate to PCS 0= defect propagates to PCS (default)
1	PCS: AIS-P Mask Enable ¹ , RW 1= defect does not propagate to PCS 0= defect propagates to PCS (default)
2	PCS: PLM-P Mask Enable ¹ , RW 1= defect does not propagate to PCS 0= defect propagates to PCS (default)
3	PCS: LOF Mask Enable ¹ , RW 1= defect does not propagate to PCS 0= defect propagates to PCS (default)
4	Tx RDI-P: PLM-P Mask Enable ² , RW 1= defect does not assert RDI-P 0= defect asserts RDI-P (default)
5	Tx RDI-P: LCD-P Mask Enable ² , RW 1= defect does not assert RDI-P 0= defect asserts RDI-P (default)
6	Tx RDI-P: AIS-P Mask Enable ² , RW 1= defect does not assert RDI-P 0= defect asserts RDI-P (default)
7	Tx RDI-P: LOP-P Mask Enable ² , RW 1= defect does not assert RDI-P 0= defect asserts RDI-P (default)
8	Tx RDI-L: AIS-L/LOS/LOF Mask Enable ² , RW 1= defect does not assert RDI-L 0= defect asserts RDI-L (default)
9	Tx RDI-L: WIS Sync Mask Enable ² , RW 1= defect does not assert RDI-L 0= defect asserts RDI-L (default)
10	Tx RDI-P: RDI-L Mask Enable ² , RW 1= RDI-L alarm does not trigger RDI-P alarm 0= defect asserts RDI-P (default)
15-11	Reserved, RO

1. By default, this defect propagates to the PCS layer of the device. The PCS will generate a local fault signal on the XAUI output to the upstream MAC.

2. When this defect is detected on the receive input, an RDI-x defect is sent in the transmit WIS overhead by default. When masked, the RDI-x defect is not sent.

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Bit	PCS Vendor Specific Packet Generator Control 3.C020	PCS Vendor Specific Packet Generator Send Data MSB 3.C021	PCS Vendor Specific Packet Generator Send Data LSB 3.C022	PCS Vendor Specific Packet Generator Send Control 3.C023
0	TX Packet Generator Enable ¹ , RW 0 = Disable, Default 1 = Enable	Lane 2 XGMII Data Byte, RW Default = 8'h00	Lane 0 XGMII Data Byte, RW Default = 8'h00	Lane 0 XGMII Control Bit, RW 0 = Data, Default 1 = Control
1	RX Packet Generator Enable ¹ , RW 0 = Disable, Default 1 = Enable			Lane 1 XGMII Control Bit, RW 0 = Data, Default 1 = Control
2	Reserved, RO	•		Lane 2 XGMII Control Bit, RW 0 = Data, Default 1 = Control
3	Reserved, RO			Lane 3 XGMII Control Bit, RW 0 = Data, Default 1 = Control
4	Packet Type, RW			Reserved, RO
5	00 = Data (fixed) 01 = Data (incremental) 10 = Control (fixed) 11 = Reserved Default = 00			Reserved, RO
6	Reserved, RO			Reserved, RO
7	Reserved, RO			Reserved, RO
8	Generator Mode, RW	Lane 3 XGMII Data Byte, RW	Lane 1 XGMII Data Byte, RW	Reserved, RO
9	00 = Idle ModeDefa01 = Burst Mode1010 = Continuous Mode11 = ReservedDefault = 00	Default = 8'h00	Default = 8'h00	Reserved, RO
10	Reserved, RO			Reserved, RO
11	Reserved, RO			Reserved, RO
12	Reserved, RO			Reserved, RO
13	Reserved, RO			Reserved, RO
14	Reserved, RO			Reserved, RO
15	Reserved, RO			Reserved, RO

1. When either packet generator is enabled, both Tx and Rx packet checkers will be automatically enabled.

Bit	PCS Vendor Specific	PCS Vendor Specific	PCS Vendor Specific
	Packet Generator	Packet Generator	Packet Generator
	Burst Size	Packet Size	IPG Size
	3.C024h	3.C025h	3.C026h
15:0	Burst Size, RW Default = 16'd256	Packet Size defined by XGMII columns, RW Default = 16'd5	IPG Size defined by XGMII columns, RW Default = 16'd1

Bit	PCS Vendor Specific Packet Checker Control 3.C030h	PCS Vendor Specific Packet Checker Expected Data MSB 3.C031h	PCS Vendor Specific Packet Checker Expected Data LSB 3.C032h	PCS Vendor Specific Packet Checker Expected Control 3.C033h
0	TX Packet Checker Enable ¹ , RW 0 = Disable, Default 1 = Enable	Lane 2 XGMII Data Byte, RW Default = 8'h00	Lane 0 XGMII Data Byte, RW Default = 8'h00	Lane 0 XGMII Control Bit, RW 0 = Data, Default 1 = Control
1	RX Packet Checker Enable ¹ , RW 0 = Disable, Default 1 = Enable			Lane 1 XGMII Control Bit, RW 0 = Data, Default 1 = Control
2	Reserved, RO			Lane 2 XGMII Control Bit, RW 0 = Data, Default 1 = Control
3	Reserved, RO			Lane 3 XGMII Control Bit, RW 0 = Data, Default 1 = Control
4	Packet Type, RW			Reserved, RO
5	00 = Data (fixed) 01 = Data (incremental) 10 = Control (fixed) 11 = Reserved Default = 00			Reserved, RO
6	Reserved, RO			Reserved, RO
7	Reserved, RO			Reserved, RO
15:8	Reserved, RO	Lane 3 XGMII Data Byte, RW Default = 8'h00	Lane 1 XGMII Data Byte, RW Default = 8'h00	Reserved, RO

1. Both Checkers On == (3.C020h.0=1) OR (3.C020h.1=1) OR (3.C030h.0=1) OR (3.C020h.0=1)



Bit	PCS Vendor Specific	PCS Vendor Specific	PCS Vendor Specific	PCS Vendor Specific
	RX Packet Checker	RX Packet Checker	TX Packet Checker	TX Packet Checker
	Error Counter	Packet Counter	Error Counter	Packet Counter
	3.C034h	3.C035h	3.C036h	3.C037h
15:0	Rx Error Detected Counter,	Rx Packet Received Counter,	Tx Error Detected Counter,	Tx Packet Received Counter,
	RO	RO	RO	RO
	cleared upon read	cleared upon read	cleared upon read	cleared upon read
	non-rollover	non-rollover	non-rollover	non-rollover

Bit	Extended Line Monitoring Control 3.CC00h	Extended Link Monitoring Status 1 3.CC01h	Extended Link Monitoring Status 2 3.CC02h	Extended Link Monitoring Pseudo- Random Block Feature Control 3.CC03h	Tx Pseudo- Random Block Counter 3.CC04h
0	Extended Link Monitoring TX Enable RW 0 = disabled, default 1 = enabled (initiates query)	Query_successful FLAG (AMCC Part detected), RO 0 = No AMCC part at remote end 1 = AMCC part at remote end	PHY Query Trans- mitted Counter, RO Non-rollover, cleared on read	Pseudo-random Block TX enable, RW 0 = disabled, default 1 = enabled (begins trans- mission)	Transmitted Pseudo- Random Block coun- ter, RO Rollover, cleared on read
1	Extended Link Monitoring RX Enable RW 0 = disabled, default 1 = enabled (enables query response)	Reserved, RO		Pseudo-random Block RX enable, RW 0 = disabled (default) 1 = enabled (enables checker)	
2	Reserved, RO	Reserved, RO		Pseudo-random single Block corrupt, RW 0 = disabled, default 1 = enabled (sends single corrupted block)	
3	Reserved, RO	Reserved, RO		Reserved, RO	
4	Reserved, RO	Reserved, RO		Reserved, RO	
5	Reserved, RO	Reserved, RO		Reserved, RO	
6	Reserved, RO	Reserved, RO		Reserved, RO	
7	Reserved, RO	Reserved, RO		Reserved, RO	
15:8	Reserved, RO	Reserved, RO	PHY Query Received Counter, RO Non-rollover, cleared on read	Reserved, RO	

Bit	Rx Pseudo-Random Block Counter 3.CC05h	Rx Pseudo-Random Block Error counter 3.CC06h
15:0	Received Pseudo-Random Block counter, RO Non-rollover latched on read cleared on read of 3.CC06h	Received Pseudo-Random Block Error counter, RO Non-rollover latched on read of 3.CC05h cleared on read

Bit	RMDIO Control 3.CC08h	RMDIO Device Address Control 3.CC09h	RMDIO Register Address Control 3.CC0Ah
0	PHY RMDIO feature TX enable, RW 0 = disabled, default 1 = enabled	MDIO Device Address, RW 5'h01 = PMA/PMD (default) 5'h02 = WIS	MDIO Register Address, RW Default value is 16'h0000
1	PHY RMDIO feature RX enable, RW 0 = disabled 1 = enabled, default	5'h03 = PCS 5'h04 = XGXS other = Unsupported device address	
2	PHY RMDIO Remote Read Request, RW 1= Remote Read Requested 0= No Action (default)		
3	PHY RMDIO Remote Write Request ^{1 2} , RW 1= Remote Write Requested 0= No Action (default)		
4	Reserved, RO		
5	Reserved, RO		
6	Reserved, RO	Reserved, RO	
7	Reserved, RO	Reserved, RO	
8	Reserved, RO	Reserved, RO	
9	Reserved, RO	Reserved, RO	
10	Reserved, RO	Reserved, RO	
11	Reserved, RO	Reserved, RO	
12	Reserved, RO	Reserved, RO	
13	Reserved, RO	Reserved, RO	
14	Reserved, RO	Reserved, RO	
15	Reserved, RO	Reserved, RO	

1. RMDIO write request has a lower priority than RMDIO read request. If both are activated simultaneously, the read request will be sent first.

2. The RMDIO write feature is password protected to prevent accidental writes. To enable RMDIO writes, the correct password must be written to Register 3.CC0Fh. Please contact AMCC for further information.



Bit	RMDIO Status 3.CC0Bh	RMDIO Received Data 3.CC0Ch	RMDIO Write Data 3.CC0Eh	Unlock RMDIO Write Feature 3.CC0Fh
0	RMDIO Read Request Sent, RO/LH	RMDIO Received Data, RO	RMDIO write Data Value, RW	Password to enable
1	RMDIO Write Request Sent, RO/LH			RMDIO write fea- ture, RW
2	RMDIO Read Response Received, RO/LH			
3	RMDIO Write Response Received, RO/LH			
4	Reserved, RO			
5	Reserved, RO			
6	Reserved, RO			
7	Reserved, RO			
8	Reserved, RO			
9	Reserved, RO			
10	Reserved, RO			
11	Reserved, RO			
12	Reserved, RO			
13	Reserved, RO			
14	Reserved, RO			
15	Reserved, RO			



13.4 PHY_XS Registers (Device 4)

Bit	PHY_XS Control 1 4.0	PHY_XS Status 1 4.1
0	Reserved, RO	Reserved, RO
1	Reserved, RO	Power down capability, RO 1 = ability to power down
2	Speed Selection, RO 0 = operation at 10 Gb/s	PHY XS Transmit link status, RO/LL 1=transmit link up ¹
3	Speed Selection, RO 0 = operation at 10 Gb/s	Reserved, RO
4	Speed Selection, RO 0 = operation at 10 Gb/s	Reserved, RO
5	Speed Selection, RO 0 = operation at 10 Gb/s	Reserved, RO
6	Speed Selection, RO 1 = operation at 10 Gb/s and above	Reserved, RO
7	Reserved, RO	Local fault, RO 1=fault condition ²
8	Reserved, RO	Reserved, RO
9	Reserved, RO	Reserved, RO
10	Reserved, RO	Reserved, RO
11	Power Down, RW 0 = don't power down 1 = power down ³	Reserved, RO
12	Reserved, RO	Reserved, RO
13	Speed Selection, RO 1 = operation at 10 Gb/s and above writes ignored	Reserved, RO
14	loopback, RW 1= enable PHY_XS loopback	Reserved, RO
15	Reset RW/SC 1= reset	Reserved, RO

1. PHY_XS transmit link status = latched low version of MDIO reg 4.24.12, transmit lanes aligned

2. PHY_XS Local fault = PHY_XS transmit fault (MDIO reg 4.8.11) + PHY_XS receive fault (MDIO reg 4.8.10)

3. PHY_XS power down enabled will power down the whole device with the exception of MDIO access



Bit	PHY_XS Identifier 4.2	PHY_XS Identifier 4.3
15:0	PHY_XS Identifier ¹ , RO 1100_0010_0000_0000	PHY_XS Identifier, RO 0000_0000_0010_0101

1. The PHY_XS unique identifier is the AMCC identifier.

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Bit	PHY_XS Speed Ability Register 4.4	PHY_XS Devices in Package Register 4.5	PHY_XS Devices in Package Register 4.6	PHY_XS Status 2 Register 4.8
0	1, PCS is capable of operat- ing at 10 Gb/s, RO	0, Clause 22 registers not present in package, RO	Reserved, RO	Reserved, RO
1	Reserved, RO	1, PMA/PMD present in package, RO	Reserved, RO	Reserved, RO
2	Reserved, RO	1, WIS present in package (QT2032), RO 0, WIS not present in package (QT2022), RO	Reserved, RO	Reserved, RO
3	Reserved, RO	1, PCS present in package, RO	Reserved, RO	Reserved, RO
4	Reserved, RO	1, PHY_XS present in package, RO	Reserved, RO	Reserved, RO
5	Reserved, RO	0, DTE_XS not present in package, RO	Reserved, RO	Reserved, RO
6	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO
7	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO
8	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO
9	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO
10	Reserved, RO	Reserved, RO	Reserved, RO	Receive local fault ^{1 2} ,RO/LH 1=fault condition linked to 1.9003h.0
11	Reserved, RO	Reserved, RO	Reserved, RO	Transmit local fault ^{3 2} , RO/LH 1=fault condition linked to 1.9004h.0
12	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO
13	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO
14	Reserved, RO	Reserved, RO	Reserved, RO	0=Device responding at this address, RO
15	Reserved, RO	Reserved, RO	0, vendor specific device not present in package, RO	1=Device responding at this address, RO

1. PHY_XS Receive Local fault condition = (*xlock* = XAUI pll locked), where *xlock* = 4.C000h.3

2. This bit is linked to an MDIO latched high diagnostic alarm register bit. When either register is read both bits will be cleared.

3. PHY_XS Transmit Local fault condition = (Lane deskew), where lane deskew = 4.24.12



Bit	10G PHY XGXS Lane Status Register 4.24 (4.18h)	PHY_XS Test Control register 4.25 (4.19h)
0	Lane 0 sync, RO 1=lane is in sync	Test Pattern Select, RW bit 1 bit 0
1	Lane 1 sync, RO 1=lane is in sync	1 1 reserved 1 0 mixed speed 0 1 low speed 0 0 high speed
2	Lane 2 sync, RO 1=lane is in sync	XGXS Receive Test Pattern Enable ¹ , RW 0 = disable 1 = enable
3	Lane 3 sync, RO 1=lane is in sync	Reserved, RO
4	Reserved, RO	Reserved, RO
5	Reserved, RO	Reserved, RO
6	Reserved, RO	Reserved, RO
7	Reserved, RO	Reserved, RO
8	Reserved, RO	Reserved, RO
9	Reserved, RO	Reserved, RO
10	PHY_XS loopback ability, RO 1 = capable of PHY_XS loopback	Reserved, RO
11	PHY_XS pattern testing ability, RO 1 = capable of PHY_XS pattern testing	Reserved, RO
12	XGXS transmit lanes aligned, RO 1= lanes aligned	Reserved, RO
13	Reserved, RO	Reserved, RO
14	Reserved, RO	Reserved, RO
15	Reserved, RO	Reserved, RO

1. XGXS test pattern precedence: test(4.25.2), PRBS(4.C000h.10), CJPAT(4.C000h.8), CRPAT(4.C000h.9).

Bit	PHY_XS Vendor Specific Register 4.C000h	PHY_XS Vendor Specific Register 4.C001h
0	Transmit XGXS reset, RW 0=reset 1= not reset, default Note: not self clearing	XAUI Lane 0 PRBS Error, RO/LH 1 = PRBS Error
1	Receive XGXS reset, RW 0=reset 1= not reset, default Note: not self clearing	XAUI Lane 0 PRBS Error, RO/LH 1 = PRBS Error
2	Reserved, RO	XAUI Lane 0 PRBS Error, RO/LH 1 = PRBS Error
3	Receive path XAUI PLL locked <i>xlock</i> , RO 1=locked	XAUI Lane 0 PRBS Error, RO/LH 1 = PRBS Error
4	<i>xtxlock<0></i> = lane 0 lock, RO 1=lane 0 in lock	Reserved, RO
5	<i>xtxock<1></i> = lane 1 lock, RO 1=lane 1 in lock	Reserved, RO,



Bit	PHY_XS Vendor Specific Register 4.C000h	PHY_XS Vendor Specific Register 4.C001h
6	<i>xtxlock<2></i> = lane 2 lock, RO 1=lane 2 in lock	Reserved, RO
7	<i>xtxock</i> <3> = lane 3 lock, RO 1=lane 3 in lock	Reserved, RO
8	CJPAT Generator Enable ¹ , RW 0 = disable, default 1 = enable	Reserved, RO
9	CRPAT Generator Enable ¹ , RW 0 = disable, default 1 = enable	Reserved, RO
10	XAUI PRBS Generator Enable ¹ , RW 0 = Generator Disabled (default) 1 = Generator Enabled	Reserved, RO
11	XAUI PRBS Checker Enable, RW 0 = Checker Disabled (default) 1 = Checker Enabled	Reserved, RO
12	TxXMONCV source 0 = lane 3 recovered clock (default) 1 = lane 3 recovered data (XCKGN VCO CV at TxXMONCV)	Reserved, RO
13	XAUI network loopback data override, RW 1=transmit data (default) 0=transmit idles	XAUI version, RO
14	XAUI system loopback enable, RW 0= loopback disabled (default) 1= loopback enabled	Reserved, RO
15	XAUI system loopback data override, RW 1=transmit data 0=transmit all 1's (default)	Reserved, RO

1. XGXS test pattern precedence: test(4.25.2), PRBS(4.C000h.10), CJPAT(4.C000h.8), CRPAT(4.C000h.9).

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Bit	PHY_XS Vendor Specific Register 4.C002h	
5:0	Reserved, RO	
6	XGXS Rx rate adjust underflow ¹ , RO/LH 1 = underflow linked to 1.9003h.6	
7	XGXS Rx rate adjust overflow ¹ , RO/LH 1 = overflow linked to 1.9003h.6	
8	XGXS Tx rate adjust underflow ¹ , RO/LH 1 = underflow linked to 1.9004.2	
9	XGXS Tx rate adjust overflow ¹ , RO/LH 1 = overflow linked to 1.9004.2	
11:10	Reserved, RO	
12	XGXS Rx Rate Inserted Idle Flag, RO/LH	
13	XGXS Rx Rate Removed Idle Flag, RO/LH	
14	XGXS Tx Rate Inserted Idle Flag, RO/LH	
15	XGXS Tx Rate Removed Idle Flag, RO/LH	

1. This bit is linked to an MDIO latched high diagnostic alarm register bit. A read of either register clears both.

Bit	PHY_XS Vendor Specific Register 4.C003h	PHY_XS Vendor Specific Register 4.C004h
3:0	XAUI Lane 0 Sync offset, RO	XAUI Lane 0 Align offset, RO
7:4	XAUI Lane 1 Sync offset, RO	XAUI Lane 1 Align offset, RO
11:8	XAUI Lane 2 Sync offset, RO	XAUI Lane 2 Align offset, RO
15:12	XAUI Lane 3 Sync offset, RO	XAUI Lane 3 Align offset, RO

Bit	PHY_XS Vendor Specific Register 4.C005h	PHY_XS Vendor Specific Register 4.C006h
0	Reserved, RO	XAUI Lane 0 8b/10b Decode Error, RO/LH 1 = Decoding Error
1	Reserved, RO	XAUI Lane 1 8b/10b Decode Error, RO/LH 1 = Decoding Error
2	Reserved, RO	XAUI Lane 2 8b/10b Decode Error, RO/LH 1 = Decoding Error
3	Reserved, RO	XAUI Lane 3 8b/10b Decode Error, RO/LH 1 = Decoding Error
11:4	Reserved, RO	Reserved, RO
12	XAUI Lane 0 Clock Phase Error, RO/LH 1 = Clock Phase Error	Reserved, RO
13	XAUI Lane 1 Clock Phase Error, RO/LH 1 = Clock Phase Error	Reserved, RO
14	XAUI Lane 2 Clock Phase Error, RO/LH 1 = Clock Phase Error	Reserved, RO
15	XAUI Lane 3 Clock Phase Error, RO/LH 1 = Clock Phase Error	Reserved, RO

Bit	PHY_XS Vendor Specific Register 4.C007h	
1:0	XAUI analog loopback lane select (to RxXAUI3)Bit 0Bit 1D0TxXAUI0 (default)01TxXAUI110TxXAUI211TxXAUI3	
2	Analog XAUI Loopback Enable, RW 0 = Disabled (default) 1 = Enabled	
3	Analog XAUI Loopback Clock Select, RW 0 = Loopback Lane Data (default) 1 = Loopback Lane Clock	
7:4	Reserved, RO	
8	Idle decoding disable, RW 0 = enable (default) 1 = disable	
15:9	Reserved, RO	

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Bit	PHY_XS Vendor Specific AMCC Test Patterns Control Register 4.C010h	PHY_XS Vendor Specific AMCC Test Patterns Programmable Value Register 4.C011h
0	Enable XAUI Lane 0 for AMCC Test Pattern 0 = Disable, Default 1 = Enable	AMCC Test Pattern Programmable Value, RW
1	Enable XAUI Lane 1 for AMCC Test Pattern 0 = Disable, Default 1 = Enable	
2	Enable XAUI Lane 2 for AMCC Test Pattern 0 = Disable, Default 1 = Enable	
3	Enable XAUI Lane 3 for AMCC Test Pattern 0 = Disable, Default 1 = Enable	
4	Select AMCC Test Pattern on XAUI Lane 0 0 = Static, Default 1 = User Defined Value	
5	Select AMCC Test Pattern on XAUI Lane 1 0 = Static, Default 1 = User Defined Value	
6	Select AMCC Test Pattern on XAUI Lane 2 0 = Static, Default 1 = User Defined Value	
7	Select AMCC Test Pattern on XAUI Lane 3 0 = Static, Default 1 = User Defined Value	
8	Reserved, RO	
9	Reserved, RO	
15:10	Reserved, RO	Reserved, RO



Bit	PHY_XS Vendor Specific VCO Monitor Control Register 4.C020h	
0	Force XAUI Driver VCO 0 = Disable, Default 1 = Force VCO	
1	Select XAUI Driver VCO Forced Frequency 0 = MIN Freq, Default 1 = MAX Freq	
2	Force XAUI CDR VCO 0 = Disable, Default 1 = Force VCO	
3	Select XAUI CDR VCO Forced Frequency 0 = MIN Freq, Default 1 = MAX Freq	
4	Monitor XAUI Lane 0 CDR Control Voltage ¹ 0 = Disable, Default 1 = Monitor Signal	
5	Monitor XAUI Lane 1 CDR Control Voltage ¹ 0 = Disable, Default 1 = Monitor Signal	

Bit	PHY_XS Vendor Specific VCO Monitor Control Register 4.C020h	
6	Monitor XAUI Lane 2 CDR Control Voltage ¹ 0 = Disable, Default 1 = Monitor Signal	
7	Monitor XAUI Lane 3 CDR Control Voltage ¹ 0 = Disable, Default 1 = Monitor Signal	
8	Override xtxlock[0] 0 = No Effect, Default 1 = Set xtxlock[0] to 1	
9	Override xtxlock[1] 0 = No Effect, Default 1 = Set xtxlock[1] to 1	
10	Override xtxlock[2] 0 = No Effect, Default 1 = Set xtxlock[2] to 1	
11	Override xtxlock[3] 0 = No Effect, Default 1 = Set xtxlock[3] to 1	
12	Override xrxlock 0 = No Effect, Default 1 = Set xrxlock to 1	
13	Spare Reg, RW	
14	Spare Reg, RW	
15	Spare Reg, RW	

1. When enabled, the TxXMONCV output signal will monitor the selected lane. Do not enable more than one lane at a time.

Bit	PHY_XS Vendor Specific	PHY_XS Vendor Specific	PHY_XS Vendor Specific	PHY_XS Vendor Specific
	XAUI Lane 0 Error	XAUI Lane 1 Error	XAUI Lane 2 Error	XAUI Lane 3 Error
	Counter	Counter	Counter	Counter
	Register 4.C030h	4.C031h	4.C032h	4.C033h
7:0	XAUI Lane 0 Error Counter,	XAUI Lane 1 Error Counter,	XAUI Lane 2 Error Counter,	XAUI Lane 3 Error Counter,
	RO	RO	RO	RO
	cleared upon read	cleared upon read	cleared upon read	cleared upon read
	non-rollover	non-rollover	non-rollover	non-rollover
	Counts 8b/10b decode Errors			
	in functional mode.	in functional mode.	in functional mode.	in functional mode.
	Counts PRBS errors when			
	XAUI PRBS Checker is ena-			
	bled.	bled.	bled.	bled.
15:8	Reserved, RO	Reserved, RO	Reserved, RO	Reserved, RO

applied micro



Bit	TX Ratecomp Override Enable Register 4.C040h
0	Reserved, RO
15:1	Reserved, RO

Bit	TX Ratecomp Control1 Register 4.C041h	TX Ratecomp Control2 Register 4.C042h
7:0	TX Rate Control1 Value (RW)	TX Rate Control2 Value (RW)
15:8	Reserved, RO	Reserved, RO

Bit	TX Ratecomp Control3 Register 4.C043h	TX Ratecomp Control4 Register 4.C044h
7:0	TX Rate Control3 Value (RW)	TX Rate Control4 Value (RW)
15:8	Reserved, RO	Reserved, RO

Bit	TX Ratecomp Control5 Register 4.C045h	
7:0	TX Rate Control5 Value (RW)	
15:8	Reserved, RO	

Bit	Ratecomp Override Enable Register 4.C050h	
0	Rate Override Enable (RW) ¹ 0 = Override Disabled (default) 1 = Override Enabled (registers 4.C041 - 4.C055 are active)	
15:1	Reserved, RO	

1. To avoid unexpected behavior, the Override Enable should be activated after all Ratecomp Control registers have been programmed.

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Bit	RX Ratecomp Control1 Register 4.C051h	RX Ratecomp Control2 Register 4.C052h
7:0	RX Rate Control1 Value (RW)	RX Rate Control2 Value (RW)
15:8	Reserved, RO	Reserved, RO

Bit	RX Ratecomp Control3 Register 4.C053h	RX Ratecomp Control4 Register 4.C054h
7:0	RX Rate Control3 Threshold Value (RW)	RX Rate Control4 Threshold Value (RW)
15:8	Reserved, RO	Reserved, RO

Bit	RX Ratecomp Control5 Register 4.C055h
7:0	RX Rate Control5 Value (RW)
15:8	Reserved, RO

14 AC and DC Parameters

Table 54: Absolute Maximum Ratings

Parameter	Description	Min	Тур	Мах	Units	Conditions
Ts	Storage temperature	-40		150	°C	
Тј	Junction Temperature			125	°C	Under bias
	1.2V supply voltages	-0.6		1.5	V	
	Voltage on any CML input pin	-0.6		1.5	V	on both inputs
	Voltage on any CML output pin	-0.6		1.5	V	
	Voltage on any CMOS pin	-0.6		3.6	V	
	ESD on RXIN, TXOUT, XAUI I/O pins	-1000		1000	V	human body model
	ESD on low-speed digital I/O, power supply	-2000		2000	V	human body model

Absolute maximum ratings are limits which, if exceeded, may cause permanent damage to the device or degrade device reliability. Absolute maximum ratings are not the normal operating conditions of the device. Functional operation should be restricted to the normal operating conditions. All voltages are specified with respect to GND unless

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otherwise specified.

Table 55: Operating Conditions

Parameter	Description	Min	Тур	Мах	Units	Conditions
Та	Ambient temperature	0		80	°C	
	1.2V supply voltages	1.09	1.2	1.26	V	
Ρ	Power consumption in XFP mode (XFP = 1)		0.95	1.26	W	WIS enabled XAUI outputs - RxXLEVEL = $16.9k\Omega$ Fiber output - TxLEVEL = $4.53k\Omega$ TXPLLOUT powered up; No monitor outputs enabled; No loopbacks enabled; Equalization option on 10Gb/s input
			0.90	1.19		WIS disabled Other conditions as above.
Ρ	Power consumption in XENPAK mode (XFP=0)		1.02	1.39 1.34	W	WIS enabled XAUI outputs - RxXLEVEL = $4.53k\Omega$ Fiber output - TXLEVEL = $4.53k\Omega$ TXPLLOUT powered down; No monitor outputs enabled; No loopbacks enabled;
			0.96	1.28		WIS disabled Other conditions as above.
	Power consumption in Low Power Mode (TXON = 0)		0.2		W	
I _{XV1P2}	Current from supply XV1P2		280	333 311	mA	
I _{RV1P2}	Current from supply RV1P2		224	240 260	mA	
I _{TV1P2}	Current from supply TV1P2		152	200 175	mA	
I _{TV1P2A}	Current from supply TV1P2A		20	25	mA	
I _{RV1P2A}	Current from supply RV1P2A		20	25	mA	
I _{COREVCC}	Current from supply COREVCC			341	mA	
	External Supply filtering					See "Power Supply Filtering and Decoupling" on page 210.
	Voltage drop due to filtering: XV1P2, RV1P2 or TV1P2 relative to COREVDD			45	mV	
	Voltage drop due to filtering: TV1P2A relative to TV1P2			15	mV	
	Voltage drop due to filtering: RV1P2A relative to RV1P2			15	mV	

Table 56:	190B	LBGA	Package	Constants
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Parameter	Description	Min	Тур	Мах	Units	Conditions/Notes
θ^{JC}	Junction-to-Case Thermal Resistance		12.3		°C/W	
θ_{JB}	Junction-to-Ball Thermal Resistance		22.7		°C/W	Calculated using boundary conditions defined in JESD51-8.
θ_{JA}	Junction-to-Ambient Thermal Resistance		32.7		°C/W	With natural convection only, no heat sink or air flow
			29.5			1 m/s air flow, no heat sink.
			28.2			2 m/s air flow, no heat sink.

Note that θ_{JB} was calculated using boundary conditions defined in JESD51-8. Note that θ_{JA} was calculated using a 1S2P multi-layer JEDEC standard PCB (FR-4, 4" x 4", 0.063" thick) under forced convection with 0.5m/s (100LFM) airflow.

Parameter	Description	Min	Тур	Мах	Units	Conditions
Vol	output low voltage			0.2	V	lol = 4mA
loff	Open-drain output off-state leakage			2.5	μA	at 2.5V
lol	output low current	8			mA	Vol = 0.6V
Vih	input high voltage level	0.84			V	3.3V tolerant
Vil	input low voltage level			0.36	V	
Rpd	input pad pulldown resistance See Table 3 on page 13 for a list of pads with pulldowns	30	50	95	kΩ	
Rpu	input pad pullup resistance	21	36	49	kΩ	TDI,TMS
	See Table 3 on page 13 for a list of pads with pullups	14	24	46		TRST_N, RESETN
		30	50	95		all other pads with pullups
Hyst	hysteresis		80		mV	Applies to RESETN, TRST_N, EEPROM_SCL and EEPROM_SDA pins
			35			Applies to MDC, TMS, TDCC, TCK and TDI pins
Cio	input / output capacitance		3.5	5	pF	Vio(dc) = 0.6V

Table 57: General CMOS I/O DC Parameters

Table 58: LED1, LED2, LED3 Output DC Parameters

Parameter	Description	Min	Тур	Max	Units	Conditions/Notes
Vol	output low voltage level			0.4	V	sinking 10mA

Table 59: JTAG AC Parameters

Parameter	Description	Min	Тур	Мах	Units	Conditions/Notes
fmax	TCK operating frequency			10	MHz	
Tsu	TDI, TMS input setup time requirement			10	ns	wrt TCK rising edge. See Note 1 ¹ .
Thd	TDI, TMS input hold time requirement			10	ns	wrt TCK rising edge. See Note 1.
Tdel	TDO output propagation delay			30	ns	See Note 1 and 2^2 . 330ohm pullup to 1.2V, or 750ohms to 3.3V, Cload = 50pF.

- 1. Timing is measured from the point where signals cross a voltage level equal to COREVDD/2.
- 2. For a rising TDO output, the delay is measured to a crossing level of 0.7*Vpu. For a falling TDO output, the delay is measured to a crossing level of 0.3*Vpu. TDO is generated on the falling edge of TCK. TDI is clocked in on the rising edge of TCK. Therefore TDO propagation delay must not exceed half a TCK period minus the TDI setup time requirement.

Table 60: MDIO 1.2V Bidirectional Pad DC Parameters

Parameter	Description	Min	Тур	Max	Units	Conditions/Notes
Voh	output high voltage			Vpu	V	loh = -100μA
loff	Open-drain output off-state leakage			2.5	μA	at 2.5V
1-1		5.5				Vol = 0.2V (for 1.2V operation)
lol	output low current	8			mA	Vol = 0.6V (for 3.3V operation)
Vol	output low voltage			0.2	V	Vpu = 1.2V with 180Ω pullup resistor
Vih	input high voltage level	0.84			V	3.3V tolerant
Vil	input low voltage level			0.36	V	
Vpu	pullup supply voltage		1.2		V	
Cin	Input capacitance			5	pF	
Cload	Load capacitance			470	pF	
Rpu	Pullup Resistance	180			Ω	with 1.2V pullup voltage
		600 500				with 3.3V pullup voltage

Table 61: MDIO AC Parameters

Parameter	Description	Min	Тур	Мах	Units	Conditions	
Thold	MDIO data input hold time requirement			10	ns	wrt MDC rising edge	
Tsetup	MDIO data input setup time requirement			10	ns	wrt MDC rising edge	
	OPERATION UNDER HIGH CAPACITIVE LOAD (1.2V pullup)						

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Table 61: MDIO AC Parameters

Parameter	Description	Min	Тур	Мах	Units	Conditions
Tdelay	delay from MDC rising edge to MDIO data output edge See Note.	0		300	ns	RPU=400Ω; Cload=470pF
Fmax	MDC clock rate			3.125	MHz	RPU=400Ω; Cload=470pF
	MDC high and low times	160			ns	RPU=400Ω; Cload=470pF
	OPERATION UNDER LOW CAPACITIVE LO	OAD (1.2V	pullup)			
Tdelay	delay from MDC rising edge to MDIO data output edge See Note.	0		32	ns	RPU=180Ω; Cload=100pF
Fmax	MDC clock rate			25.0	MHz	RPU=180Ω; Cload=100pF
	MDC high and low times	20			ns	RPU=180 Ω ; Cload=100pF

Table 62: RDCC, RDCC_CLK, TDCC, TDCC_CLK AC Parameter Table

Parameter	Description	Min	Тур	Мах	Units	Conditions
fRDCC, fTDCC	output clock frequency		1.9375		MHz	
tRDCC_delay	RDCC output data delay wrt RDCC_CLK falling edge			0.1	μS	See Note 1.
tTDCC_setup	TDCC input data setup time wrt TDCC_CLK falling edge	0.1			μS	See Note 2.
tTDCC_hold	TDCC input data hold time wrt TDCC_CLK falling edge	0.1			μs	See Note 2.
Note 1: For an	output rising edge, the delay is measured to a	crossing le	evel of 0.7*	/pullup. Fo	r an output	falling edge, the delay is

Note 1: For an output rising edge, the delay is measured to a crossing level of 0.7*Vpullup. For an output falling edge, the delay is measured to a crossing level of 0.3*Vpullup.

Note 2: Input timing is measured from the point where input signals cross a voltage level equal to COREVDD/2.

Table 63: EEPROM_SDA & EEPROM_SCL 3.3V Bidirectional Pad DC Parameters

Parameter	Description	Min	Тур	Max	Units	Conditions
Voh	output high voltage			Vpu	V	3.3V tolerant
Vol	output low voltage			0.2	V	sinking 3mA
Vih	input high voltage level	0.84			V	
Vil	input low voltage level			0.4	V	
Cin	input capacitance			5	pF	



Table 63: EEPROM_SDA & EEPROM_SCL 3.3V Bidirectional Pad DC Parameters

Parameter	Description	Min	Тур	Max	Units	Conditions
Cload	external load capacitance			470	pF	
Rpu	external pullup resistance to Vpu		15		kΩ	

Table 64: EEPROM Interface AC Parameters

Parameter	Description	Min	Тур	Max	Units	Conditions
fSCL	EEPROM_SCL clock frequency		37		kHz	
tlow	EEPROM_SCL low time	5	13.5		μS	
thigh	EEPROM_SCL high time	5	13.5		μS	
ttrans	SDA and SCL rise and fall time			300	ns	
tdelay	SDA output delay wrt SCL	5	6.75	8	μS	
tSDA_setup	SDA setup time wrt SCL			1	μS	
tSDA_hold	SDA hold time wrt SCL			1	μS	

Table 65: RXPLLOUT Characteristics

Parameter	Description	Min	Тур	Мах	Units	Conditions
	output swing		400		mVpp	per side

Table 66: EREFCLK, TXPLLOUT¹, SREFCLK² and VCXOI² Input Specifications

Parameter	Description	Min	Тур	Мах	Units	Conditions			
Zse	clock single-ended input impedance	40	50	60	Ω				
Zd	clock differential input impedance	80	100	120	Ω				
	Differential input clock amplitude	400	900	1600	mVpp	AC coupled			
	Duty cycle	40	50	60	%				
Tr/Tf	Rise/Fall time	200	250	1250	ps	20-80%			
f _{EREF}	Frequency		156.25		MHz	10GE application			
			159.375	-		10GFC application			
f _{SREF}			155.52 or 622.08		MHz	WIS applications			
f _{tolREF}	frequency tolerance ³	-100		+100	ppm				
	622MHz Reference clock:								

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Parameter	Description	Min	Тур	Мах	Units	Conditions
	single side-band phase noise @ 1kHz			-85	dBc/Hz	To meet SONET jitter
	single side-band phase noise @ 10kHz			-105	dBc/Hz	requirements.
	single side-band phase noise @ 100kHz			-125	dBc/Hz	
	single side-band phase noise @ 1MHz			-130	dBc/Hz	
	single side-band phase noise @ 10MHz			-130	dBc/Hz	-
	155/156/159 MHz Reference clock:	1	I			
	single side-band phase noise @ 1kHz			-105	dBc/Hz	To meet SONET jitter
	single side-band phase noise @ 10kHz			-125	dBc/Hz	- requirements. -
	single side-band phase noise @ 100kHz			-140	dBc/Hz	
	single side-band phase noise @ 1MHz			-140	dBc/Hz	
	single side-band phase noise @ 10MHz			-140	dBc/Hz	

Table 66: EREFCLK, TXPLLOUT¹, SREFCLK² and VCXOI² Input Specifications (Continued)

1. Applies when TXPLLOUT configured as an input.

2. QT2032 only.

3. The device will work properly in WAN mode with +-100ppm frequency tolerance. However, SONET compatible applications require a +-20ppm tolerance.

Table 67: XAUI Input Interface

Parameter	Description	Min	Тур	Мах	Units	Conditions
	BAUD Rate See Note 1.		3.125		Gb/s	For 10GE, where f _{EREF} = 156.25 MHz
			3.1875			For 10GFC, where f _{EREF} = 159.375 MHz
	BAUD Rate tolerance	-100		+100	ppm	
	Differential input amplitude and Input Compliance Mask	200		1600	mVpp	see figure 46 on page 194
	Differential input impedance		100		Ω	
S11D	Differential return loss (referenced to 100Ω) Common mode return loss (referenced to 25Ω)	10 6			dB dB	100MHz to 2.5GHz
	Input Differential Skew			75	ps p-p	at crossing point
	Jitter amplitude tolerance deterministic jitter deterministic + random jitter total jitter	0.37 0.55 0.55 + Figure 45			UI pp	all jitter sources combined
Note 1: Baud r	ate is specified relative to the 10GE or 10	OGFC reference	clock frequ	iency in 1	Table 66 o	n page 191

Figure 45: XAUI Input Sinusoidal Jitter Tolerance Mask

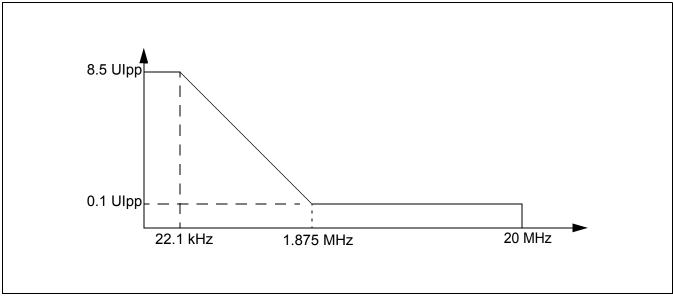


Figure 46: XAUI Driver Far End Template

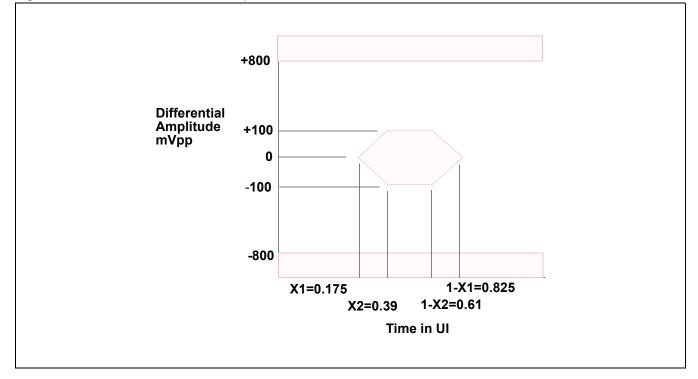


Table 68: XAUI Driver Characteristics

Parameter	Description	Min	Тур	Max	Units	Conditions						
	BAUD Rate		3.125		Gb/s	For 10GE, where f _{EREF} = 156.25 MHz						
	See Note 3.		3.1875	-		For 10GFC, where f _{EREF} = 159.375 MHz						
	Differential Eye Height (opening) See Note 1.	870	1000		mVpp	4.53k Ω @ RxXLEVEL (module application)						
			300		mVpp	16.9k Ω @ RxXLEVEL (XFP application)						
	Transition times	40		100	ps	20%-80%. See Note 4.						
	Total Output jitter, TJ			0.35	UI	no pre-equalization						
	Output Deterministic jitter, DJ			0.17	UI	no pre-equalization						
	Output differential skew			15	ps	measured from the crossings of the eyes for P vs. N outputs						
	Differential output impedance		100		Ω	DC						
S22D	Differential output return loss (referred to 100Ω)	10			dB	312.5 to 625 MHz						
S22D	Differential output return loss (referred to 100Ω)	see eqn in Note 2			dB	625MHz to 3.125GHz						
						ude will meet the XAUI near-end template 00mVpp differential for minimum power.						
Note 2. For 62	25MHz < freq < 3.125GHz, S22D =	specified in IEEE 802.3. For XFP line card application, output level can be adjusted down to 300mVpp differential for minimum power. Note 2. For 625MHz < freq < 3.125GHz, S22D = -10 + 10log(freq/625) dB										



Table 68: XAUI Driver Characteristics

Parameter Description Min Typ Max Units Conditions									
Note 3: Baud rate is specified relative to the reference clock frequency in Table 66 on page 191									
Note 4: Measured using a low-frequency square-wave pattern to allow for settling of the waveform resulting in an accurate topline and baseline reference.									



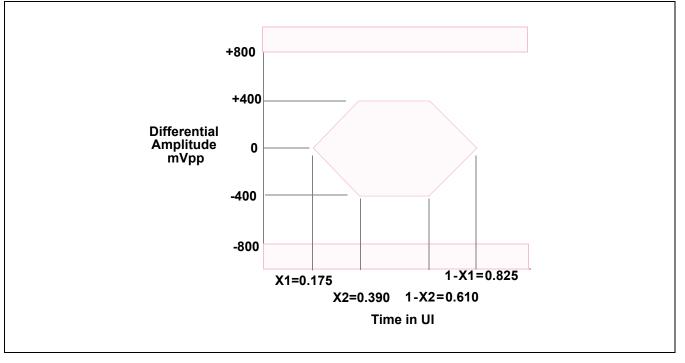


Table 69: Serial Receiver Specifications

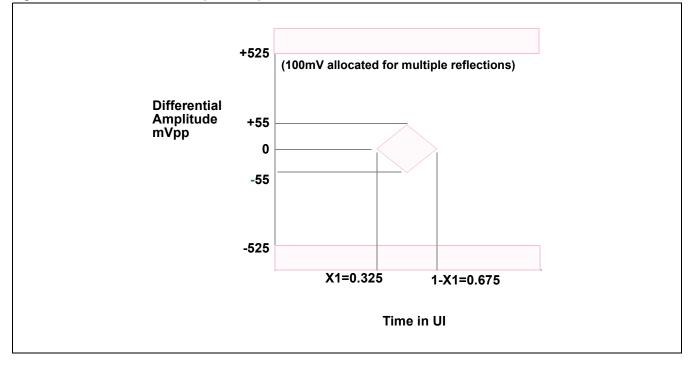
Parameter	Description	Min	Тур	Мах	Units	Conditions
	Nominal bit rate See Note 4.		10.3125 10.51875		Gb/s	10GE applications 10GFC applications
			9.95328	-		WIS applications
	BAUD rate tolerance	-100		+100	ppm	
Zse	Single-ended input impedance		50		Ω	
Zd	Differential input impedance		100		Ω	
Zm	Input impedance mismatch			5	%	
	Stressed input amplitude p-p	10		400	mVpp	Per side, applied differentially (XFP=0)
SDD11	Differential input return loss	20			dB	0.05-0.1GHz
	Differential input return loss	10			dB	0.1-7.5GHz
	Differential input return loss (See Note 1)				dB	7.5-15GHz

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Parameter	Description	Min	Тур	Мах	Units	Conditions			
SCC11	Common-mode input return loss	6			dB	0.1-15GHz			
SCD11	Differential to common-mode conversion	12			dB	0.1-15GHz			
JTOL_XFP	Jitter amplitude tolerance	0.65			Ulpp	XFP = 1, SJ@80MHz (see Note 2)			
JTOL_ nonXFP		0.4			Ulpp	XFP = 0, SJ@80MHz (see Note 3)			
	Eye Mask in XFP mode		Figure 48			XFP = 1			
TI	CDR Lock Time at Start-up			200	ms	from application of input data and de- assertion of RXLOSB_I			
	Note 1: Return Loss given by equation SDE	011(dB)=	= 10 - 16.6Lo	g10(f/7.5), with f in	GHz			
	Note 2: Total Jitter made up of DDJ+RJ+SJ additional length corresponding to a worst-o		•	•	0				
	Note 3: Jitter arrived at according to the same procedure as described in IEEE 802.3 Clause 52.9.10.2. Total Jitter (TJ) made up of DDJ+DCD+RJ+SJ where the DDJ is generated using a 7.5GHz Bessel-Thomson filter, DCD (minimum 0.05UIpp) is generated using 1GHz sinusoidal amplitude interference and the SJ is applied as per the template given in Figure 52-4 of IEEE802.3.								
	Note 4: Baud rate is specified relative to the	e referen	ice clock freq	uency in	Table 66	on page 191			

Table 69: Serial Receiver Specifications (Continued)

Figure 48: 10 Gb/s Receiver Input Compliance Mask in XFP mode





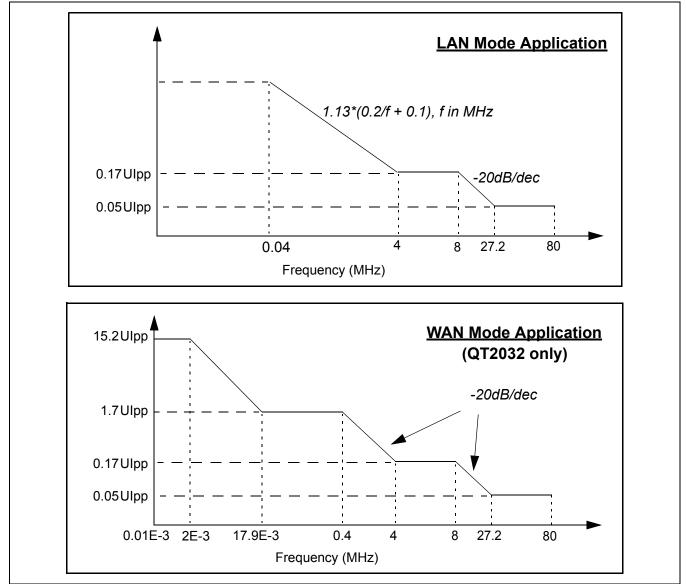


Figure 49: 10 Gb/s Receiver Input Sinusoidal Jitter Tolerance in XFP mode

The LOS detector output is seen at pin LOSOUTB. The LOS assert and deassert thresholds trigger off of the input signal amplitude. Please consult AMCCs' Application Note "Implementing LOS for the QT2022/QT2032" for more information on design practices with the LOS feature.

Figure 50: LOSOUTB Hysteresis

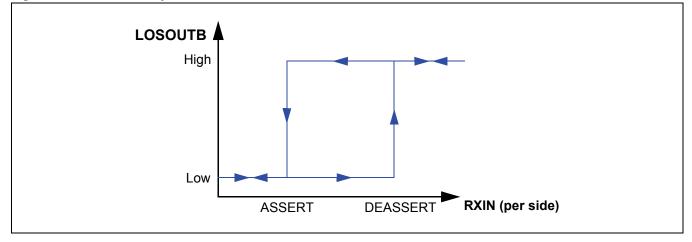


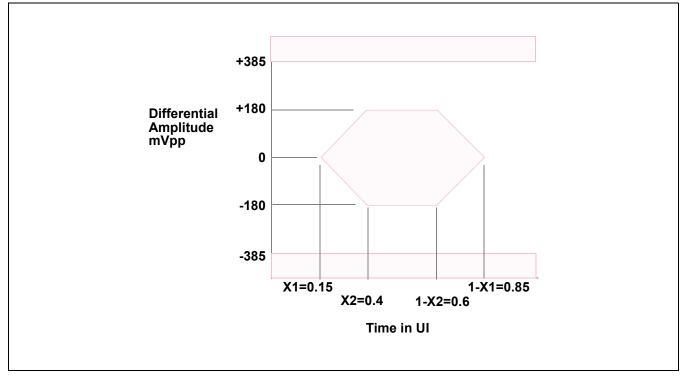
Table 71: Serial Transmitter Specifications

Parameter	Description	Min	Тур	Мах	Units	Conditions
f _{TXOUT}	LAN Mode nominal bit rat		10.3125 10.51875		Gb/s	10GE applications 10GFC applications
	WAN Mode nominal bit rate (QT2032 only)		9.95328		Gb/s	SREFSEL = "0", f _{SREF} *64 SREFSEL = "1", f _{SREF} *16
Zse	single-ended output impedance		50		Ω	
Zd	differential output impedance		100		Ω	
Zm	Single-ended impedance mismatch			5	%	
	Differential Output Amplitude	360	Figure 51		mVpp	output voltage swing set by external resistor connected to TXLEVEL pin. TxLEVEL = 4.53 k Ω
Tr, Tf	Output Rise and Fall Times	24			ps	20 to 80%. See Note 2.
	Output AC Common Mode Voltage			15	mVrms	
SDD22	differential output return loss	20			dB	0.05-0.1GHz
	differential output return loss	10			dB	0.1-7.5GHz
	differential output return loss (see Note 1)				dB	7.5-15GHz
SCC22	common-mode output return loss	6			dB	0.1-15GHz
DJ	LAN Mode Deterministic Jitter		0.05	0.10 0.07	UI pp	TxLEVEL = 4.53kΩ

Table 71:	Serial Transmitter Specifications (Continued)
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Parameter	Description	Min	Тур	Max	Units	Conditions
TJ	LAN Mode Total jitter		See Figure 51	0.30	UI pp	TxLEVEL = 4.53kΩ
	WAN Mode			7	mUIrms	50kHz - 80MHz
	Total Output Jitter (TJ) (QT2032 only) See Note 3.			50	mUlpp	50kHz - 80MHz measured over a 60s interval
				150	mUlpp	20kHz - 80MHz measured over a 60s interval
	Eye Mask See Note 3.	Figure 51				
	Note 1: Return Loss given by equation SDD22(dB)= 10 - 16.6Log10(f/7.5), with f in GHz					
	Note 2: Measured using a low-frequency square-wave pattern to allow for settling of the waveform resulting in an accurate topline and baseline reference.					
	Note 3: All reference clocks are	driven d	ifferentially.			

Figure 51: 10.3125Gb/s Transmitter Output Compliance Mask



Parameter	Description	Min	Тур	Max	Units	Conditions
	single-ended load impedance	40	50	60	Ω	
	differential load impedance	80	100	120	Ω	
	differential swing (p-p)	640	850	1600	mVpp	See Note 2.
	duty cycle	40		60	%	
	rise/fall time	200	250	1250	ps	20-80% in XFP mode See Note 2
	frequency See Note 1. See Table 8 on page 35.				MHz	
	BAUD rate variation	-100		+100	ppm	
	random jitter			10	ps rms	up to 100MHz

Table 72: TXPLLOUT Reference Clock Output Specifications (XFP=1)



Table 73: AC Boundary Scan Test Receiver Specifications for XAUI inputs (as per IEEE 1149.6)	Table 73: AC Bounda	ry Scan Test Receiver Sp	ecifications for XAUI inp	uts (as per IEEE 1149.6)
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Parameter	Description	1149.6 Reference	Min	Тур	Max	Units	Notes
dV	Valid input swing (see 1149.6 Fig. 40)	6.2.1.1Rule b, c	300		800	mV	Min is assumed 80% of driver min
Ttrans	10-90% transition time (see 1149.6 Fig. 40)	6.2.1.1Rule b			330	ps	Max based on XAUI driver sim with 50cm FR4 Ttrans_max corresponds with dVmin
Vthreshold	Threshold voltage in level- detection mode	6.2.2.1Rule a		0.9		V	cm bias of input receiver
Vhyst_level	Hysteresis voltage offset in level-detection mode	6.2.2.1Rule a		see note			Same as Vhyst_edge
Thyst	Hysteresis delay	6.2.2.1Rule b	1.0		10	ns	Thyst_min corresponds with dVmax Thyst_max corresponds with dVmin
Vhyst_edge	Hysteresis voltage offset in edge-detection mode	6.2.3.1 Rule b	100	224	270	mV	
HP_mult	high-pass filter multiplier	6.2.3.1Rule i	25			x	From Table 3 in 1149.6. no low-pass filter Assuming Vhyst/dVmin=0.9 max
Thp	high-pass time constant	6.2.3.1Rule f	250			ns	HP_mult * Thyst_max
Chp	high-pass AC coupling cap		6.25			nF	Assuming 40ohms min termination
Ttest/Thp	Test pulsewidth multiplier for AC (edge-det) mode	6.2.3.1Rule k	3			х	
Ttest	Test period for AC (edge-det) mode	6.2 Fig 40 in 1149.6.	1500			ns	assuming Chp=10nF, Thp=500ns NOTE TCKperiod can be much shorter than Ttest for EXTEST_PULSE
TCKperiod/ Thp	TCK period multiplier for level- det mode		2			х	5*Thp = 2.5*TCKperiod
TCKperiod	TCK period for level-det mode	6.2 Fig 42 in 1149.6.	1000			ns	assuming Chp=10nF, Thp=500ns
TCKfreq	TCK frequency for level-det mode				1	MHz	assuming Chp=10nF, Thp=500ns

Note: It is assumed that XAUI inputs are always AC coupled, permitting implementation of IEEE1149.6 section

6.2.3.1 Rule a, Method 2.

Table 74: VCXO PLL Interface Parameters

Parameter	Description	Min	Тур	Max	Units	Notes
	PFD Gain		400		mV/2π rad	
	PFD Differential Output Swing		+-400		mVpp	
	VCXO characteristics					Please see VCXOI input specifications in Table 66 on page 191
	PFD differential R _{out}		2		kΩ	

Table 75: Round-trip Delay Constraints

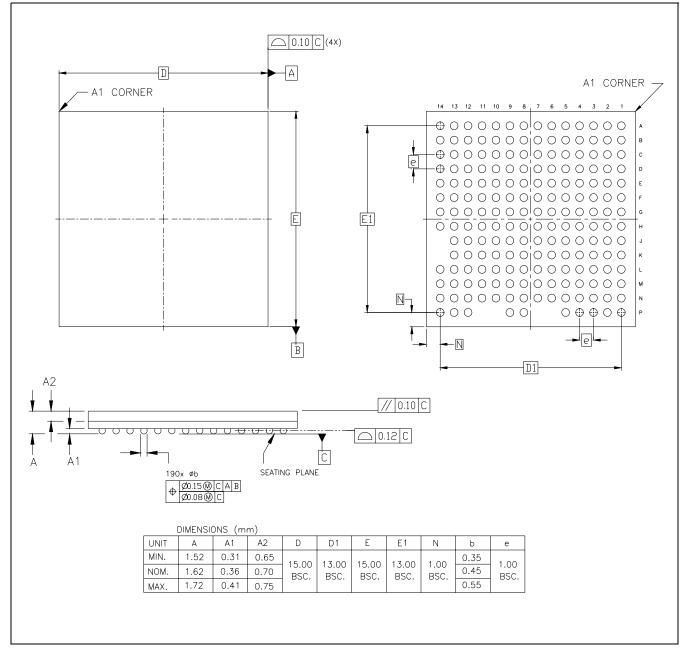
Parameter	Description	Min	Тур	Мах	Units	Notes
XGXS & XAUI	XGXS & XAUI sublayer round-trip time			400	ns	Includes 20" of FR4 in each direction (~7ns)
10GBASE-R PCS	PCS sublayer round-trip time			160	ns	
WIS	WIS sublayer round-trip time			2500	ns	Default round-trip delay. Does not meet IEEE 802.3 specification.
				1350		Requires modification of default register values. See Section 18.9 on page 216 for details. Meets IEEE delay requirement.
Serial PMA & PMD	Serial PMA & PMD sublayer round- trip time			40	ns	Excludes optical fiber patch cord.



15 Mechanical

The QT2022/32 is housed in a cavity up 15 x 15mm² LBGA package. There are 190 solder balls that are spaced 1.0mm apart. Figure 52 shows the package dimensions.





 Dimension D tolerances: MIN = 14.90, MAX = 15.10 (units in mm) Dimension E tolerances: MIN = 14.90, MAX = 15.10 (units in mm)

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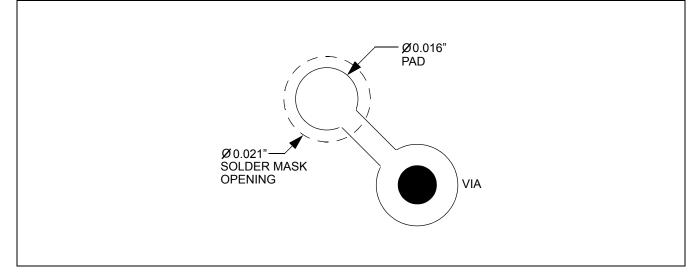
The QT2022/32 product is available with two choices of ball composition. The first option is a RoHS compliant solder ball made from a $Sn_{95.5\%}Ag_{4\%}Cu_{0.5\%}$ alloy material. The second option is the standard $Sn_{63\%}Pb_{37\%}$ solder ball. Ordering information for the two choices is contained in Table 79 on page 219. The chip package is RoHS compliant for all order codes.



15.1 PCB Layout Recommendations

A recommended NSMD (No Solder Mask Defined) pad structure is given in Figure 53. The structure and values are recommendations only, and will vary with manufacturing process.





15.2 Baking instructions

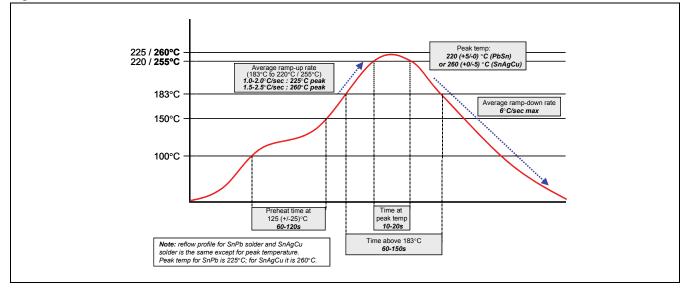
To remove moisture, bake at 125°C for 14 hours using an oven with nitrogen purge per IPC / JEDEC J-STD-033. Baking removes the remote chance of popcorn effects during the reflow process.

15.3 Thermal Reflow Profile

The recommended reflow profile for the QT2022/32 is shown in Figure 54. Peak temperatures are shown for both the leaded and lead-free versions of the products. The lead-free version has a peak temperature of 260°C. The standard leaded version has a peak temperature of 225°C.









Γ

16 Marking Drawing

Figure 55: Marking Drawing

NOTES	(Unless Otherwise Specified):
• Laser mark r	nomenclature as indicated and approximately where shown.
Pin 1	AMCCC XXXXXXXXXX M YYWW ZZZZZZ JJJJJJJJJJ ▲ CCCCCCC (e1)
ROW #1: AM ROW #2: AM ROW #3: M — Mai YY: WW ROW #4: ZZZ ROW #5: JJJ ROW #6: — ESI CC	Dev order – including symbols): CC Logo CC Part Ordering ID XXXXXXXX: 11 digit Order Code (see ordering information) sk Protection Symbol Assembly Year Code /: Assembly Week Code ZZZZ: 6 digit AppliedMicro Lot Code JJJJJJ: Up to 9 characters Alpha-Numeric Supplier Assembly Lot Code O protection symbol CC: Assembly Location DEC J-STD-609 Pb-free marking standard

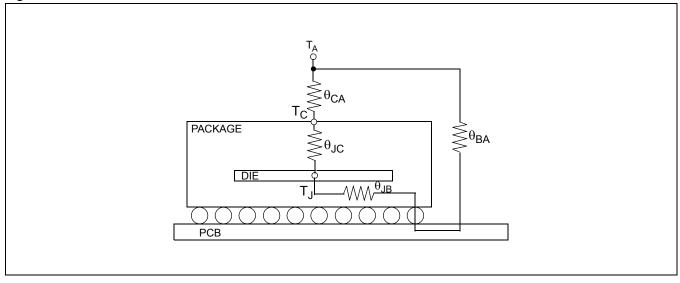
17 Thermal

The QT2022/32 190-ball LBGA package incorporates state-of-the-art high speed performance in a low-cost plastic package with an advanced thermal solution. There are two primary thermal paths, junction-to-case (JC) and junction-to-ball (JB).

The central 5x5 ball array on the package provide 25 thermal relief paths into the PCB substrate. These are used as a primary heat dissipation path for the chip. To optimize thermal performance, please ensure there is a ground via for each thermal ball in the layout. Thermal modelling is based on a 1S2P multilayer JEDEC standard (100x100mm), 1.6mm FR4 PCB.

The thermal model for the package is given in Figure 56. Package thermal parameters are given in Table 56, "190B LBGA Package Constants," on page 188.

Figure 56: LBGA Thermal Model

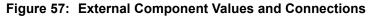


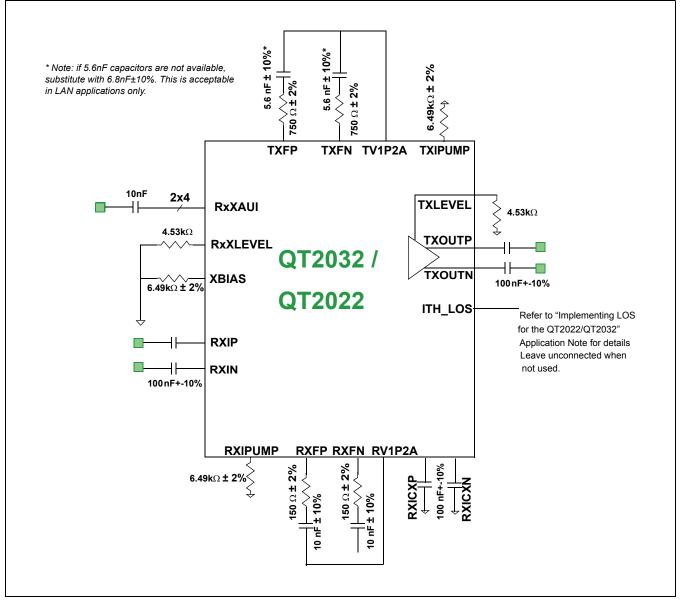


18 Application Notes

18.1 External Components

Figure 57 illustrates external components required to bias or terminate signal pins for proper operation of the QT2022/32.





18.2 Loop Filter Component Selection

The receive PLL components (connected to the RXFN/P pins in Figure 57) and the transmit PLL components (connected to the TXFN/P pins in Figure 57) must be selected carefully. Due to the sensitivity of these circuits, AMCC recommends thin film capacitors instead of the more common ceramic capacitors. Ceramic capacitors are known to exhibit a piezoelectric effect, most often observed during temperature cycling. The voltage spikes caused by a ceramic capacitor can adversely affect the PLL performance, potentially inducing errors on the traffic.

For further information on the piezoelectric effect, please read the Application Note, "Piezoelectric Effect in Ceramic Capacitors" at www.atceramics.com.

18.3 Power Supply Filtering and Decoupling

Power supply filtering recommendations are provided in a separate Application Note. Please contact AMCC for further information.

18.4 Dual 10GE & 10GFC Rate Support

With the QT2022/32, a module or system card can be designed that will support both the 10GE and 10GFC rates in a single design. This is accomplished by configuring the TXPLLOUT pins as clock inputs. Two reference clocks can be supplied to the chip, one at 156.25 MHz (for 10GE) and the other at 159.375 MHz (for 10GFC). One clock can be connected to the standard EREFCLK input and the other to the TXPLLOUT input.

By default, the EREFCLK input is selected. By setting MDIO Register bit 1.C001h.7 to 1, the reference clock supplied to the TXPLLOUT pins will be selected and the clock signal on the EREFCLK input is ignored. Either input may be used for the two different clocks. Device jitter performance is the same with both inputs.

To minimize module power consumption and to prevent coupling, the unused oscillator should be powered down using the GPIO drivers (LED1, LED2 or LED3). One GPIO output can be used to drive the enable/disable pin for each oscillator.

Clock input selection requires an MDIO command. The default settings can be modified by taking advantage of the extended EEPROM memory support. Please see Section 10.7, "Register Configuration from External EEPROM," on page 91 for details.

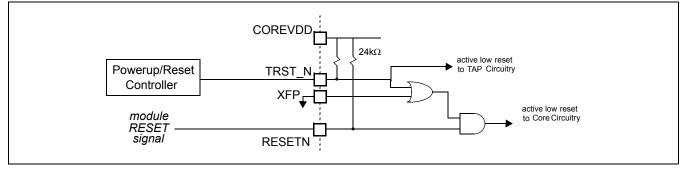
18.5 Reset Requirements

18.5.1 Powerup Reset in a Module Application

In a module application (XFP=0), the reset signal must be applied to the TRST_N pin after powerup to guarantee proper operation. This will reset the TAP circuitry and the Core Circuitry inside the chip. A reset signal must be applied after hotplug and should be provided by a powerup/reset controller inside the module. The reset signal from the module edge connector can be applied to the TRST_N signal, as shown in Figure 58. The module reset signal can also be applied directly to the RESETN pin.

The TAP port requires a reset only on powerup. It does not need to be reset afterwards for proper operation of the chip and therefore does not need to be connected to the module edge connector RESET signal.

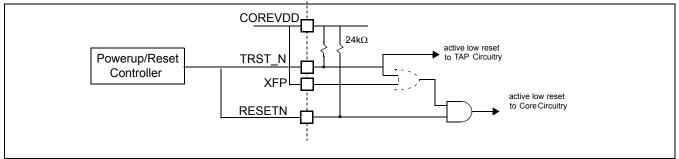
Figure 58: Powerup Reset in a Module Application



18.5.2 Powerup Reset in a System Application

In a system application (XFP=1), the reset signal must be applied to the TRST_N pin and the RESETN pin after powerup to guarantee proper operation. The reset signal to the TRST_N pin is required to reset the TAP circuitry. The reset signal to the RESETN pin is required to reset the Core circuitry.





18.5.3 Valid Startup Sequences

Valid startup sequences are depicted in Figure 60. A hard reset must be applied during the startup sequence. The hard reset signal must be applied to the TRST_N and/or RESETN pins, as described in Section 18.5.1 or Section 18.5.2, as applicable. The hard reset signal must be held low for a minimum of 500us after the power supplies have stabilized to acceptable values (as specified in Table 55 on page 187).

A valid Ethernet reference clock must be supplied to the chip before the RESETN signal is pulled high. The chip can be powered up in low power mode if desired (TXON low). A soft reset is not required but can be applied. A soft reset cannot be substituted for a hard reset on startup.

In a XENPAK module application, the hard reset must be supplied by a reset controller inside the module in order to meet the requirement specified in XENPAK MSA Figure 16.

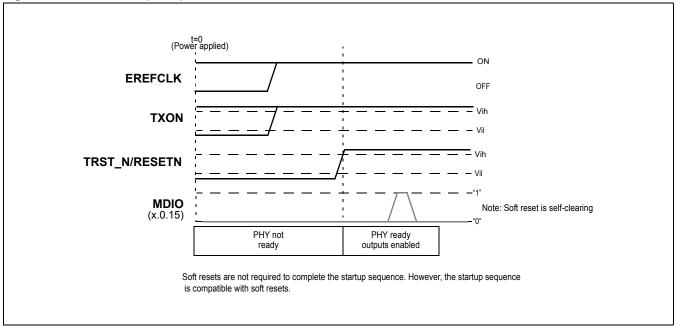


Figure 60: Valid Startup Sequences



18.5.4 Reset Timing Recommendations After Powerup

It is recommended to ensure there are no I2C transactions in progress before applying a reset to the QT2022/32. The reset can interrupt any ongoing I2C transactions and re-initialize the QT2022/32's I2C bus controller. However, it will not reset the peripheral I2C device. If an I2C transaction is interrupted by a reset, the peripheral device will expect the transaction to continue.

After reset the QT2022/32 will initialize the bus as described on page 89. This will clear all I2C transactions, so all peripheral devices are ready to accept a new command. However, robust firmware should not rely on this feature to clear the bus.

I2C activity is reported in the NVR Control/Status Register (1.8000h) and DOM Control/Status Register (1.A100h). Ensure the Command Status fields of both registers do not report "in progress" (bits 3:2 NOT = '10') before applying a reset.

Refer to AMCC document GAN2072, "Reset Timing Recommendations" for more details.

18.6 MDIO Bus Implementation

Although the MDIO bus is a relatively low-speed bus the transition times can be very fast, so correct implementation is important. The MDC signal, originating from the Station Manager (STA) on the host system, may or may not require a pullup resistor depending on implementation. The MDIO does require a pullup.

In a module application, it is recommended that all pullup resistors be placed on the host card. If the pullup resistors are placed in the module, the pullups will act in parallel in a multi-port line card. The total pullup resistance will be reduced in accordance with the number of populated modules. Thus the pullup resistance will be unpredictable and, if it is too low, may exceed the current drive capabilities of the driver.

18.7 Improving MDIO Bus Integrity

In many systems, there can be significant ringing and crosstalk on the MDIO and MDC signals. The ringing is caused by potentially large capacitance and self-inductance of the signal lines. Very fast transitions can stimulate LC ringing and result in crosstalk between the two signal lines, since they are often routed in close proximity.

To minimize or eliminate ringing, place a small-valued series resistor directly on the MDIO and MDC nets. The resistor introduces a real loss into the circuit, which effectively damps out the ringing. The resistor value, R, should be less than ~10% the value of the pullup resistor, Rpu, to prevent significant ground offset of Vil. For module applications, series resistors should be placed in the module as well as on the hostboard. The resistor on the hostboard should be placed near the middle of the bus.

To avoid crosstalk, the MDIO and MDC signals should be separated sufficiently on the layout. Placement of a ground plane or power plane between the traces will help eliminate crosstalk.

Include component footprints for pullups to VCC on MDIO and MDC inside the module. This will provide the flexibility to modify the bus termination as required. Modifications to the termination may be required to ensure bus integrity on different host cards.

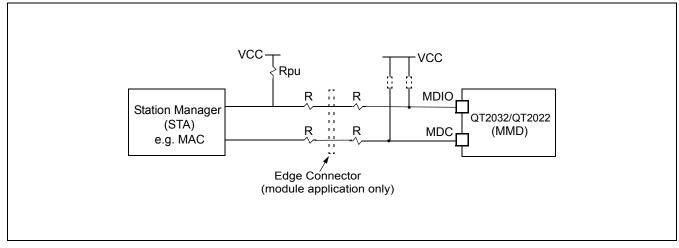


Figure 61: MDIO Bus Implementation



18.8 XAUI Traffic Testing with a BERT

It is possible to program a parallel traffic generator and error detector (BERT) to generate and detect errors in a XAUI-compliant data stream. For example, the exact CJPAT pattern can be programmed into the BERT's pattern buffer, as specified in IEEE 802.3-2005 Clause 48A.5.1. This pattern can be sent into the XAUI input of a QT2022/32 device, looped back on the fiber interface and returned to the BERT error detector. In this setup, the QT2022/32 LAN reference clock must be synchronous to the BERT reference clock. This test setup is shown in Figure 18.8.

During normal operation of the QT2022/32, this test setup will fail to work as intended. The BERT error detector will not be able to synchronize to the output data from the DUT. This is due to the idle randomization process in the 8b/ 10b encoder, which will scramble the ||A||, ||K|| and ||R|| codes in the signal stream. The bitstream received by the BERT will not exactly match the transmitted bitstream. Since the BERT is not protocol-aware, it will be unable to synchronize to this pattern.

This problem can be defeated by disabling the idle decode process within the QT2022/32.

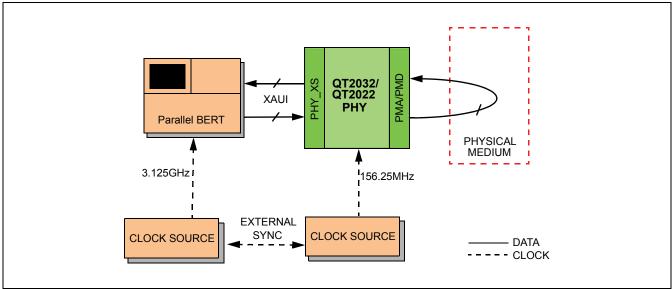


Figure 62: XAUI Pattern Testing with a Parallel BERT

This is described in detail in Section 11.7, "Disabling the Idle Decode Process," on page 106. When the idle decode process has been disabled, the test setup in Figure 18.8 will work as expected. However, the disparity of the output signal from the QT2022/32 must be accounted for in the BERT receiver pattern.

18.8.1 Running Disparity with CJPAT

The CJPAT pattern produces the same disparity on all 4 lanes. Only two possible encodings can occur. Only one of the two encodings will match the signal from the RxXAUI output from the chip. Each pattern must be loaded into the BERT's pattern buffer to see which one matches. The running disparity will be maintained until the signal is interrupted.

If the signal is interrupted or the chip is reset, the running disparity will have a 50:50 chance of remaining the same. The CJPAT pattern that is loaded into the BERT might need to be swapped for the alternate pattern.

Note: The CJPAT pattern cited in the IEEE 802.3-2005 Standard Clause 48A.5.1 does not include sufficient idle codes to meet the input requirements of the XAUI interface. These requirements are specified in Clause 48.2.4.2. More specifically, Lane 0 does not receive a valid ||A|| ordered_set to allow lane alignment (see Table 48A-10). In order for the CJPAT pattern to work properly, an additional ||A|| column must be added at the end of the pattern.

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18.9 Jumbo Frame Support and Round-Trip Delay in WAN Applications

The default startup configuration of the QT2032 supports jumbo frame transmission (10kB frame size). This is supported in both WAN and LAN modes. When operating in WAN mode, the round-trip delay time of the chip exceeds the IEEE requirement of 14336 bit times¹ (BT) specified in Clause 50.3.7. The delay constraints of the QT2022/32 are presented in Table 75 on page 202.

The QT2032 can be programmed to comply with the IEEE round-trip delay constraints. However, in doing so jumbo frames are not supported. Table 76 on page 216 provides the necessary information to program the chip to meet the delay constraints. All registers listed in the table must be set to guarantee the specified delay constraint.

Register bit-4.C050h.0 is an enable bit. The enable bit must be set last when reprogramming the delay constraints. When this bit is set to '0', the chip will operate in its default mode i.e. it will support jumbo frames.

Register Address	Values to Meet IEEE Round-Trip Delay Constraint in WAN mode (max. 2kB Packets)
4.C041h	0x0000
4.C042h	0x00F8
4.C043h	0x0002
4.C044h	0x000B
4.C045h	0x0001
4.C051h	0x0004
4.C052h	0x00FD
4.C053h	0x006E
4.C054h	0x00FD
4.C055h	0x0078
4.C051h	0x0001

Table 76: Register Values for Round-Trip Delay Compliance

18.10 DOM Memory Behavior

The DOM memory definition is presented in Table 27 and Table 28 of the XENPAK MSA. Most of the defined fields store 16-bit values that span two I2C addresses. To ensure partially updated fields are not read over the MDIO bus², the QT2022/32 organizes the DOM memory into pairs. When an MDIO command reads an even-numbered address location in the DOM memory range 1.A000h-1.A0FFh, the register at the next higher MDIO address will be latched. This means that the current value will not be updated to show a newer value, even if the peripheral DOM device is read again. The latched odd register address will be unlatched by two (or more) successive MDIO reads.

The most recently read value from the DOM device on the I2C interface is buffered in internal memory. MDIO reads of the even address will update the associated odd MDIO register with the most recent value.

This is expected behavior for most of the defined registers in this space, which store 16-bit fields that span two addresses. MDIO reads from these memory addresses must be performed in pairs to upload the full 16-bit field.

This is not expected behavior for MDIO Registers 1.A070h - 1.A071h and 1.A074h - 1.A075h. These registers do not store fields that span two registers. To ensure MDIO reads to the odd addresses report the current value, perform MDIO reads in pairs. Read the associated even address first. Alternatively, read each odd register twice.

The contents of register 1.A071h feed into the LASI alarm. Note that the internally buffered memory value is used to drive the LASI alarm. The LASI alarm will trigger as expected, even if the MDIO register is latched with an old value.

^{1.} The bit time (BT) is the reciprocal of the bit rate. For 10GE, 1 BT = 100ps. See IEEE 802.3-2002 Clause 1.4.50 for more details.

^{2.} In particular, if the MSB of a two-byte field is read over the MDIO bus while a DOM update is in progress, the LSB may be updated before it is read over the MDIO bus, such that the LSB and MSB contain values from two different DOM read events.



19 References

The industry standards, documents, and references listed in Table 77 represent information relevant to the development and deployment of the QT2022/32.

Table 77: Supporting Documents

Document	Revision	Date	Description
IEEE Std. 802.3-2005	Released 2005	2005	CSMA/CD Access Method and Physical Layer Specifications (IEEE Computer Society - LAN/MAN Standards Committee)
XENPAK MSA	Issue 3.0	September 18, 2002	XENPAK 10 Gigabit Ethernet Multi-Source Agreement (XENPAK MSA Group)
IPC/JEDEC J-STD-033A	Revision 1.0	July 2002	Handling, Packing, Shipping, and Use of Moisture/Reflow Sensitive Surface Mount Devices (JEDEC JC-14.2 Committee and IPC B-10a CCCT Group)
IEEE Std. 1149.6-2003	Released 2003		Standard for Boundary-Scan Testing of Advanced Digital Networks
IEEE Std. 1149.1-2001	Released 2001		IEEE Standard Test Access Port and Boundary-Scan Architecture
INCITS T11/Project 1413-D	Revision 3.1	June 7, 2002	Fibre Channel 10 Gigabit (10GFC) Standard Working Draft
XFP MSA	Revision 3.1	April 2, 2003	Industry multi-source agreement specifying a fiber optic module with a 10G electrical interface (adopted revision).
JEDEC JESD8-11		October, 2000	1.5 and 0.9-1.6V Power Supply Voltage and Interface Standard for Nonterminated Digital Integrated Circuits
RL2032_2022-0	Revision 2.0	July 11, 2005	QT2032A2/QT2022C2 Reliability Report (Applied Micro Circuits Corporation)
GR-253-CORE	Issue 3	September, 2000	Synchronous Optical Network (SONET) Transport Systems: Common Generic Criteria (Telcordia Technologies)
RoHS Directive		February 13, 2003	Directive 2002/95/EC of the European Parliament and the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (Official Journal of the European Union L 037, 13/02/2003 P. 19 - 23)
"Piezoelectric Effect in Ceramic Capacitors"			Application Note describing piezoelectric effects in ceramic capacitors. Published by American Technical Ceramics (www.atceramics.com)
QAN0026	v1.1	July, 2004	Implementation and Usage Tips for XFP Applications (Applied Micro Circuits Corporation)
QAN0054	v1.1	March 30, 2005	Reset Timing Recommendations for AMCC PHYs (Applied Micro Circuits Corporation)
QAN0074	v0.3	June 2, 2006	Implementing LOS for the QT2022/QT2032 (Applied Micro Circuits Corporation)



Table 78: Revision History

Rev	Date	Description
5.11	April 7, 2010	Updated the "Revision History" notes for Revision 5.00 with additional details about the solder ball diameter (see underlined text).
5.10	March 11, 2010	Updated "WIS Synchronization (Octet and Frame Delineation)" on page 41 with more information on framing pattern. Added Section "SEF Defect Generation" on page 41, Section "LOF Defect Generation" on page 42 and "LOS Defect Generation" on page 42. Corrected typo on Section 8.4.1 on page 62 to reference register field 1.9002h.7 instead of 1.9002h.3. Updated marking drawing in Figure 55 on page 207 to include the AppliedMicro lot code (add Row #4) Indicated tolerances for parameters D and E of Package Outline Drawing in Figure 52 on page 203. Corrected turnaround (TA) timing in MDIO Read and Read Increment transactions in figure 23 on page 76.
5.00	December 16, 2009	Page 201, Package Outline Drawing updated. <u>The nominal solder ball diameter (b) was changed from</u> <u>0.46mm to 0.45mm, in accordance with JEDEC Standard Procedures and Practices. See JEDEC Publi-</u> <u>cation No. 95, SPP-003 Issue C, Item Number 11.2-740(S) for details.</u>
2.03	November 4, 2009	Page 201, reference to ball diameter removed. Page 216, ordering information changed from QT2022PRKCB-1 to QT2022PRKCB
2.02	September 4, 2009	Page 206, added Marking Drawing Page 217, updated Ordering Information
2.01	March 4, 2008	Pg 13, Corrected description of EREFCLKC input. Added requirement for external AC coupling.
2.00	December 20, 2006	Increased maximum power consumption specification for WAN mode in Table 55 on page 187. Changed DJ specification for 10Gbps serial transmitter in Table 71 on page 198. Changed maximum current draw for XV1P2 and TV1P2 power supplies in Table 55 on page 187. Decreased maximum current draw for RV1P2 power supply in Table 55 on page 187. Added specification of maximum current draw for COREVCC power supply in Table 55 on page 187. Inserted additional lol specification for MDIO in Table 60 on page 189 to show IEEE compliance. Changed pullup specification for 3.3V operation for MDIO in Table 60 on page 189. Corrected definition of 2.C500h bit 8 to be Reserved (RO); corrected definition of 2.C500h bit 9 to be "Far-end AIS-P/LOP-P" (RO) Corrected definition of 1.C003h bits 15:14 to remove 600kHz operation which is not supported by I2C. Corrected definition of "PHY_XS Code Error" to properly refer to the XAUI code violation fields in 4.C006h.3:0 in Table 25 on page 58. Updated bit field definition of 1.8.10 (PMA Receive Local Fault) and 1.8.11 (PMA Transmit Local Fault) to be consistent with Table 19 on page 58. Also updated text description of Section 8.2.4 on page 55 for consistency. Updated the definition of 2.C502h bits 7 and 6 to more accurately describe the behavior in Table 29 on page 68 and in the register map (2.C502h and 2.C501h updated). Corrected definition of MDIO register 2.C002h.9 to "WIS TX SS Bit Insert Enable" on page 151. Added text describing features and usage of WIS Tx OH Byte Insert feature in Section 7.3.9 on page 49. Updated definition of WIS register field 2.C000h.5 to match behavior as flag that detects NDF. Note: In this document, deleted text is shown with a strikethrough. Inserted text is <u>underlined</u>.
1.02	October 13, 2006	Minor updates
1.01	September 19, 2006	Converted to AMCC format.



20 Ordering Information

To order QT2032 and QT2022 products, quote the order number listed in Table 76.

Table 79: Ordering Information

Product description	Product name	Version	Order number
QT2032	QT2032	A2, SnPb solder balls	QT2032PBKCB
		A2, SnAgCu solder balls	QT2032PRKCB
QT2022	QT2022	C2, SnPb solder balls	n/a
		C2,SnAgCu solder balls	QT2022PRKCB
QT2032A2/QT2022C2 Evaluation board ¹			QT2032-EKG-1A2
QT2032A2 2-port XFP Reference Design Kit			QT2032-RD7-1A2

1. The evaluation board comes with a mounted QT2032. The QT2022 product can be evaluated by operating the QT2032 in LAN mode.





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